

IECEX Certificate of Conformity

INTERNATIONAL ELECTROTECHNICAL COMMISSION IEC Certification System for Explosive Atmospheres

for rules and details of the IECEx Scheme visit www.iecex.com

Certificate No.:

IECEX KTL 19.0028X

Page 1 of 3

Certificate history:

Status:

Current

Issue No: 0

Date of Issue:

2019-11-19

Applicant:

Gastron Co., Ltd.

23, Gunpocheomdansaneop 1-ro, Gunpo-si

Gyeonggi-do 15881 Korea, Republic of

Equipment:

Portable Multi Gas Detector, G-Finder Multi GFM-400 Series

Optional accessory:

Type of Protection:

Intrinsic Safety "i"

Marking:

Ex ia IIC T4 Ga

Approved for issue on behalf of the IECEX Certification Body:

Park, Jong-koo

Position:

Signature:

(for printed version)

Date:

Certification Manager

1. This certificate and schedule may only be reproduced in full.

2. This certificate is not transferable and remains the property of the issuing body.

3. The Status and authenticity of this certificate may be verified by visiting www.iecex.com or use of this QR Code.



Certificate issued by:

Korea Testing Laboratory 87, Digital-ro, 26-gil, Guro-gu Seoul Korea, Republic of





IECEx Certificate of Conformity

Certificate No.:

IECEX KTL 19.0028X

Page 2 of 3

Date of issue:

2019-11-19

Issue No: 0

Manufacturer:

Gastron Co., Ltd.

23, Gunpocheomdansaneop 1-ro, Gunpo-si

Gyeonggi-do 15881 Korea, Republic of

Additional manufacturing locations:

This certificate is issued as verification that a sample(s), representative of production, was assessed and tested and found to comply with the IEC Standard list below and that the manufacturer's quality system, relating to the Ex products covered by this certificate, was assessed and found to comply with the IECEx Quality system requirements. This certificate is granted subject to the conditions as set out in IECEx Scheme Rules, IECEx 02 and Operational Documents as amended

STANDARDS:

The equipment and any acceptable variations to it specified in the schedule of this certificate and the identified documents, was found to comply with the following standards

IEC 60079-0:2017

Explosive atmospheres - Part 0: Equipment - General requirements

Edition:7.0

IEC 60079-11:2011 Explosive atmospheres - Part 11: Equipment protection by intrinsic safety "i"

Edition:6.0

This Certificate does not indicate compliance with safety and performance requirements other than those expressly included in the Standards listed above.

TEST & ASSESSMENT REPORTS:

A sample(s) of the equipment listed has successfully met the examination and test requirements as recorded in:

Test Report:

KR/KTL/ExTR19.0029/00

Quality Assessment Report:

NL/DEK/QAR19.0002/00



IECEx Certificate of Conformity

Certificate No.:

IECEX KTL 19.0028X

Page 3 of 3

Date of issue:

2019-11-19

Issue No: 0

EQUIPMENT:

Equipment and systems covered by this Certificate are as follows:

The G-Finder Multi GFM-400 series are hand-held, battery operated multi gas detectors. The "G-Finder Multi" is a brand name and the main model name is "GFM-400". The detector is a personal safety device designed to continuously monitor the presence of oxygen(O_2), Carbon Monoxide (CO), Hydrogen Sulfide (H_2 S) and one of methane (CH₄) or propane (C_3H_8). The detector samples the atmosphere in diffusion mode using an electrochemical sensors for O_2 , a dual toxic electrochemical sensor for CO and H_2 S, and an IECEx certified NDIR sensor for CH₄ or C_3H_8 .

The detector alerts the user to potentially unsafe exposure with visual, vibrating and audible alarms when gas concentration exceeds user configurable set points, and readings are displayed on a LCD. The detector has IR communications for changing the alarm set point, the calibration range and etc. The IR communications shall only be used in safe area.

The detector is comprised of two printed circuit boards with a LCD, three gas sensors and two batteries in parallel, housed in a non-metallic enclosure which is constructed by double-shot injection molding with polycarbonate and thermoplastic elastomer alloy. The non-metallic enclosure consists of a front half (cover) and a back half (body). A wide LCD window of the front half of the enclosure is fully covered with an anti-static coating film. A metallic suspender clip is attached to the back half of the enclosure. The parts of the enclosure are secured by screws. The detector has no facilities for connection of external circuits.

Power is provided by non-user replaceable, two Lithium/Thionyl chloride (Li/SOCl₂) batteries (Tekcell, type SB-AA11 manufactured by VITZRO CELL, AA size, Nominal 3.6 V, Peak 3.9 V, 2.5 Ah) connected in parallel. The detector is intended to be a disposable unit. The ambient temperature range for the series is -20 °C $\leq T_a \leq$ +50 °C.

The configuration for GFM-400 series is as follows;

GFM-400(-X)(-Y)

- GFM-400: Model name
- *X: Flammable gas type (blank(default sensor), MM2.5, MM100, MP1.5, MP2.5, PP1.5, PP2.5)
- *: This option can be selected only if the user require a particular target gas, a particular calibration gas and a particular measurement range different from the default sensor to detect a flammable gas (CH₄ or C₃H₈).
- **Y: Housing body color (blank: orange(default), YE: yellow, GN: green, VT: violet, and etc.)
- **: This option is not marked on the label and can only be used at an order if the user require a particular housing body color different from the default. The option does not affect intrinsic safety.

For the detailed information, see the instruction manual.

SPECIFIC CONDITIONS OF USE: YES as shown below:

The G-Finder Multi GFM-400 is provided with the anti-static coating film covering over the LCD window to avoid danger of ignition due to electrostatic charge. Periodic inspection of this coating film is required to ensure no degradation, delamination, abrasions or other deformities to this surface. Care must be taken to avoid exposure to excessive heat, harsh chemicals or solvents, sharp edges and abrasive surfaces. Clean only with a damp cloth.



IECEx Test Report Summary

Date of issue: 2019-11-19

INTERNATIONAL ELECTROTECHNICAL COMMISSION IEC Certification System for Explosive Atmospheres

for rules and details of the IECEx Scheme visit www.iecex.com

EXTR Ref. No.: KR/KTL/ExTR19.0029/00 Page 1 of 1

EXTR Free Ref. No.: PI181060 Status: Issued

List of Standards IEC 60079-0:2017 Edition:7.0, IEC 60079-11:2011

Covered: Edition:6.0

Issuing ExTL: KTL - Korea Testing Laboratory

Endorsing ExCB: KTL - Korea Testing Laboratory

Manufacturer: Gastron Co., Ltd.

23, Gunpocheomdansaneop 1-ro, Gunpo-si

Gyeonggi-do 15881

Location of Manufacturer:

Korea, Republic of

Ex Protection: Intrinsic safety "i"

Ex ia IIC T4 Ga

Ratings: Battery Powered (Nominal 3.6 V, Peak 3.9 V, 2.5 Ah × 2) - Two Lithium/Thionyl chloride (Li/SOCI2) batteries

in parallel, non-user replaceable, Tekcell, type SB-AA11 manufactured by VITZRO CELL

■ Ambient Temperature Range: -20 °C ≤ Ta ≤ +50 °C

Equipment: Portable Multi Gas Detector, G-Finder Multi GFM-400 Series

Model Reference: GFM-400(-X)(-Y)

- GFM-400: Model name

- *X: Flammable gas type (blank(default sensor), MM2.5, MM100, MP1.5, MP2.5, PP1.5, PP2.5)

*: This option can be selected only if the user require a particular target gas, a particular calibration gas and a particular measurement range different from the default sensor to detect a flammable gas (CH4 or C3H8).

- **Y: Housing body color (blank : orange(default), YE : yellow, GN : green, VT : violet, and etc.)

**: This option is not marked on the label and can only be used at an order if the user require a particular

housing body color different from the default. The option does not affect intrinsic safety.

For the detailed information, see the instruction manual.

Related IECEx Certificates:

IECEx KTL 19.0028X Issue 0

Comments:



IECEX TEST REPORT COVER

ExTR Reference Number...... KR/KTL/ExTR19.0029/00

ExTR Free Reference Number: PI181060

Compiled by + signature (ExTL): Choi, Yong-Won

Reviewed by + signature (ExTL)....: Min, Yeong-Seung

Approved by + signature (ExCB) ...: Kim, Dong-Jin

Date of issue 2019.11.19.

Ex Testing Laboratory (ExTL): KTL(Korea Testing Laboratory)

Address 87, Digital-ro 26-gil, Guro-gu, Seoul, Korea

Ex Certification Body (ExCB) KTL(Korea Testing Laboratory)

Address 87, Digital-ro 26-gil, Guro-gu, Seoul, Korea

Applicant's name...... GASTRON Co., Ltd.

Address 23, Gunpocheomdansaneop 1-ro, Gunpo-si, Gyeonggi-do, 15881,

Korea

Standards associated with this

ExTR package...... IEC 60079-0:2017, IEC 60079-11:2011

Clauses considered...... All clauses considered

Test Report Form Number ExTR Cover_7 (released 2018-02)

Related Amendments, Corrigenda

or ISHs: N/A

Test item description Portable Multi Gas Detector

Model/type reference G-Finder Multi GFM-400 Series

Code (e.g. Ex __ II__ T__)..... Ex ia IIC T4 Ga

Rating Nominal 3.6 V, Peak 3.9 V, 2.5 Ah × 2 (Two Lithium/Thionyl

chloride (Li/SOCl2) batteries in parallel, non-user replaceable)

ExTR Package Contents

Assembled ExTR documents and Additional reference material:

IECEx Test Report Cover

IECEx Test Report: IEC 60079-0, Edition 7

IECEx Test Report: IEC 60079-11, Edition 6

Manufacturer's name...... GASTRON Co., Ltd.

15881, Korea

Certificate No. (optional)..... IECEx KTL 19.0028X

QAR Reference No. (optional): NL/DEK/QAR19.0002/00

Particulars: Test item vs. Test requirements

Classification of installation and use : Hand-held

Ingress protection: IP20 or greater

Rated ambient temperature range (°C).....: -20 °C $\leq T_a \leq +50$ °C

General remarks:

The test results presented in this ExTR package relate only to the item or product tested.

- "(See Attachment #)" refers to additional information appended to the ExTR package.
- "(See appended table)" refers to a table appended to the ExTR package.
- Throughout this ExTR package, a point is used as the decimal separator.
- Where the term "N/A" appears in any part of an ExTR package, it indicates that the associated issue was considered "Not applicable" to the involved evaluation.
- In accordance with IECEx 02, a Receiving ExCB may request a sample of the Ex equipment and copies of the documentation referred to in an ExTR Cover.

The technical content of this ExTR package shall not be reproduced except in full without the written approval of the Issuing ExCB and ExTL.

General product information:

The G-Finder Multi GFM-400 series are hand-held, battery operated multi gas detectors. The "G-Finder Multi" is a brand name and the main model name is "GFM-400". The detector is a personal safety device designed to continuously monitor the presence of oxygen(O_2), Carbon Monoxide (CO), Hydrogen Sulfide (CO) and one of methane (CO) or propane (CO). The detector samples the atmosphere in diffusion mode using an electrochemical sensors for CO, a dual toxic electrochemical sensor for CO and CO0 and CO1 and CO2.

The detector alerts the user to potentially unsafe exposure with visual, vibrating and audible alarms when gas concentration exceeds user configurable set points, and readings are displayed on a LCD. The detector has IR communications for changing the alarm set point, the calibration range and etc. The IR communications shall only be used in safe area.

The detector is comprised of two printed circuit boards with a LCD, three gas sensors and two batteries in parallel, housed in a non-metallic enclosure which is constructed by double-shot injection molding with polycarbonate and thermoplastic elastomer alloy. The non-metallic enclosure consists of a front half (cover) and a back half (body). A wide LCD window of the front half of the enclosure is fully covered with an anti-static coating film. A metallic suspender clip is attached to the back half of the enclosure. The parts of the enclosure are secured by screws. The detector has no facilities for connection of external circuits.

Power is provided by non-user replaceable, two Lithium/Thionyl chloride (Li/SOCl₂) batteries (Tekcell, type SB-AA11 manufactured by VITZRO CELL, AA size, Nominal 3.6 V, Peak 3.9 V, 2.5 Ah) connected in parallel. The detector is intended to be a disposable unit. The ambient temperature range for the series is -20 °C $\leq T_a \leq +50$ °C.

The configuration for GFM-400 series is as follows;

GFM-400(-X)(-Y)

- GFM-400: Model name
- *X: Flammable gas type (blank(default sensor), MM2.5, MM100, MP1.5, MP2.5, PP1.5, PP2.5)
- * : This option can be selected only if the user require a particular target gas, a particular calibration gas and a particular measurement range different from the default sensor to detect a flammable gas (CH₄ or C₃H₈).

BARCODE area

for future

- **Y: Housing body color (blank : orange(default), YE : yellow, GN : green, VT : violet, and etc.)
- **: This option is not marked on the label and can only be used at an order if the user require a particular housing body color different from the default. The option does not affect intrinsic safety.

For the detailed information, see the instruction manual.

Copy of Marking Plate:

G-Finder Multi

Model: GFM-400 S/N: XXXXXXXX IECEx KTL 19.0028X XXX XX ATEX XXXX

GYJxx.xxxxX 19-KA2BO-XXXX

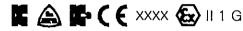
R-C-G99-GFM-400

Ex ia IIC T4 Ga IP68

 $(-20^{\circ}C \le Ta \le +50^{\circ}C)$

Manufactured: Gastron Co., Ltd.

Address: 23, gunpocheomdansaneop 1- ro,Gunpo-si Gyeonggi-do, 15881, Rep. of KOREA





Understand manual before operating



YYYYMM Made in Korea

Details regarding 'trade agent' / 'local assembler' application in accordance with OD 203:

N/A

Testing not fully performed by ExTL staff at the above ExTL address:

N/A

National differences considered as part of this evaluation:

N/A

"Specific Conditions of Use" / "Schedule of Limitations":

The G-Finder Multi GFM-400 is provided with the anti-static coating film covering over the LCD window to avoid danger of ignition due to electrostatic charge. Periodic inspection of this coating film is required to ensure no degradation, delamination, abrasions or other deformities to this surface. Care must be taken to avoid exposure to excessive heat, harsh chemicals or solvents, sharp edges and abrasive surfaces. Clean only with a damp cloth.

Routine tests:

N/A

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| Technical Documents | | | |
|--------------------------------------|-------------|---|------------|
| Title: Drawing No.: Rev. Level: Date | | | |
| GFM-400 INTRINSIC BLOCK DIAGRAM | Ex-GE-25S00 | 1 | 2019-08-14 |
| GFM-400 MAIN SCHEMATIC | Ex-GE-25S01 | 1 | 2019-07-24 |
| GFM-400 SENSOR SCHEMATIC | Ex-GE-25S02 | 1 | 2019-08-13 |

| GFM-400 BLEUTOOTH SCHEMATIC Ex-GE-25803 1 2019-07-15 TOP LAYER / MAIN PCB Ex-GE-25P00-1 0 2019-07-22 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / MAIN PCB Ex-GE-25P00-3 0 2019-07-22 BOTTOM LAYER / MAIN PCB Ex-GE-25P00-3 0 2019-07-22 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYER / MAIN PCB Ex-GE-25P00-5 0 2019-07-22 GROUND PLANE / MAIN PCB Ex-GE-25P00-6 0 2019-07-22 POWER PLANE / MAIN PCB Ex-GE-25P00-7 0 2019-07-22 FOWER PLANE J IMENSION / MAIN PCB Ex-GE-25P00-8 0 2019-07-22 ROTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 ROWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 POWER PLANE J SENSOR PCB Ex-GE-25P01-1 0 2019-07-22 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / SENSOR PCB Ex-GE-25P01-1 0 2019-09-20 SILK SCREEN FOTTOM + SOLDER MASK BOTTOM Ex-GE-25P01-3 0 | | | | |
|---|-------------------------------------|----------------|-----|------------|
| SILK SCREEN TOP + SOLDER MASK TOP LAYERS / MAIN PCB Ex-GE-25P00-2 0 2019-07-22 BOTTOM LAYER / MAIN PCB Ex-GE-25P00-3 0 2019-07-22 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P00-4 0 2019-07-22 LAYERS / MAIN PCB Ex-GE-25P00-5 0 2019-07-22 GROUND PLANE / MAIN PCB Ex-GE-25P00-6 0 2019-07-22 FOWER PLANE / MAIN PCB Ex-GE-25P00-7 0 2019-07-22 GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-8 0 2019-07-22 GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DOWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-1 0 2019-07-22 DRILL / MAIN PCB | GFM-400 BLEUTOOTH SCHEMATIC | Ex-GE-25S03 | 1 | 2019-07-15 |
| MAIN PCB Ex-GE-25P00-3 0 2019-07-22 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P00-4 0 2019-07-22 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P00-5 0 2019-07-22 LAYERS / MAIN PCB Ex-GE-25P00-6 0 2019-07-22 POWER PLANE / MAIN PCB Ex-GE-25P00-7 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-8 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P01-1 0 2019-07-22 DRILL / SENSOR PCB Ex-GE-25P01-1 0 2019-07-22 SILK SCREEN TOP + SOLDER MASK BOTTOM Ex | TOP LAYER / MAIN PCB | Ex-GE-25P00-1 | 0 | 2019-07-22 |
| SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P00-4 0 2019-07-22 LAYERS / MAIN PCB Ex-GE-25P00-5 0 2019-07-22 POWER PLANE / MAIN PCB Ex-GE-25P00-6 0 2019-07-22 POWER PLANE / MAIN PCB Ex-GE-25P00-7 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-8 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P01-1 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P01-1 0 2019-07-22 POWER PLANE DIMENSION PCB Ex-GE-25P01-1 0 2019-07-22 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / Ex-GE-25P01-2 0 2019-09-20 SILK SCREEN TOP + SOLDER MASK BOTTOM Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTT + SOLDER MASK BOTTOM Ex-GE-25P01-6 0 2019-09-20 | | Ex-GE-25P00-2 | 0 | 2019-07-22 |
| LAYERS / MAIN PCB Ex-GE-25P00-5 0 2019-07-22 POWER PLANE / MAIN PCB Ex-GE-25P00-6 0 2019-07-22 TOP LAYER DIMENSION / MAIN PCB Ex-GE-25P00-7 0 2019-07-22 TOP LAYER DIMENSION / MAIN PCB Ex-GE-25P00-8 0 2019-07-22 GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P01-1 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P01-1 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P01-1 0 2019-07-22 DRILL / SENSOR PCB Ex-GE-25P01-1 0 2019-07-22 DRILL / SENSOR PCB Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P01-4 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 0 | BOTTOM LAYER / MAIN PCB | Ex-GE-25P00-3 | 0 | 2019-07-22 |
| POWER PLANE / MAIN PCB Ex-GE-25P00-6 0 2019-07-22 TOP LAYER DIMENSION / MAIN PCB Ex-GE-25P00-7 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-8 0 2019-07-22 BOTTOM LAYER DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 TOP LAYER / SENSOR PCB Ex-GE-25P01-1 0 2019-09-20 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / SENSOR PCB Ex-GE-25P01-2 0 2019-09-20 BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-4 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 TOP LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 </td <td></td> <td>Ex-GE-25P00-4</td> <td>0</td> <td>2019-07-22</td> | | Ex-GE-25P00-4 | 0 | 2019-07-22 |
| TOP LAYER DIMENSION / MAIN PCB | GROUND PLANE / MAIN PCB | Ex-GE-25P00-5 | 0 | 2019-07-22 |
| BOTTOM LAYER DIMENSION / MAIN PCB | POWER PLANE / MAIN PCB | Ex-GE-25P00-6 | 0 | 2019-07-22 |
| GROUND PLANE DIMENSION / MAIN PCB Ex-GE-25P00-9 0 2019-07-22 POWER PLANE DIMENSION / MAIN PCB Ex-GE-25P00-10 0 2019-07-22 DRILL / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 TOP LAYER / SENSOR PCB Ex-GE-25P01-1 0 2019-09-20 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / SENSOR PCB Ex-GE-25P01-2 0 2019-09-20 BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS / SENSOR PCB Ex-GE-25P01-4 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-1 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-1 0 2019-09-20 < | TOP LAYER DIMENSION / MAIN PCB | Ex-GE-25P00-7 | 0 | 2019-07-22 |
| POWER PLANE DIMENSION / MAIN PCB | BOTTOM LAYER DIMENSION / MAIN PCB | Ex-GE-25P00-8 | 0 | 2019-07-22 |
| DRILL / MAIN PCB Ex-GE-25P00-11 0 2019-07-22 TOP LAYER / SENSOR PCB Ex-GE-25P01-1 0 2019-09-20 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / SENSOR PCB Ex-GE-25P01-2 0 2019-09-20 BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-4 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 TOP LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 | GROUND PLANE DIMENSION / MAIN PCB | Ex-GE-25P00-9 | 0 | 2019-07-22 |
| TOP LAYER / SENSOR PCB SILK SCREEN TOP + SOLDER MASK TOP LAYERS / Ex-GE-25P01-2 SILK SCREEN TOP + SOLDER MASK TOP LAYERS / Ex-GE-25P01-2 BOTTOM LAYER / SENSOR PCB BOTTOM LAYER / SENSOR PCB SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P01-4 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P01-5 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM Ex-GE-25P01-5 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 O 2019-09-20 DOWER PLANE / SENSOR PCB Ex-GE-25P01-7 O 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 O 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 O 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-10 O 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-11 O 2019-09-20 TOP LAYER(SILK SCREEN TOP + SOLDER MASK TOP) LAYERS / BLUETOOTH PCB BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) Ex-GE-25P02-1 BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) Ex-GE-25P02-1 GROUND-1 PLANE / BLUETOOTH PCB Ex-GE-25P02-3 O.3 2019-07-19 GROUND-2 PLANE / BLUETOOTH PCB Ex-GE-25P02-3 O.3 2019-07-19 GFM-400 MAIN PART LIST Ex-GE-25P02-1 1 2019-09-20 GFM-400-IM(M)-COVER Ex-A19060019 O 2019-07-29 GFM-400-IM(M)-COVER GFM-400-IM(M)-CO BKT Ex-A19060020 O 2019-07-29 GFM-400-IM(M)-CD BKT | POWER PLANE DIMENSION / MAIN PCB | Ex-GE-25P00-10 | 0 | 2019-07-22 |
| SILK SCREEN TOP + SOLDER MASK TOP LAYERS / SENSOR PCB Ex-GE-25P01-2 0 2019-09-20 BOTTOM LAYER / SENSOR PCB Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS / SENSOR PCB Ex-GE-25P01-4 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-11 0 2019-09-20 TOP LAYER(SILK SCREEN TOP + SOLDER MASK TOP) LAYERS / BLUETOOTH PCB Ex-GE-25P02-1 0.3 2019-07-19 BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) LAYERS / BLUETOOTH PCB | DRILL / MAIN PCB | Ex-GE-25P00-11 | 0 | 2019-07-22 |
| SENSOR PCB Ex-GE-25P01-3 0 2019-09-20 SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS / SENSOR PCB Ex-GE-25P01-4 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 TOP LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-11 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 BORTICKIK SCREEN TOP + SOLDER MASK Ex-GE-25P02-1 0.3 | TOP LAYER / SENSOR PCB | Ex-GE-25P01-1 | 0 | 2019-09-20 |
| SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS / SENSOR PCB Ex-GE-25P01-4 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 TOP LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P02-1 0.3 2019-07-19 GROUND-1 PLANE / BLUETOOTH PCB Ex-GE-25P02-2 | | Ex-GE-25P01-2 | 0 | 2019-09-20 |
| LAYERS / SENSOR PCB Ex-GE-25P01-5 0 2019-09-20 GROUND PLANE / SENSOR PCB Ex-GE-25P01-6 0 2019-09-20 POWER PLANE / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 TOP LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-11 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-11 0 2019-09-20 TOP LAYER(SILK SCREEN TOP + SOLDER MASK Ex-GE-25P02-1 0.3 2019-07-19 BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) Ex-GE-25P02-1 0.3 2019-07-19 GROUND-1 PLANE / BLUETOOTH PCB Ex-GE-25P02-2 0.3 2019-07-19 GROUND-2 PLANE / BLUETOOTH PCB Ex-GE-25P02-3 0.3 2019-07-19 <tr< td=""><td>BOTTOM LAYER / SENSOR PCB</td><td>Ex-GE-25P01-3</td><td>0</td><td>2019-09-20</td></tr<> | BOTTOM LAYER / SENSOR PCB | Ex-GE-25P01-3 | 0 | 2019-09-20 |
| POWER PLANE / SENSOR PCB | | Ex-GE-25P01-4 | 0 | 2019-09-20 |
| TOP LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-7 0 2019-09-20 BOTTOM LAYER DIMENSION / SENSOR PCB Ex-GE-25P01-8 0 2019-09-20 GROUND PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-9 0 2019-09-20 POWER PLANE DIMENSION / SENSOR PCB Ex-GE-25P01-10 0 2019-09-20 DRILL / SENSOR PCB Ex-GE-25P01-11 0 2019-09-20 TOP LAYER(SILK SCREEN TOP + SOLDER MASK TOP) LAYERS / BLUETOOTH PCB Ex-GE-25P02-1 0.3 2019-07-19 BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) LAYERS / BLUETOOTH PCB Ex-GE-25P02-2 0.3 2019-07-19 GROUND-1 PLANE / BLUETOOTH PCB Ex-GE-25P02-3 0.3 2019-07-19 GROUND-2 PLANE / BLUETOOTH PCB Ex-GE-25P02-4 0.3 2019-07-19 GFM-400 MAIN PART LIST Ex-GE-25B00 1 2019-07-19 GFM-400 SENSOR PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GROUND PLANE / SENSOR PCB | Ex-GE-25P01-5 | 0 | 2019-09-20 |
| BOTTOM LAYER DIMENSION / SENSOR PCB | POWER PLANE / SENSOR PCB | Ex-GE-25P01-6 | 0 | 2019-09-20 |
| GROUND PLANE DIMENSION / SENSOR PCB | TOP LAYER DIMENSION / SENSOR PCB | Ex-GE-25P01-7 | 0 | 2019-09-20 |
| POWER PLANE DIMENSION / SENSOR PCB | BOTTOM LAYER DIMENSION / SENSOR PCB | Ex-GE-25P01-8 | 0 | 2019-09-20 |
| DRILL / SENSOR PCB Ex-GE-25P01-11 0 2019-09-20 TOP LAYER(SILK SCREEN TOP + SOLDER MASK TOP) LAYERS / BLUETOOTH PCB Ex-GE-25P02-1 0.3 2019-07-19 BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) LAYERS / BLUETOOTH PCB Ex-GE-25P02-2 0.3 2019-07-19 GROUND-1 PLANE / BLUETOOTH PCB Ex-GE-25P02-3 0.3 2019-07-19 GROUND-2 PLANE / BLUETOOTH PCB Ex-GE-25P02-4 0.3 2019-07-19 GFM-400 MAIN PART LIST Ex-GE-25B00 1 2019-07-19 GFM-400 SENSOR PART LIST Ex-GE-25B01 1 2019-08-14 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060021 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GROUND PLANE DIMENSION / SENSOR PCB | Ex-GE-25P01-9 | 0 | 2019-09-20 |
| TOP LAYER(SILK SCREEN TOP + SOLDER MASK TOP) LAYERS / BLUETOOTH PCB BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) LAYERS / BLUETOOTH PCB GROUND-1 PLANE / BLUETOOTH PCB GROUND-2 PLANE / BLUETOOTH PCB GFM-400 MAIN PART LIST GFM-400 SENSOR PART LIST Ex-GE-25B00 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 GENERAL ASSEMBLY GENERAL ASSEMBLY GFM-400-IM(M)-COVER GFM-400-IM(M)-BODY GFM-400-IM(M)-LCD BKT Ex-A19060021 0.3 2019-07-19 Ex-GE-25P02-2 0.3 2019-07-19 Ex-GE-25P02-3 0.3 2019-07-19 Ex-GE-25P02-4 0.3 2019-07-19 Ex-GE-25B00 1 2019-07-29 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 | POWER PLANE DIMENSION / SENSOR PCB | Ex-GE-25P01-10 | 0 | 2019-09-20 |
| TOP) LAYERS / BLUETOOTH PCB Ex-GE-25P02-2 0.3 2019-07-19 BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) LAYERS / BLUETOOTH PCB Ex-GE-25P02-3 0.3 2019-07-19 GROUND-1 PLANE / BLUETOOTH PCB Ex-GE-25P02-4 0.3 2019-07-19 GROUND-2 PLANE / BLUETOOTH PCB Ex-GE-25P02-4 0.3 2019-07-19 GFM-400 MAIN PART LIST Ex-GE-25B00 1 2019-09-30 GFM-400 SENSOR PART LIST Ex-GE-25B01 1 2019-08-14 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | DRILL / SENSOR PCB | Ex-GE-25P01-11 | 0 | 2019-09-20 |
| LAYERS / BLUETOOTH PCB Ex-GE-25P02-3 0.3 2019-07-19 GROUND-2 PLANE / BLUETOOTH PCB Ex-GE-25P02-4 0.3 2019-07-19 GFM-400 MAIN PART LIST Ex-GE-25B00 1 2019-09-30 GFM-400 SENSOR PART LIST Ex-GE-25B01 1 2019-08-14 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | | Ex-GE-25P02-1 | 0.3 | 2019-07-19 |
| GROUND-2 PLANE / BLUETOOTH PCB | | Ex-GE-25P02-2 | 0.3 | 2019-07-19 |
| GFM-400 MAIN PART LIST Ex-GE-25800 1 2019-09-30 GFM-400 SENSOR PART LIST Ex-GE-25801 1 2019-08-14 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GROUND-1 PLANE / BLUETOOTH PCB | Ex-GE-25P02-3 | 0.3 | 2019-07-19 |
| GFM-400 SENSOR PART LIST Ex-GE-25B01 1 2019-08-14 GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GROUND-2 PLANE / BLUETOOTH PCB | Ex-GE-25P02-4 | 0.3 | 2019-07-19 |
| GFM-400 BLUETOOTH PART LIST Ex-GE-25B02 1 2019-07-24 GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GFM-400 MAIN PART LIST | Ex-GE-25B00 | 1 | 2019-09-30 |
| GENERAL ASSEMBLY Ex-A19060018 0 2019-07-29 GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GFM-400 SENSOR PART LIST | Ex-GE-25B01 | 1 | 2019-08-14 |
| GFM-400-IM(M)-COVER Ex-A19060019 0 2019-07-29 GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GFM-400 BLUETOOTH PART LIST | Ex-GE-25B02 | 1 | 2019-07-24 |
| GFM-400-IM(M)-BODY Ex-A19060020 0 2019-07-29 GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GENERAL ASSEMBLY | Ex-A19060018 | 0 | 2019-07-29 |
| GFM-400-IM(M)-LCD BKT Ex-A19060021 0 2019-07-29 | GFM-400-IM(M)-COVER | Ex-A19060019 | 0 | 2019-07-29 |
| | GFM-400-IM(M)-BODY | Ex-A19060020 | 0 | 2019-07-29 |
| GFM-400-IM(M)-PCB BKT Ex-A19060022 0 2019-07-29 | GFM-400-IM(M)-LCD BKT | Ex-A19060021 | 0 | 2019-07-29 |
| | GFM-400-IM(M)-PCB BKT | Ex-A19060022 | 0 | 2019-07-29 |

| Ex-A18120012 | 0 | 2019-07-29 |
|----------------|--|--|
| Ex-A19060023 | 0 | 2019-07-29 |
| Ex-A19060024 | 0 | 2019-07-29 |
| Ex-A18120009 | 0 | 2019-07-29 |
| Ex-A18120013 | 0 | 2019-07-29 |
| Ex-A19060025 | 0 | 2019-07-29 |
| Ex-A19060026 | 0 | 2019-07-29 |
| Ex-A19060027 | 0 | 2019-07-29 |
| Ex-A19060028 | 0 | 2019-07-29 |
| Ex-A19060029 | 0 | 2019-07-29 |
| Ex-A19060030 | 0 | 2019-07-29 |
| Ex-A19060031 | 0 | 2019-07-01 |
| Ex-A19060032 | 0 | 2019-07-29 |
| Ex-A19100005 | 0 | 2019-11-08 |
| Ex-A19100004 | 0 | 2019-11-08 |
| GT-07919072501 | 0.1 | 2019-07-25 |
| | Ex-A19060023 Ex-A19060024 Ex-A18120009 Ex-A18120013 Ex-A19060025 Ex-A19060026 Ex-A19060027 Ex-A19060029 Ex-A19060030 Ex-A19060031 Ex-A19060032 Ex-A19100005 Ex-A19100004 | Ex-A19060023 0 Ex-A19060024 0 Ex-A18120009 0 Ex-A18120013 0 Ex-A19060025 0 Ex-A19060026 0 Ex-A19060027 0 Ex-A19060028 0 Ex-A19060029 0 Ex-A19060030 0 Ex-A19060031 0 Ex-A19060032 0 Ex-A19100005 0 Ex-A19100004 0 |



IECEX TEST REPORT IEC 60079-0

Explosive atmospheres - Part 0: Equipment - General requirements

ExTR Reference Number....: KR/KTL/ExTR19.0029/00

ExTR Free Reference Number: PI181060

Compiled by + signature (ExTL): Choi, Yong-Won

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Date of issue: 2019.11.19.

Ex Testing Laboratory (ExTL): KTL(Korea Testing Laboratory)

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Korea

Standard....: IEC 60079-0:2017, Edition 7.0

Test procedure: **IECEx System**

Test Report Form Number: ExTR60079-0 7B DS (released 2018-01)

Related Amendments, Corrigenda or

ISHs..... N/A

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Possible test case verdicts:

- test item does meet the requirement:Pass

General remarks:

The test results presented in this Ex Test Report relate only to the item or product tested.

- "(see Attachment #)" refers to additional information appended to this document.
- "(see appended table)" refers to a table appended to this document.
- Throughout this document, a point "." is used as the decimal separator.

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| | | IEC 60079-0 | |
|----------------------------------|---|--|-------------|
| Clause | Requirement Test | Result – Remark | Verdict |
| 1 | Scope | | |
| 2 | Normative references | | |
| 3 | Terms and definitions | | |
| 4 | Equipment grouping | | |
| 4.1 | General | The equipment is for Group IIC application. | Pass |
| 4.2 | Group I | The equipment is for Group IIC application. | N/A |
| 4.3 | Group II | The equipment is for Group IIC application. | Pass |
| 4.4 | Group III | The equipment is for Group IIC application. | N/A |
| 4.5 | Equipment for a particular explosive gas atmosphere | The equipment is for Group IIC application. | N/A |
| 5 See also DS 2015/011A | Temperatures | | |
| 5.1 | Environmental influences | | |
| 5.1.1 | Ambient temperature | The ambient temperature for T4 class is -20 °C $\leq T_a$ \leq +50 °C. Instead of applying 'X' marking, the upper information is included in the marking label on the equipment and the manual. | Pass |
| 5.1.2 | External source of heating or cooling | The equipment is a hand-held, battery powered device. Thus, there are no external sources of heating or cooling. | N/A |

| | | IEC 60079-0 | |
|--------|---------------------|--|---------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| | | The equipment is not intended to be connected to a separate external source of heating or cooling. The maximum surface temperature rise of the non-metallic enclosure and internal PCB bracket of the equipment determined at worst fault conditions is negligible (less than 10 K). The service temperature is regarded as 60 °C at 50 °C ambient. | |
| 5.2 | Service temperature | Minimum thermal deformation temperature of the non-metallic enclosure and internal PCB bracket is 80 °C, which is higher than 60 °C. Highest continuous operating temperatures of adhesive materials used for attaching the marking label and the anti-static coating film to the enclosure are 145 °C and 180 °C respectively, which are higher than 60 °C. Thus, the service temperature does not adversely affect the type of protection, intrinsic safety. | Pass |

| 5.3 | Maximum surface temperature | | |
|-----------|---|--|------|
| 5.3.1 | Determination of maximum surface temperature | The equipment is marked as T4. | Pass |
| 5.3.2 | Limitation of maximum surface to | emperature | |
| 5.3.2.1 | Group I electrical equipment | The equipment is for Group IIC application. | N/A |
| 5.3.2.2 | Group II electrical equipment | The equipment was assessed to satisfy the assigned temperature class T4 (135 °C) at 50 °C ambient. | Pass |
| | | See Cl.5.3.3 for the details. | |
| 5.3.2.3 | Group III electrical equipment | | |
| 5.3.2.3.1 | Maximum surface temperature for EPL Da | The equipment is for Group IIC application. | N/A |
| 5.3.2.3.2 | Maximum surface temperature for EPL Db | The equipment is for Group IIC application. | N/A |
| 5.3.2.3.3 | Maximum surface temperature determined without a layer of dust for EPL Dc | The equipment is for Group IIC application. | N/A |

| | | IEC 60079-0 | · |
|--------|---|---|----------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| | | All the small components on the boards conform to Table 3 and Table 4. | |
| 5.3.3 | Small component temperature for Group I or Group II electrical equipment | In case of small components having total surface area not less than 20 mm², maximum dissipation power in each component is less than 1.25 W required at T4 and 50 °C ambient as per Table 4 because maximum power supplied from the batteries to the boards after passing through the zener diodes, D1~D2, the internal resistance of the batteries and the current limiting resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board, is 0.130 W and maximum dissipation power of each current limiting resistor is 0.374 W. | Pass |
| | | In case of small components having total surface area less than 20 mm², maximum surface temperature of the components does not exceed 275 °C as per Table 3. See Cl. 26.5.1.3 for the details. | |
| | | Therefore, considering the above, the equipment satisfies the assigned temperature class T4 at 50 °C ambient. | |
| 5.3.4 | Component temperature of smooth surfaces for Group I or Group II electrical equipment | This clause is not applicable. | N/A |
| | | | |
| 6 | Requirements for all electrical eq | uipment | |
| 6.1 | General | To supplement IEC 60079-0:2017, IEC 60079- 11:2011 was applied. | Pass |
| 6.2 | Mechanical strength of equipment | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 6.3 | Opening times | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| , | C: | This player is explicited as year Table 4 of ICO | <u> </u> |
| 6.4 | Circulating currents in enclosures (e.g. of large electric machines) | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 6.5 | Gasket retention | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| | | | |
| 6.6 | Electromagnetic and ultrasonic e | nergy radiating equipment | |

| | IEC 60079-0 | | | |
|--------|---|--|---------|--|
| Clause | Requirement – Test | Result – Remark | Verdict | |
| | | The equipment contains two-way IR communications. Thus, the IR source, U3, shall be assessed as one of lasers or other non-divergent continuous wave optical sources. See Cl.6.6.4. | | |
| 6.6.1 | General | The equipment also contains five LEDs, D1~D5 on the sensor board. However, the LEDs are used for indicating the operating condition and are excluded from the assessment of this clause as per the exception of the equipment detailed in Cl.1 of IEC 60079-28:2015 because the LEDs are considered to belong to non-array divergent LEDs used for example to show equipment status or backlight function. | Pass | |
| 6.6.2 | Radio frequency sources | There are no radio frequency sources in the equipment. | N/A | |
| 6.6.3 | Ultrasonic sources | There are no ultrasonic sources in the equipment. | N/A | |
| | | The IR source shall satisfy the requirements as per Cl.5.2.2 of IEC 60079-28:2015. The IR source is used for EPL Ga, Group IIC and temperature class T4. The maximum input power of the IR source is limited within 3.2 mW by the | | |
| 6.6.4 | Lasers, luminaires, and other non-divergent continuous wave optical sources | internal resistance of the battery and the current limiting resistors, R5 on the main board and R25 on the sensor board, under consideration of fault conditions in accordance with the over-power / energy fault protection criteria according to Cl.5.2.5 of IEC 60079-28:2015. The aforementioned value, 3.2 mW, does not exceed the safe optical radiated power limit, 35 mW, listed in Table 2 of IEC 60079-28:2015. Thus, the equipment conforms to the requirements of IEC 60079-28:2015. | Pass | |

| | 7 | Non-metallic enclosures and non-metallic parts of enclosures |
|--|---|--|
|--|---|--|

| 7.1 | General | | |
|---------|------------------------------|--|-----|
| 7.1.1 | Applicability | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 7.1.2 | Specification of materials | | |
| 7.1.2.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 7.1.2.2 | Plastic materials | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 7.1.2.3 | Elastomers | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 7.1.2.4 | Materials used for cementing | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |

| Requirement - Test | Result - Remark | Verdict |
|--|--|--|
| • | Modult Montain | Verdict |
| | | |
| Thermal endurance | | |
| Tests for thermal endurance | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| Material selection | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| Alternative qualification of elastomeric sealing O-rings | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| | | • |
| Resistance to ultraviolet light | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| _ | Tests for thermal endurance Material selection Alternative qualification of elastomeric sealing O-rings | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. Material selection This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. Alternative qualification of elastomeric sealing O-rings This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. |

| 7.4 | Electrostatic charges of | on external non-metallic materials | |
|-------|--------------------------|---|------|
| 7.4.1 | Applicability | The equipment has a non-metallic enclosure, which is made of polycarbonate, LUPOY PC 1201-15, and is covered with conductive thermoplastic elastomer alloy, RTP 2099 E X 100781, and an anti-static coating film, JB-SD10008, for ESD protection. A certification label sticker is attached on the surface covered by the conductive elastomer. | Pass |

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|--------|---|--|---------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| | | The surface resistance of the conductive elastomer, RTP 2099 E X 100781, was tested as per Cl.26.13 and measured to be less than 3 × 108 Ω at (30 \pm 5) % relative humidity. | |
| | | The surface resistance of the anti-static coating film, JB-SD10008, was tested as per Cl.26.13 and measured to be less than 2 × $10^7 \Omega$ at (50 ± 5) % relative humidity. | |
| | | According to the construction of the enclosure, there are non-conductive parts made of polycarbonate, LUPOY PC 1301EP-30, which are accessible under normal condition of use, maintenance and cleaning in a hazardous location. The accessible parts are not covered by the conductive elastomer and the anti-static coating film as above. The surface areas of the accessible non-conductive parts exposed and unprotected are limited within the allowable size as per item b) of CI.7.4.2. | |
| 7.4.2 | Avoidance of a build-up of electrostatic charge for Group I or Group II | The maximum thickness of the certification label sticker as the non-metallic layer is 148 µm from the manufacturer's datasheet, which is limited within the allowable thickness, 0.2 mm, as per item c) of CI.7.4.2. | Pass |
| | | Thus, the non-metallic enclosure of the equipment is considered as suitable for avoidance of a build-up of electrostatic charge. | |
| | | Additionally, 'X' marking and the following specific condition of use are applied as per item d) of CI.7.4.2 by provision of the anti-static coating film; | |
| | | "The G-Finder Multi GFM-400 is provided with the anti-static coating film covering over the LCD window to avoid danger of ignition due to electrostatic charge. Periodic inspection of this coating film is required to ensure no degradation, delamination, abrasions or other deformities to this surface. Care must be taken to avoid exposure to excessive heat, harsh chemicals or solvents, sharp edges and abrasive surfaces. Clean only with a damp cloth." | |
| | | The specific condition above was specified in the instruction manual. See the instruction manual. | |
| 7.4.3 | Avoidance of a build-up of electrostatic charge for Group III | The equipment is for Group IIC application. | N/A |

| parts I ne equipment is portable or personal. N/A | 7.5 | Attached external conductive parts | The equipment is portable or personal. | N/A |
|---|-----|------------------------------------|--|-----|
|---|-----|------------------------------------|--|-----|

| 3 | Metallic enclosures and metallic parts of enclosures |] |
|---|--|---|
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| | | IEC 60079-0 | · |
|---------|-----------------------------|--|----------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 8.1 | Material composition | The drawings in technical documents of this IECEx Test Report Cover and the manufacturer's datasheet specify the material. | Pass |
| 8.2 | Group I | The equipment is for Group IIC application. | N/A |
| 0.2 | Group r | The equipment is for Group no application. | 14// |
| | | The suspender clip secured to the back half of the enclosure is made of stainless steel (STS304). | |
| 8.3 | Group II | STS304 does not contain, by mass, more than the material limits of this clause for EPL Ga. | Pass |
| <u></u> | | Refer to the material datasheet for the details. | <u> </u> |
| 8.4 | Group III | The equipment is for Group IIC application. | N/A |
| 8.5 | Copper Alloys | There are no parts of enclosures constructed of copper or copper alloys in the equipment. | N/A |
| 9 | Fasteners | | |
| 9.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 9.2 | Special fasteners | See Cl.9.1. | N/A |
| | | | |
| 9.3 | Holes for special fasteners | | |
| 9.3.1 | Thread engagement | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 9.3.2 | Tolerance and clearance | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 9.4 | Hexagon socket set screws | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 10 | Interlocking devices | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 11 | Bushings | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |

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|-------------------------------|--|--|---------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| 12 | (Reserved for future use) | | |
| 13 See also DS 2014/001 | Ex Components | | |
| 13.1 | General | The equipment is not an EX component. | N/A |
| 13.2 | Mounting | See Cl.13.1. | N/A |
| 13.3 | Internal mounting | See Cl.13.1. | N/A |
| 13.4 | External mounting | See Cl.13.1. | N/A |
| 13.5 | Ex Component certificate | See Cl.13.1. | N/A |
| 14 | Connection facilities | | |
| 14.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 14.2 | Type of protection | See Cl.14.1. | N/A |
| 14.3 | Creepage and clearance | See Cl.14.1. | N/A |
| 15 | Connection facilities for earthi | ng or bonding conductors | |
| 15.1 | Equipment requiring earthing | or bonding | |
| 15.1.1 | Internal earthing | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 15.1.2 | External bonding | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 15.2 | Equipment not requiring earthing | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 15.3 | Size of protective earthing conductor connection | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |

| _ | | IEC 60079-0 | |
|---------------|--|--|---------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| 15.4 | Size of equipotential bonding conductor connection | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 15.5 | Protection against corrosion | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 15.6 | Secureness of electrical connections | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 15.7 | Internal earth continuity plate | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 16 | Entries into enclosures | | |
| 16.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 16.2 | Identification of entries | See Cl.16.1. | N/A |
| 16.3 | Cable glands | See Cl.16.1. | N/A |
| 16.4 | Blanking elements | See Cl.16.1. | N/A |
| 16.5 | Thread adapters | See Cl.16.1. | N/A |
| 16.6 | Temperature at branching point and entry point | See Cl.16.1. | N/A |
| 16.7 | Electrostatic charges of cable sheaths | See Cl.16.1. | N/A |
| 17 | Supplementary requirements for | electric machines | |
| 17.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |

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|----------|--|--|---------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| 17.2 | Ventilation | | |
| 17.2.1 | Ventilation openings | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 17.2.2 | Materials for external fans | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 17.2.3 | Cooling fans of rotating electric machines | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 17.2.3.1 | Fans and fan hoods | See Cl.17.2.3. | N/A |
| 17.2.3.2 | Construction and mounting of the ventilating systems | See Cl.17.2.3. | N/A |
| 17.2.3.3 | Clearances for the ventilating system | See Cl.17.2.3. | N/A |
| 17.2.4 | Auxiliary motor cooling fans | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 17.2.5 | Room ventilating fans | | |
| 17.2.5.1 | Applicability | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 17.2.5.2 | General | See Cl.17.2.5.1. | N/A |
| 17.2.5.3 | Fan and fan hoods | See Cl.17.2.5.1. | N/A |
| 17.2.5.4 | Construction and mounting | See Cl.17.2.5.1. | N/A |
| 17.2.5.5 | Clearances for rotating parts | See Cl.17.2.5.1. | N/A |
| | | | |
| 17.3 | Bearings | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | | | |
| 18 | Supplementary requirements for | switchgear | |
| | | | |
| 18.1 | Flammable dielectric | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | | | |
| 18.2 | Disconnectors | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | | | |
| 18.3 | Group I – Provisions for locking | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |

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|--------|---|--|----------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 18.4 | Doors and covers | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 19 | Reserved for future use | | |
| 20 | Supplementary requirements for connection | external plugs, socket outlets and connectors for field | d wiring |
| 20.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 20.2 | Explosive gas atmospheres | See Cl.20.1. | N/A |
| 20.3 | Explosive dust atmospheres | See Cl.20.1. | N/A |
| 20.4 | Energized plugs | See Cl.20.1. | N/A |
| 21 | Supplementary requirements for | luminaires | |
| 21.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 21.2 | Covers for luminaires of EPL Mb, EPL Gb, or EPL Db | See Cl.21.1. | N/A |
| 21.3 | Covers for luminaires of EPL Gc or EPL Dc | See Cl.21.1. | N/A |
| 21.4 | Sodium lamps | See Cl.21.1. | N/A |
| 22 | Supplementary requirements for | caplights and handlights | |
| 22.1 | Group I caplights | The equipment is not a caplight nor a handlight. | N/A |
| 22.2 | Group II and Group III caplights and handlights | See Cl.22.1. | N/A |
| 23 | Equipment incorporating cells ar | | |

| | | IEC 60079-0 | |
|--------------|--|---|---------------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 23.1 | General | The equipment is battery operated. | Pass |
| | - " | | |
| 23.2 | Interconnection of cells to form batteries | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | | | , |
| | | The batteries used in the equipment are Tekcell, type SB-AA11 manufactured by VITZRO CELL | |
| 23.3 | Cell types | The battery consists of a Lithium/Thionyl chloride(Li/SOCl2) cell. Table 13 (Primary Cells) includes Lithium/Thionyl chloride(Li/SOCl2). | Pass |
| | | According to the requirements of DS 2019/002, the battery was confirmed to comply with the requirements of UL 1642 by 3rd-party certification of the lithium battery from an IECEE NCB, UL. | |
| | | | |
| 23.4 | Cells in a battery | The battery contains a single cell. | Pass |
| . | | T | |
| 23.5 | Ratings of batteries | The battery is used within the allowable limits defined by the battery manufacturer. | Pass |
| | | T. | |
| 23.6 | Interchangeability | Primary and secondary cells or batteries are not used inside the same equipment enclosure. The battery is not intended to be replaced by the user. | N/A |
| | | | |
| 23.7 | Charging of primary batteries | The equipment contains only two same primary batteries connected in parallel and has no other power sources nor connections for external circuits. | Pass |
| | | | |
| 23.8 | Leakage | Leakage of electrolyte did not occur during the test per Cl.10.5.2 of IEC 60079-11. | Pass |
| | | See Cl.10.5.2 in ExTR of IEC 60079-11. | |
| | | | - |
| 23.9 | Connections | The battery is not intended to be replaced by the user. Making electrical connection to the batteries need not be considered by the user. | N/A |
| | | | |
| 23.10 | Orientation | The battery is not intended to be replaced by the user. The indication of battery orientation is not necessary. | N/A |
| | | | 1 |
| 23.11 | Replacement of cells or batteries | The battery is not intended to be replaced by the user. | N/A |

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|-----------------------------------|---|---|------------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 23.12 | Replaceable battery pack | The battery is not intended to be replaced by the user. | N/A |
| 24 | Documentation | Documents submitted by the manufacturer provide details of the explosion safety aspects of the equipment necessary to determine compliance with Ex standards. See technical documents of the IECEx Test Report | Pass |
| | | Cover. | |
| 25 | Compliance of prototype or sample with documents | Compliance of prototype or sample with documents is secured. | Pass |
| 26 | Type tests | | |
| 26.1 | Conorol | All the negerous tests were serviced out | Pass |
| 26.1 | General | All the necessary tests were carried out. | Pass |
| 26.2 | Test configuration | Most unfavourable configurations were considered. | Pass |
| 26.3 | Tests in explosive test mixtures | All test mixtures have above 95% purity. | Pass |
| 26.4 | Tests of enclosures | | |
| 26.4.1 | Order of tests | | |
| 26.4.1.1 | Metallic enclosures, metallic parts of enclosures and glass parts of enclosures | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.4.1.2 | Non-metallic enclosures or non-r | metallic parts of enclosures | |
| 26.4.1.2.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.4.1.2.2 | Group I equipment | See Gl-26.4.1.2.1 | N/A |
| 26.4.1.2.3 | Group II and Group III equipment | See Cl.26.4.1.2.1. | N/A |
| 26.4.2 | Resistance to impact | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.4.3 | Drop test | The equipment was dropped four times from a height of 1 m onto a horizontal concrete surface while at 5 K below the minimum ambient temperature of -20 °C. | Pass |
| 26.4.4 | Acceptance criteria | There was no ejection or separation of any component from the equipment and no damage to invalidate intrinsic safety of the equipment. | Pass |
| 26.4.5 See also DS 2012/003 | Degree of protection (IP) by encl | losures | |

| | | IEC 60079-0 | | |
|----------|---------------------|---|---------|--|
| Clause | Requirement - Test | Result – Remark | Verdict | |
| 26.4.5.1 | Test procedure | IP Test was conducted according to IEC 60529. | Pass | |
| 26.4.5.2 | Acceptance criteria | The equipment is considered to provide a degree of protection of at least IP20 by examination of drawings and test of a sample unit. (IP20 is required as minimum according to Cl.6.1.2.2 of IEC 60079-11). | Pass | |

| 26.5 | Thermal tests | | |
|----------|----------------------------------|---|------|
| 26.5.1 | Temperature measurement | | |
| 26.5.1.1 | General | Surface temperature for the purpose of intrinsic safety was determined by evaluation or was measured by testing as this clause. | Pass |
| 26.5.1.2 | Service temperature | The maximum surface temperature rise of the non-metallic enclosures of the equipment determined at worst fault conditions is negligible (less than 10 K). The service temperature is regarded as 60 °C at 50 °C ambient. | Pass |
| | | In case of small components having total surface area less than 20 mm², maximum surface temperature of the components does not exceed 275 °C required at T4 and 50 °C ambient as per Table 3. In other words, their thermal coefficients, Rthj-a (Junction to Ambient) or Rthc-a (Case to Ambient), shall be less than (275 °C - 50 °C) / 0.130 W = 1 730 °C/W. | |
| | | Temperature tests were conducted on some small components to determine their thermal coefficients which are not obtained from the manufacturers. The results were determined as follows. | |
| 26.5.1.3 | Maximum surface temperature | 1) R31(100 Ω, 1/10 W) on the sensor board at 0.130 W : 41.3 °C at 24.7 °C ambient → Rthc-a = (41.3 °C − 24.7 °C) / 0.130 W = 127 °C/W. | Pass |
| | | 2) R43(51 Ω, 1/4 W) on the sensor board at 0.130 W : 38.7 °C at 24.7 °C ambient → Rthc-a = (38.7 °C − 24.7 °C) / 0.132 W = 106 °C/W. | |
| | | The components smaller than 20 mm ² were verified from the manufacturers' datasheets and the testing results above as having their thermal coefficients less than 1 730 °C/W. | |
| | | Therefore, considering the above, the equipment satisfies the assigned temperature class T4 at 50 °C ambient. | |
| | | Refer to Appendix A.3.1 and B.1 in ExTR of IEC 60079-11 for details. | |
| 26.5.2 | Thermal shock test | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.5.3 | Small component ignition test (C | Group I and Group II) | |
| 26.5.3.1 | General | This clause is excluded because the small component ignition test is not necessary. | N/A |
| 26.5.3.2 | Procedure | See Cl.26.5.3.1. | N/A |

| | | IEC 60079-0 | |
|----------|--|--|---------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| 26.5.3.3 | Acceptance criteria | See Cl.26.5.3.1. | N/A |
| | | | |
| 26.6 | Torque test for bushings | | |
| 26.6.1 | Test procedure | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 26.6.2 | Acceptance criteria | See Cl.26.6.1. | N/A |
| | | | |
| 26.7 | Non-metallic enclosures or non- | metallic parts of enclosures | |
| 26.7.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.7.2 | Test temperatures | See Cl.26.7.1. | N/A |
| - | | | |
| 26.8 | Thermal endurance to heat | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| | | | |
| 26.9 | Thermal endurance to cold | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| | | | |
| 26.10 | Resistance to UV light | | |
| 26.10.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.10.2 | Light exposure | See Cl.26.10.1. | N/A |
| 26.10.3 | Acceptance criteria | See Cl.26.10.1. | N/A |
| | | | |
| 26.11 | Resistance to chemical agents for Group I equipment | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| | -, | | |
| 26.12 | Earth continuity | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | | | |
| 26.13 | Surface resistance test of parts of enclosures of non-metallic | The surface resistance of the conductive elastomer, RTP 2099 E X 100781, was tested as per Cl.26.13 and measured to be less than 3 × 10 ⁸ Ω at (30 ± 5) % relative humidity. | Pass |
| 20.10 | materials | The surface resistance of the anti-static coating film, JB-SD10008, was tested as per Cl.26.13 and measured to be less than 2 × $10^7 \Omega$ at (50 ± 5) % relative humidity. | , 466 |

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|---------|--|--|---------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 26.14 | Measurement of capacitance | | |
| 26.14.1 | General | See Cl.7.5. | N/A |
| 26.14.2 | Test procedure | See Cl.26.14.1. | N/A |
| | | | • |
| 26.15 | Verification of ratings of ventilating fans | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| 26.16 | Alternative qualification of elastomeric sealing O-rings | This clause is excluded as per Table 1 of IEC 60079-11 because Cl.6.1.2.3 a) of IEC 60079-11 is not applied for the assessment of the equipment. | N/A |
| 26.17 | Transferred charge test | | |
| 26.17.1 | Test equipment | See Cl.7.4.2. | N/A |
| 26.17.2 | Test sample | See Cl.7.4.2. | N/A |
| 26.17.3 | Test procedure | See Cl.7.4.2. | N/A |
| | , | | 1 |
| 27 | Routine tests | Routine tests are not considered necessary. | N/A |
| | | | |
| 28 | Manufacturer's responsibility | | |
| 28.1 | Conformity with the documentation | Manufacturer's responsibility | Pass |
| 28.2 | Certificate | See Cl.28.1. | Pass |
| | | | _ |
| 28.3 | Responsibility for marking | By marking the product in accordance with Cl.29, the manufacturer is attesting on his own responsibility that the equipment has been constructed in accordance with the applicable requirements of the relevant standards in safety matters. Routine verifications per Cl.28.1 have been successfully completed and the product complies with the documentation. | Pass |
| 29 | Marking | | |
| <u></u> | 1 | | |
| 29.1 | Applicability | Applicability of Ex marking is secured in the production process. | Pass |
| | | | 1 |
| 29.2 | Location | See the label drawing (Ex-A19060032). The marking is located on the enclosure in a clear | Pass |

| | | IEC 60079-0 | |
|-----------|---|--|--------------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| | | See the label drawing (Ex-A19060032). | |
| | | The marking includes the following: | |
| | | the name of the manufacturer or his registered trade mark; | |
| | | 2) the manufacturer's type identification; | |
| 29.3 | General | 3) a serial number; | Pass |
| 20.0 | | 4) the name or mark of the certificate issuer and the certificate reference; | |
| | | 5) the symbol "X" placed after the certificate reference; | |
| | | 6) the specific Ex marking, See Cl.29.4; | |
| | · | 7) any additional marking. | ļ |
| | | | |
| 29.4 | Ex marking for explosive gas atmospheres | Ex ia IIC T4 Ga | Pass |
| <u></u> . | | | |
| 29.5 | Ex marking for explosive dust atmospheres | The equipment is for Group IIC application. | N/A |
| _ | | | |
| 29.6 | Combined types (or levels) of protection | This clause is not applicable. | N/A |
| 29.7 | Multiple types of protection | This clause is not applicable. | N/A |
| | | | |
| 29.8 | Ga equipment using two independent Gb types (or levels) of protection | This clause is not applicable. | N/A |
| 29.9 | Boundary wall | This clause is not applicable. | N/A |
| _ | | | |
| 29.10 | Ex Components | The equipment is not an EX component. | N/A |
| 29.11 | Small Ex Equipment and small Ex Components | The equipment is not a small equipment. | N/A |
| | | | |
| 29.12 | Extremely small Ex Equipment and extremely small Ex Components | See Cl.29.11. | N/A |
| _ | | | |
| 29.13 | Warning markings | The equipment does not need any warning marking. | N/A |
| | | | |
| 29.14 | Cells and batteries | The battery is not intended to be replaced by the user. | N/A |
| | | | |

| | | IEC 60079-0 | , |
|------------------------|---|--|--------------|
| Clause | Requirement – Test | Result – Remark | Verdic |
| 29.15 | Electric machines operated with a converter | The equipment is not an electric machine operated with a converter. | N/A |
| 29.16 | Examples of marking | See Cl.29.3. | Pass |
| 30 | Instructions | | |
| 30.1 | General | Instruction manual complies with requirements of the standard. | Pass |
| 30.2 | Cells and batteries | The battery is not intended to be replaced by the user. | N/A |
| 30.3 | Electric machines | The equipment is not an electric machine. | N/A |
| 30.4 | Ventilating fans | The equipment is not a ventilating fan. | N/A |
| 30.5 | Cable glands | The equipment is not a cable gland. | N/A |
| Annex A (Normative) | Supplementary requirements for | cable glands | |
| A.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.2 | Constructional requirements | | |
| A.2.1 | Cable sealing | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.2.2 | Filling compounds | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.2.3 | Clamping | | <u> </u> |
| A.2.3.1 | General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.2.3.2 | Group II or III cable glands | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.2.4 | Lead-in of cable | | 1 |
| A.2.4.1 | Sharp edges | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.2.4.2 | Point of entry | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | | 1 | 1 |

| | IEC 60079-0 | |
|--|--|--|
| Requirement Test | Result – Remark | Verdict |
| Released by a tool | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Fixing | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Degree of protection | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Type tests | | |
| Tests of clamping of non-armour | ed and braided cables | |
| Cable glands with clamping by the sealing ring | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Cable glands with clamping by filling compound | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Cable glands with clamping by means of a clamping device | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Clamping test | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Mechanical strength | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Tests of clamping of armoured cables | | |
| Tests of clamping where the armourings are clamped by a device integral to the gland | | |
| General | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Clamping test | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Mechanical strength | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Tests of clamping where the armourings are not clamped by a device integral to the gland | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Type test for resistance to impact | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Test for degree of protection (IP) of cable glands | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| Marking | · · · · · · · · · · · · · · · · · · · | *1 |
| Marking of cable glands | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| | Released by a tool Fixing Degree of protection Type tests Tests of clamping of non-armour Cable glands with clamping by the sealing ring Cable glands with clamping by filling compound Cable glands with clamping by means of a clamping device Clamping test Mechanical strength Tests of clamping of armoured content of clamping where the armouring test Mechanical strength Clamping test Mechanical strength Tests of clamping where the armourings are not clamped by a device integral to the gland Type test for resistance to impact Test for degree of protection (IP) of cable glands Marking | Requirement - Test Result - Remark Released by a tool Scale - Remark This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. Type tests Tests of clamping of non-armoured and braided cables Cable glands with clamping by the sealing ring Cable glands with clamping by filling compound Cable glands with clamping by means of a clamping device Cable glands with clamping by means of a clamping device Cable glands with clamping by means of a clamping device Cable glands with clamping by means of a clamping device This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. Tests of clamping where the armourings are clamped by a device integral to the gland This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. Tests of clamping where the armourings are clamped by a device integral to the gland This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. Tests of clamping where the armourings are clamped by a device integral to the gland This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. Tests of clamping where the armourings are the equipment is an intrinsically safe apparatus. This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsic |

| IEC 60079-0 | | | |
|-------------|---------------------------------------|--|---------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| A.4.2 | Identification of cable-sealing rings | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |
| A.5 | Instructions | This clause is excluded as per Table 1 of IEC 60079-11 because the equipment is an intrinsically safe apparatus. | N/A |

| Annex B (Normative) Requirements for Ex Components | s | | |
|--|--|---------------------------------------|-----|
| Table B.1 | Applicability of clauses to Ex Components | The equipment is not an EX component. | N/A |

| Annex C (Informative) | Example of rig for resistance to impact test | |
|--------------------------|--|---|
| (Intormative) | | ļ |

| Annex D (Informative) | Electric machines connected to converters |
|-----------------------|---|

| Annex E (Informative) | Temperature evaluation of electric machines |
|-----------------------|---|
|-----------------------|---|

| Annex F | Guideline flowchart for tests of non-metallic enclosures or non-metallic parts of enclosures |
|---------------|--|
| (Informative) | |

| _ | | y-manufacture | _ |
|-----|--------------------------|--|---|
| - 1 | Annex G (Informative) | Guidance flowchart for tests of cable glands | |
| - 1 | | Guidance flowchart for tests of cable glands | |

| Annex H (Informative) | Shaft voltages resulting in motor bearing or shaft brush sparking Discharge energy calculation |
|--------------------------|--|

Measurement Section, including Additional Narrative Remarks (as deemed applicable) N/A



IECEx TEST REPORT IEC 60079-11

Explosive atmospheres - Part 11: Equipment protection by intrinsic safety "i"

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Korea

Standard: IEC 60079-11:2011, 6th Edition

Test procedure....:: IECEx System

Test Report Form Number.....: ExTR60079-11 6A DS (released 2017-09)

Instructions for Intended Use of Ex Test Report:

An Ex Test Report provides a clause-by-clause documentation of the initial evaluation and testing that verified compliance of an item or product with an IEC, ISO, ISO/IEC or IEC/IEEE Ex standard or technical specification. This Ex Test Report is part of an ExTR package that may include other Ex Test Report, Addendum, National Differences and Partial Testing documents, along with a single ExTR Cover. An Ex Test Report is to be compiled and reviewed by the ExTL. The Issuing ExCB indicates final approval of the Ex Test Report as part of the overall ExTR package on the associated ExTR Cover.

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Possible test case verdicts:

- test case does not apply to the test item:N / A
- test item does meet the requirement:Pass

General remarks:

The test results presented in this Ex Test Report relate only to the item or product tested.

- "(see Attachment #)" refers to additional information appended to this document.
- "(see appended table)" refers to a table appended to this document.
- Throughout this document, a point "." is used as the decimal separator.

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| | | EC 60079-11 | |
|---|--|--|----------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| 1 | Scope | | <u>.</u> |
| | Осоре | · · · · · · · · · · · · · · · · · · · | <u></u> |
| 2 See also DS 2010/006A | Normative references | | |
| 3 | Terms and definitions | | |
| | | | |
| 4 | Grouping and classification of intrinsically safe apparatus and associated apparatus | Gas group : IIC Temperature class : T4 | Pass |
| 5 | Levels of protection and ignition c | ompliance requirements of electrical apparatus | |
| 5.1 | General | Level of protection is "ia". | Pass |
| 5.2 | Level of protection "ia" | Refer to Appendix A.1 for details. | Pass |
| 5.3 | Level of protection "ib" | Refer to Appendix A.1 for details. | N/A |
| 5.4 | Level of protection "ic" | Refer to Appendix A.1 for details. | N/A |
| 5.5 | Spark ignition compliance | Refer to Appendix A.2 for details. | Pass |
| 5.6 | Thermal ignition compliance | | |
| 5.6.1 | General | Refer to Appendix A.3 for details. | Pass |
| 5.6.2 See also DS 2015/016 DS 2015/009 | Temperature for small components for Group I and Group II | Refer to Appendix A.3.1 for details. | Pass |
| 5.6.3 | Wiring within intrinsically safe apparatus for Group I and Group II | Refer to Appendix A.3.2 for details. | Pass |
| 5.6.4 | Tracks on printed circuit boards for Group I and Group II | Refer to Appendix A.3.3 for details. | Pass |
| 5.6.5 | Intrinsically safe apparatus and component temperature for Group III | The equipment is for Group IIC application. | N/A |

| | IEC 60079-11 | | | |
|---|------------------|--|-----|--|
| Clause Requirement – Test Result – Remark Ver | | | | |
| 5.7 | Simple apparatus | The equipment is not considered as a simple apparatus. | N/A | |

| 6 Apparatus construction | | |
|--------------------------|--|--|
|--------------------------|--|--|

| 6.1 | Enclosures | | |
|---------|------------------------------------|--|------|
| | | An enclosure is necessary for protection against contact with live parts and ingress of solid foreign bodies and liquids. | |
| | | The enclosure consists of 3 parts as the non- metallic front half (cover) and back half of the enclosure (body) and the metallic suspender clip. | |
| 6.1.1 | General | The non-metallic parts of the enclosure are made through double-shot injection moulding with polycarbonate, LUPOY PC 1201-15, manufactured from LG chem and conductive thermoplastic elastomer alloy, RTP 2099 E X 100781, manufactured from RTP. The parts of the enclosure are secured by screws. The metallic suspender clip is made of STS304. The clip is secured to the back half of the enclosure by a screw. The LCD window of the front half of the enclosure is fully covered with an anti-static coating film, JB-SD10008, manufactured from DAEHYUNSTJB. | Pass |
| | | The designation of the surfaces which form the boundary of the enclosure is specified in technical documents of this IECEx Test Report Cover. | |
| 6.1.2 | Enclosures for Group I or Group I | l apparatus | |
| 6.1.2.1 | General | The enclosure provides a degree of at least IP20 as the equipment relying on the separation requirements of Table 5. | Pass |
| | | See Cl.26.4.5 in ExTR of IEC 60079-0. | |
| 6.1.2.2 | Apparatus complying with Table 5 | See Cl.6.1.2.1. | Pass |
| 6.1.2.3 | Apparatus complying with Annex F | See Cl.6.1.2.1. | N/A |
| 6.1.3 | Enclosures for Group III apparatus | The equipment is for Group IIC application. | N/A |

| 6.2 | Facilities for connection of external circuits | | |
|-------|--|---|-----|
| 6.2.1 | Terminals | There are no terminals for external connections in the equipment. | N/A |
| 6.2.2 | Plugs and sockets | There are no plugs and sockets for external connections in the equipment. | N/A |

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|--------|---|--|---------|--|--|
| Clause | Requirement – Test | Result – Remark | Verdict | | |
| 6.2.3 | Determination of maximum external inductance to resistance ratio (<i>Lo/Ro</i>) for resistance limited power source | The equipment is not a resistance limited power source. So, the L ₀ /R ₀ cannot be determined. | N/A | | |
| 6.2.4 | Permanently connected cable | The equipment is not supplied with permanently connected cables. | N/A | | |
| 6.2.5 | Requirements for connections and accessories for IS apparatus when located in the non-hazardous area | The equipment is not provided with connections and accessories that are restricted to use in a non-hazardous area. | N/A | | |

| 6.3 | Separation distances | | |
|-------|--------------------------------|---|------|
| 6.3.1 | General | Annex F is not applied for the equipment. | Pass |
| | | Intrinsic safety depends on separation of conductive parts between circuits of the following blocks, between the infallible components/ assemblies and the surrounding circuits, and across the current limiting devices. Thus, the requirements of this clause were considered against the aforementioned separation. | |
| | Separation of conductive parts | The circuits on the boards were classified into source power block (battery), block-A (Buzzer), block-B(Motor, LED), block-C(CPU, LCD, Electrochemical Sensor, IRDA and etc) and block-D(NDIR Sensor) according to the applied voltage and current levels. The voltage and current levels applied in each block were determined after the application of faults, as provided in Cl.5.2, except the segregation between the following blocks and the effect of the electrochemical cells for the detection of gases. For power source block | |
| 6.3.2 | (continues in the next page) | U _{max} = 3.9 V (from a maximum open circuit voltage of one Lithium/Thionyl chloride (Li/SOCl ₂) cell in the battery), | Pass |
| | | $U_n = 3.6 V (from a nominal voltage of one Lithium/Thionyl chloride (Li/SOCl2) cell in the battery),$ | |
| | | I_{max} = U_{max} / (internal resistance of the batteries in parallel + R2 R5 R10 on the main board) = 3.9 V / (5.68 Ω + 7.26 Ω) = 0.30 A; | |
| | | For block-A | |
| | | U_{max} = 3.9 V × 3 = 11.7 V (from U3 with 3X charge pump in block-A), | |
| | | U _n = 3.6 V (from power source block), | |
| | | I_{max} = U_{max} from power source block / (internal resistance of the batteries in parallel + R2 (R1 + R10 (R5 + R4 R7 R8 on the main board R25 R8 R13 R20 R23 R40 on the sensor board))) = 3.9 V / 27.0 Ω = 0.144 A; | |

| | | IEC 60079-11 | |
|--------|------------------------------------|---|----------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| | | For block-B | |
| | | $U_{max} = 4.1 \text{ V (from D1 and D2 between block-A}$ and block-C), | |
| | | U _n = 3.6 V (from power source block), | |
| | | I_{max} = U_{max} from power source block / (internal resistance of the batteries in parallel + R5) + U_{max} from D1 and D2 / (R4 R7 R8 on the main board R25 R8 R13 R20 R23 R40 on the sensor board) = 3.9 V / 27.46 Ω + 4.1 V / 241.44 Ω = 0.159 A; | |
| | | For block-C | |
| | | U _{max} = 4.1 V (from D1 and D2 between block-A and block-C), | : |
| | | U _n = 3.6 V (from power source block), | |
| | | I_{max} = U_{max} from power source block / (internal resistance of the batteries in parallel + R10 (R5 + R4 R7 R8 on the main board R25 R8 R13 R20 R23 R40 on the sensor board)) + U_{max} from D1 and D2 / R1 on the main board = 3.9 V / (5.68 Ω + 20.12 Ω) + 4.1 V / (1 KΩ × 0.99) = 0.155 A; | |
| | | For block-D | |
| | | U_{max} = 4.1 V (from D1 and D2 between block-A and block-C), | |
| 6 3 0 | Separation of conductive parts | U _n = 3.6 V (from power source block), | D |
| 6.3.2 | (continues from the previous page) | $\begin{split} I_{\text{max}} &= U_{\text{max}} / (\text{R1} \text{R10} (\text{R5} + \text{R4} \text{R7} \text{R8} \text{ on the} \\ \text{main board } \text{R25} \text{R8} \text{R13} \text{R20} \text{R23} \text{R40} \text{ on} \\ \text{the sensor board)} + \text{R43} \text{R44} \text{R45} \text{ on the} \\ \text{sensor board)} &= 4.1 \text{ V} / ((19.91 \ \Omega + 27.57 \ \Omega) \times \\ 0.99) &= 0.087 \text{ A}; \end{split}$ | Pass |
| | | According to classification of the above blocks, the 10 V and 30 V lines in Table 5 were used to assess separation distances of conductive parts on the circuit board. The separation distances of conductive parts on the board, except the block-A including the 3X charge pump circuit for voltage increase, were assessed using 3.9 V or 4.1 V (10 V line). The separation distances of conductive parts in the block-A and between the block-A and the other blocks on the board were assessed using 11.7 V (30 V line). | |
| | | See the block diagram (Ex-GE-25S00) and the related circuit drawings for identification of the aforementioned blocks in detail. | |
| | | Manufacturing tolerances do not reduce the distances specified in the PCB layout drawings by more than 10 % or 1 mm, whichever is smaller. | |
| | | A PCB bracket including a battery container and a insulation sheet between the batteries and the main board are used for assembling and fixing internal parts each other, and considered as non-metallic insulating partitions. | |

| | IEC 60079-11 | | | |
|---------|---|---|---------|--|
| Clause | Requirement – Test | Result Remark | Verdict | |
| 6.3.2 | Separation of conductive parts | The non-metallic insulating partitions above have a thickness of at least 0.9 mm and appropriate CTI in accordance with Table 5 as the PCB bracket covering a part of the block-A using 11.7 V has the CTI of 100 or greater. | Pass | |
| | (continues from the previous page) | The other requirements of this clause regarding the fault mode were applied when considering the application of faults, as provided in Cl.5.2, for the assessment of safety critical parts on which intrinsic safety depends. | Pass | |
| 6.3.2.1 | Distances according to Table 5 | The application of faults was considered using Table 5 according to the requirements of this clause for "ia" protection. | Pass | |
| 6.3.2.2 | Distances according to Annex F | Annex F is not applied for the equipment. | N/A | |
| 6.3.3 | Voltage between conductive parts | See Cl.6.3.2. | Pass | |
| 6.3.4 | Clearance | The minimum clearance of critical separations between conductive parts assessed with 10 V conforms to at least 1.5 mm. The critical separations are applied to components and tracks except ground tracks on both sides of the circuit boards as follows: between two blocks except the block-A; between the current limiting resistors (R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board) and the surrounding parts; across the current limiting resistors. | | |
| | | The minimum clearance of critical separations between conductive parts assessed with 30 V conforms to at least 2.0 mm. The critical separations are applied to components and tracks except ground tracks on both sides of the board as follows: between the block-A and the other blocks; between the assembly of the zener diodes (D1 and D2) and the surrounding parts. | Pass | |
| | | Thus, all the critical separations mentioned as above were considered as infallible separations. | | |
| | | Intrinsic safety does not depend on all the other separation distances within each block except the safety components above, which were considered as non-countable short-circuit faults. | | |
| 6.3.5 | Separation distances through casting compound | Casting compound is not used. | N/A | |

| | | IEC 60079-11 | |
|--------|---|--|---------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 6.3.6 | Separation distances through solid insulation | The minimum distance of critical separations through solid insulation between conductive parts assessed with 10 V or 30 V conforms to at least 0.5 mm. The critical separations are applied to a battery pack containing two batteries connected in parallel and components/tracks except ground tracks on four layers of the circuit boards each, which were identically verified to the spaces specified in Cl.6.3.4. | Pass |
| | | Thus, all the separation distances through solid insulation as above were considered as infallible separations. | |
| | | Intrinsic safety does not depend on all the other separation distances through solid insulation within each block, which were considered as non-countable short-circuit faults. | |
| 6.3.7 | Composite separations | No composite separations are considered for the equipment. | N/A |
| 6.3.8 | Creepage distance | The minimum creepage distance of critical separations between conductive parts assessed with 10 V conforms to at least 1.5 mm. The critical separations are applied to components and tracks except ground tracks on both sides of the circuit boards as follows: between two blocks except the block-A; between the current limiting resistors (R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board) and the surrounding parts; across the current limiting resistors. The minimum creepage distance of critical separations between conductive parts assessed with 30 V conforms to at least 2.0 mm. The critical separations are applied to components | Pass |
| | | and tracks except ground tracks on both sides of the board as follows: between the block-A and the other blocks; between the assembly of the zener diodes (D1 and D2) and the surrounding parts. Thus, all the critical separations mentioned as | |
| | | above were considered as infallible separations. Intrinsic safety does not depend on all the other separation distances within each block except the safety components above, which were considered as non-countable short-circuit faults. | |
| | | The part around J1 on bottom side of the sensor board is coated at least once by brushing. The coating material is PAS-7800 and is specified on the relevant PCB drawing (Ex-GE-25P01-3). | |
| 6.3.9 | Distance under coating | The minimum distance under coating of conductive parts between the block-B and the block-C assessed with 10 V conforms to at least 0.5 mm, which was considered as an infallible separation. | Pass |

| | | IEC 60079-11 | |
|--------|---|--|---------------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| 6.3.10 | Requirements for assembled printed circuit boards | There are no additional requirements. | N/A |
| 6.3.11 | Separation by earthed screens | Earthed screen is not used. | N/A |
| 6.3.12 | Internal wiring | Internal wiring is used for connection between the battery pack containing two batteries connected in parallel and the main board. The separations of conductors are determined by the radial thicknesses of extruded insulation on the wires. It conforms to at least 0.5 mm from the 30 V line in Table 5. All the separations of conductors through extruded insulation on the wires were considered as infallible separations. | Pass |
| 6.3.13 | Dielectric strength requirement | The equipment is a hand-held, battery powered device and does not require dielectric strength tests. | N/A |
| 6.3.14 | Relays | The equipment does not contain any relays. | N/A |
| 6.4 | Protection against polarity reversal | Polarity reversal is not possible since the batteries in parallel are connected to the circuit board at the manufacturer's facility and are not intended to be replaced by the user. Thus, protection against polarity reversal is not required. | N/A |
| | <u> </u> | | - |
| 6.5 | Earth conductors, connections and terminals | Earth conductors, connections and terminals are not required to maintain intrinsic safety. | N/A |
| | · | | |
| 6.6 | Encapsulation | | Tauc |
| 6.6.1 | General | The equipment has no encapsulation. | N/A |
| 6.6.2 | Encapsulation used for the exclusion of explosive atmospheres | See Cl.6.6.1. | N/A |
| | | | |
| 7 | Components on which intrinsic s | afety depends | |

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|--------------------------------|--|---|---------|
| Clause | Requirement – Test | Result – Remark | Verdict |
| | | Safety components on which intrinsic safety depends are as follows: | |
| | | 1) Zener diodes D1 and D2 to prevent 11.7 V level of the block-A, made by the 3X charge pump circuit for voltage increase, from being introduced elsewhere on the circuit boards except the block-A and ensure that 4.1 V level from the block-A is applied to all the other blocks; | |
| 7.1 See also DS 2004/003 | Rating of components | 2) Resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board, to limit currents and powers supplied to circuits in the blocks and segregate each block from being adversely affected by capacitors and inductors in the other blocks; | Pass |
| | | The zener diodes and the resistors do not operate at more than 2/3 of their maximum ratings. | |
| | | Refer to Appendix A.4 for details. | |
| | | The equipment contains five internal connections | |
| 7.2 | Connectors for internal connections, plug-in cards and | on the circuit boards for the sensor assemblies (two electrochemical sensors and one NDIR sensor), the LCD and the vibration motor, four pairs of internal plugs and sockets to connect between the main board and the sensor board, and one internal connector to connect from the battery pack to the main board. | Pass |
| | components | By structural features of internal connections above, all the connections within the equipment are conducted only in a designated way so that incorrect connection or interchangeability with other connector is not possible. | , 400 |
| | | The failure to open circuits of the connections does not affect intrinsic safety adversely. | |

| 7.3 Fuses The equipment does not contain any fuses. N/A | |
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| 7.4 | Primary and secondary cells and batteries | |
|-----|---|--|
| | | |

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|-------------------|---|---|---------|
| Clause | Requirement – Test | Result - Remark | Verdict |
| | | The equipment is powered by two Lithium/ Thionyl Chloride (Li/SOCl ₂) batteries in parallel (Tekcell, type SB-AA11 manufactured by VITZRO CELL, IEC 60086-1 type E). | |
| | | The batteries in parallel are connected to the circuit board at the manufacturer's facility and are not intended to be replaced by the user. | |
| 7.4.1 | General | According to the requirements of DS 2019/002, the battery was confirmed to comply with the requirements of UL 1642 by 3rd-party certification of the lithium battery from an IECEE NCB, UL. Thus, the battery is considered as being safe against explosion risk of some lithium type batteries. The battery is also used within its condition of acceptability and the manufacturer's instruction. | Pass |
| | | Therefore, the equipment need not be marked with a warning marking as specified in item a) of Table 11. | |
| 7.4.2 See also | Battery construction | The battery was tested for spark ignition and temperature rise under short circuit condition as per Cl.10.5.3. See Cl.10.5.3. | Pass |
| DS2010/003 | | The battery does not require addition of electrolyte, and has a sealed metallic enclosure. | |
| 7.4.3 | Electrolyte leakage and ventilation | Ten samples of the Tekcell, type SB-AA11 battery were tested in accordance with Cl.10.5.2, with acceptable results. There was no spillage of electrolyte. | Pass |
| | | See Cl.10.5.2. | |
| | | The cell type used in the equipment is Lithium/Thionyl Chloride(Li/SOCl2). | |
| 7.4.4 | Cell voltages | According to the table 13 of IEC 60079-0, a maximum open-circuit (peak) voltage is 3.9 V and a nominal voltage is 3.6 V (for IEC 60086-1 type E cell). | Pass |
| 7.4.5 | Internal resistance of cell or battery | The internal resistance of the battery pack containing two batteries connected in parallel was determined in accordance with Cl.10.5.3 as 5.68 Ω . | Pass |
| | | See Cl.10.5.3. | |
| 7.4.6 | Batteries in equipment protected by other types of protection | The equipment is not protected by flameproof (or other technique). | N/A |
| 7.4.7 | Batteries used and replaced in explosive atmospheres | The batteries in parallel are connected to the circuit board at the manufacturer's facility and are not intended to be replaced by the user. | N/A |

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|--------|--|---|---|---|--|
| Clause | Requirement – Test | Result – Remark | Verdict | | |
| | | | The batteries in parallel are connected to the circuit board at the manufacturer's facility and are not replaced in a hazardous area. | , | |
| | | The battery does not require current limiting devices to ensure the safety of the battery itself because internal resistance of the battery is big enough. | | | |
| 7.4.8 | Batteries used but not replaced in explosive atmospheres | The batteries are housed in the enclosure secured with screws, and the batteries are installed without reducing the intrinsic safety of the equipment by the mechanical shape of the enclosure and the battery compartment, and the structural features of the battery pack. The drop test in accordance with CI.26.4.3 of IEC 60079-0 did not result in the ejection or separation of the battery pack from the equipment in such a way as to invalidate intrinsic safety. | Pass | | |
| | | Therefore, the equipment need not be marked with a warning marking as specified in item b) or d) of Table 11. | | | |
| 7.4.9 | External contacts for charging batteries | The equipment contains primary batteries and does not contain any external contacts for charging batteries. | N/A | | |

| 7.5 See also DS 2015/007 | Semiconductors | | |
|--------------------------------|-------------------------|---|------|
| 7.5.1 | Transient effects | The equipment is battery powered and intrinsically safe. Transients effects generated within the intrinsically safe equipment were ignored. | N/A |
| 7.5.2 | Shunt voltage limiters | For "ia" protection, the zener diodes, D1 and D2, are rated to withstand at least 1.5 times the maximum dissipation power in the zener mode and at least 1.5 times the maximum possible short-circuit current in the forward direction. | Pass |
| 7.5.3 | Series current limiters | Refer to Appendix A.4.2 for details. The equipment does not contain any series current limiters using semiconductors. | N/A |

| 7.6 See also DS 2016/002 DS2012/009 | Failure of components, connections and separations | Failure of components, connections and separation distances were assessed in this report as being not capable of causing an ignition in a hazardous area. | Pass |
|--|--|---|------|
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| Clause | Requirement – Test | Result - Remark | Verdict |
| 7.7 | Piezo-electric devices | The equipment contains a piezo-electric buzzer and was tested in accordance with Cl.10.7. The piezo-electric buzzer is part no. CBE1440BP-L, manufactured by Daeyoung Electric. The maximum energy stored by the capacitance of the buzzer at the maximum measured voltage does not exceed 50 µJ for group IIC apparatus. | Pass |
| | | See Cl.10.7 for details. | |
| | | | |
| | | The equipment contains two electrochemical sensors for the detection of oxygen and toxic gases. Sensor types are shown on part list (Ex-GE-25B01). | |
| 7.8 | Electrochemical cells for the detection of gases | According to manufacturer's specifications, All the electrochemical sensors do not generate more than 1.3 V and 1.5 A at worst fault condition by two sensors connected in parallel. They were considered for their addition to voltages and currents which may affect spark ignition assessment and testing as per Cl.10.1. | Pass |
| | | See Cl.10.1. | |
| 8 | intrinsic safety depends | ssemblies of components and infallible connections | |
| 8.1 | Level of Protection "ic" | Level of protection for the equipment is "ia". | N/A |
| 8.2 | Mains transformers | | |
| 8.2.1 | General | The equipment does not contain any transformers. | N/A |
| 8.2.2 | Protective measures | See Cl.8.2.1. | N/A |
| 8.2.3 | Transformer construction | See Cl.8.2.1. | N/A |
| 8.2.4 | Transformer type tests | See Cl.8.2.1. | N/A |
| 8.2.5 | Routine test of mains transformers | See Cl.8.2.1. | N/A |
| | | | 1 |
| 8.3 | Transformers other than mains transformers | The equipment does not contain any transformers. | N/A |
| 8.4 | Infallible windings | | |
| | | The equipment does not contain any Infallible | NI/A |
| 8.4.1 | Damping windings | damping windings. | N/A |
| 8.4.2 | Inductors made by insulated conductors | The equipment does not contain any Infallible Inductors made by insulated conductors. | N/A |

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| Clause | Requirement – Test | Result – Remark | Verdict | | |
| 8.5 | Current-limiting resistors | Resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board are used as the current-limiting resistors. All the aforementioned resistors are film type. The resistors are rated to withstand at least 1.5 times the maximum voltage and to dissipate at least 1.5 times the maximum power after the application of faults, as provided in Cl.5.2. The resistors are not invalidated after the application of faults as well. Refer to Appendix A.4.1 for details. | Pass | | |

| 8.6 See also DS 2003/003 | Capacitors | | |
|--------------------------------|---------------------|---|-----|
| 8.6.1 | Blocking capacitors | The equipment does not contain any blocking capacitors. | N/A |
| 8.6.2 | Filter capacitors | The equipment does not contain any filter capacitors. | N/A |

| 8.7 | Shunt safety assemblies | | , |
|-------|-------------------------|--|------|
| 8.7.1 | General | The zener diodes, D1 and D2, on the circuit board are used as shunt components in an infallible shunt safety assembly. The zener diodes are duplicated in the assembly and rated properly for "ia" protection as per Cl.7.5.2. The zener diodes are not invalidated after the application of faults, as provided in Cl.5.2, as well. | Pass |
| | | Refer to Appendix A.4.2 for details. | |
| 8.7.2 | Safety shunts | The shunt safety assembly is considered as a safety shunt that can be used to limit voltage to capacitors in the block-B/C/D. | Pass |
| 8.7.3 | Shunt voltage limiters | The shunt safety assembly is considered as a shunt voltage limiter to ensure that defined voltage level, 4.1 V, is applied to intrinsically safe circuits. | Pass |
| | _ | The analysis of transients for the assembly is not required because the assembly is fed from batteries in accordance with Cl.7.4. | |

| | | The followings were considered as infallible against open circuit failure: | |
|-----|---|---|------|
| 8.8 | Wiring, printed circuit board tracks, and connections | The zener diodes, D1 and D2, on the circuit board are infallibly connected to ground with at least 2 mm wide, 35 µm thick track. The connections to the board of the zener diodes above are infallibly soldered as a soldered joint of the surface mount component mounted in accordance with the component manufacturer's recommendation. | Pass |

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| Clause | Requirement – Test | Result Remark | Verdict |
| 0.0 | Calvariaelt, comparating company | | |
| 8.9 | Galvanically separating compone | 1 | T |
| 8.9.1 | General | The equipment does not contain any galvanically separating components. | N/A |
| 8.9.2 | Isolating components between intrinsically safe and non-intrinsically safe circuits | See Cl.8.9.1. | N/A |
| 8.9.3 | Isolating components between separate intrinsically safe circuits | See Cl.8.9.1. | N/A |
| | · | | |
| 9 | Supplementary requirements for s | specific apparatus | |
| | | | |
| 9.1 | Diode safety barriers | | |
| 9.1.1 | General | The equipment is not a standalone diode safety barrier. | N/A |
| 9.1.2 | Construction | | |
| 9.1.2.1 | Mounting | See Cl.9.1.1. | N/A |
| 9.1.2.2 | Facilities for connection to earth | See Cl.9.1.1. | N/A |
| 9.1.2.3 | Protection of components | See Cl.9.1.1. | N/A |
| | · · · · · · · · · · · · · · · · · · · | | |
| 9.2 | FISCO apparatus | The equipment is not a FISCO apparatus. | N/A |
| | | | |
| 9.3 | Handlights and caplights | The equipment is not a Handlight nor a caplight. | N/A |
| | , | | |
| 10 | Type verifications and type tests | | <u>.</u> |
| | , special spec | | |
| 10.1 See also DS 2013/002 | Spark ignition test | | |
| 10.1.1 | General | Spark ignition tests were not considered necessary because the circuits in the equipment were exempted from type tests by the methods described in Annex A. | Pass |
| <u>.</u> | | Refer to Appendix A.2 for details. | <u> </u> |
| 10.1.2 | Spark test apparatus | Tests were not conducted. | N/A |
| 10.1.3 | Test gas mixtures and spark test | apparatus calibration current | |
| 10.1.3.1 | Explosive test mixtures suitable for tests with a safety factor of 1.0 and calibration current of the spark test apparatus | Tests were not conducted. | N/A |
| 10.1.3.2 | Explosive test mixtures suitable for tests with a safety factor of 1.5 and calibration current of the spark test apparatus | Tests were not conducted. | N/A |

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| Clause | Requirement – Test | Result – Remark | Verdict |
| 10.1.4 | Tests with the spark test apparatu | ıs | - |
| 10.1.4.1 | Circuit test | Tests were not conducted. | N/A |
| 10.1.4.2 | Safety factors | When using the methods described in Annex A for assessment, a safety factors of 1.5 was considered. | Pass |
| 10.1.5 | Testing considerations | | |
| 10.1.5.1 | General | Tests were not conducted. | N/A |
| 10.1.5.2 | Circuits with both inductance and capacitance | The sum of all the capacitances or all the inductances in each block on the circuit boards is less than 1 % of the allowable limit. The circuits were considered acceptable without further testing. | Pass |
| | | Refer to Appendix A.2.4 for details. | |
| 10.1.5.3 | Circuits using shunt short-circuit | Circuits do not use crowbar protection. | N/A |
| 10.1.3.3 | (crowbar) protection | Refer to Appendix A.2.5 for details. | IN/A |
| 10.1.5.4 | Results of spark test | Tests were not conducted. | N/A |

| 10.2 | Temperature tests (continues in the next page) | In case of small components having total surface area not less than 20 mm², maximum dissipation power in each component is less than 1.25 W required at T4 and 50 °C ambient as per Table 4 of IEC 60079-0 because maximum power supplied from the batteries to the boards after passing through the zener diodes, D1~D2, the internal resistance of the batteries and the current limiting resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board, is 0.130 W and maximum dissipation power of each current limiting resistor is 0.374 W. In case of small components having total surface area less than 20 mm², maximum surface temperature of the components does not exceed 275 °C required at T4 and 50 °C ambient as per Table 3 of IEC 60079-0. In other words, their thermal coefficients, Rthj-a (Junction to Ambient) or Rthc-a (Case to Ambient), shall be less than (275 °C - 50 °C) / 0.130 W = 1 730 °C/W. Temperature tests were conducted on some small components to determine their thermal coefficients which are not obtained from the manufacturers. The results were determined as follows. 1) R31(100 Ω , 1/10 W) on the sensor board at 0.130 W : 41.3 °C at 24.7 °C ambient \rightarrow Rthc-a = (41.3 °C - 24.7 °C) / 0.130 W = 127 °C/W. 2) R43(51 Ω , 1/4 W) on the sensor board at 0.130 W : 38.7 °C at 24.7 °C ambient \rightarrow Rthc-a = (38.7 °C - 24.7 °C) / 0.132 W = 106 °C/W. | Pass |
|------|--|--|------|
|------|--|--|------|

| Clause | Requirement - Test | Result – Remark | Verdict |
|--|--|--|---------|
| Temperature tests 10.2 (continues from the previous | | The components smaller than 20 mm² were verified from the manufacturers' datasheets and the testing results above as having their thermal coefficients less than 1 730 °C/W. | Pass |
| | Temperature tests (continues from the previous | Therefore, considering the above, the equipment satisfies the assigned temperature class T4 at 50 °C ambient. | |
| | page) | The maximum surface temperature rise of the enclosure of the equipment determined at worst fault conditions is negligible (less than 10 K). The service temperature is regarded as 60 °C at 50 °C ambient. | |
| | | Refer to Appendix A.3.1 and B.1 for details. | |

| 10.3 Dielectric strength tests | The equipment is a hand-held, battery powered device and does not require dielectric strength tests. | N/A | |
|--------------------------------|--|-----|--|
|--------------------------------|--|-----|--|

| 10.4 | Determination of parameters of loosely specified components | Ten samples of the vibration motor, M1 (Z6SH1B0060711), manufactured by JINLONG MACHINERY & ELECTRONIC CO., LTD., were measured at room temperature, 20 °C, to determine the maximum inductance. | Pass |
|------|---|--|------|
| | | The motor has the maximum measured inductance of 127 µH. | |

| 10.5 | Tests for cells and batteries | | |
|--------|---|--|------|
| 10.5.1 | General | The battery pack containing two batteries connected in parallel is not rechargeable and was tested as such. | Pass |
| 10.5.2 | Electrolyte leakage test for cells and batteries | Ten test samples of the battery pack were subjected to short circuit until discharged. For 12 hours after the test, there was no visible sign of electrolyte from the test samples. | Pass |
| | | The equipment contains batteries that are not changed in a hazardous area. The battery delivers a peak open-circuit voltage of 3.9 V, less than 4.5 V. Thus, the consideration of the spark ignition discharge at the terminals is not necessary. | |
| 10.5.3 | Spark ignition and surface temperature of cells and batteries | The internal resistance of the battery pack was determined from a test of ten samples as required by this clause. Its minimum value is $5.68~\Omega$. | Pass |
| | | Ten samples of the battery pack were also tested for temperature rise under short circuit condition as required by this clause. The maximum surface temperature of the battery pack determined from the tests was 126.6 °C at 50 °C ambient, which does not exceed 135 °C (T4), considering safety margin. | |

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| Clause | Requirement – Test | Result – Remark | Verdict |
| 10.5.4 | Battery container pressure tests | This test is not required. See Cl.7.4.2 for details. | N/A |
| 10.6 | Mechanical tests | · | |
| 10.6.1 | Casting compound | There is no unprotected or exposed surface of the casting compound which forms part of the enclosure. Thus, this test was not conducted. | N/A |
| 10.6.2 | Determination of the acceptability of fuses requiring encapsulation | The equipment does not contain any fuses. | N/A |
| 10.6.3 | Partitions | The equipment does not use non-metallic insulating partitions of lesser thickness than 0.9 mm on which intrinsic safety depends. | N/A |
| | | | |
| 10.7 | Tests for intrinsically safe apparatus containing piezoelectric devices | The maximum capacitance of the piezo-electric buzzer is 19.5 nF at 120 Hz from the manufacturer's specification. The voltage appearing across the buzzer was tested as required by this clause and the maximum measured value was 17.5 V. The maximum energy stored by the capacitance of the buzzer at the maximum measured voltage | Pass |
| | | was calculated using the following formula; E = $1/2 \times CV^2 = 2.99 \mu J$, which does not exceed 50 μJ for group IIC apparatus. | |
| 10.8 | Type tests for diode safety barriers and safety shunts | The equipment is not a standalone diode safety barrier. | N/A |
| | | | • |
| 10.9 | Cable pull test | The equipment is not supplied with permanently connected cables. | N/A |
| | | | |
| 10.10 | Transformer tests | The equipment does not contain any transformers. | N/A |
| 10.11 | | | |
| 10.11 | Optical isolators tests | The aminom and decreased and the second and the sec | 1 |
| 10.11.1 | General | The equipment does not contain any optical isolators. | N/A |
| 10.11.2 | Thermal conditioning, dielectric and carbonisation test | See Cl.10.11.1. | N/A |
| 10.11.2.1 | Overload test at the receiver side | See Cl.10.11.1. | N/A |
| 10.11.2.2 | Overload test at the transmitter side | See Cl.10.11.1. | N/A |
| | Thornal conditioning and | | l |
| 10.11.2.3 | Thermal conditioning and dielectric strength test | See Cl.10.11.1. | N/A |
| 10.11.2.3 10.11.2.4 | | See Cl.10.11.1. | N/A |

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| Clause | Requirement – Test | Result – Remark | Verdict |
| 10.11.2.4.2 | Transmitter side | See Cl.10.11.1. | N/A |
| 10.11.3 | Dielectric and short-circuit test | See Cl.10.11.1. | N/A |
| 10.11.3.1 | General | See Cl.10.11.1. | N/A |
| 10.11.3.2 | Pre-test dielectric | See Cl.10.11.1. | N/A |
| 10.11.3.3 | Short-circuit current test | See Cl.10.11.1. | N/A |
| 10.11.3.4 | Current limited short-circuit current test | See Cl.10.11.1. | N/A |
| 10.11.3.5 | Dielectric strength test | See Cl.10.11.1. | N/A |
| | | | |
| 10.12 | Current carrying capacity of infallible printed circuit board connections | This clause is not applicable. See Cl.8.8. | N/A |
| | | | |
| 11 | Routine verifications and tests | | |
| | | | |
| 11.1 | Routine tests for diode safety ba | rriers | |
| 11.1.1 | Completed barriers | See Cl.9.1.1. | N/A |
| 11.1.2 | Diodes for 2-diode "ia" barriers | See Cl.9.1.1. | N/A |
| | | | |
| 11.2 | Routine tests for infallible transformers | See Cl.8.2.5. | N/A |
| | | | |
| 12 | Marking | | |
| | | | |
| | | See the label drawing (Ex-A19060032). | |
| 12.1 | General | The equipment is marked with the necessary requirements in Cl.29 of IEC 60079-0 on adhesive label. | Pass |
| 12.2 | Marking of connection facilities | Additional identification marking of connection facilities is not necessary because connection facilities are not used for the external connections of the equipment. | N/A |
| 12.3 | Warning markings | No warnings are required to be present on the equipment. See Cl.7.4. | N/A |
| 12.4 | Examples of marking | See Cl.12.1. | Pass |
| | | | |
| 13 | Documentation | Documentation includes the relevant safety information. | Pass |
| Annex A (Normative) | Assessment of intrinsically safe of | | |

| IEC 60079-11 | | | |
|--------------|--|--|---------|
| Clause | Requirement - Test | Result – Remark | Verdict |
| A.1 | Basic criteria | Intrinsically safe circuits in the equipment satisfy three basic criteria which are no spark ignition, the temperature classification and the adequate separation from other circuits. | Pass |
| A.2 | Assessment using reference curves and tables | The structure and electrical parameters of the circuits in the equipment were sufficiently well defined for its safety to be deduced from the methods described in Annex A. Thus, the safety of the circuits was assessed using the reference tables, Tables A.1~A.2, and the reference curve, Figure A.6. | Pass |
| A.3 | Examples of simple circuits | See Cl.A.2. | Pass |
| A.4 | Permitted reduction of effective capacitance when protected by a series resistance | No reduction of effective capacitance is used. | N/A |

| Annex B (Normative) | Spark test apparatus for intrinsica | ally safe circuits | | | | | |
|------------------------|---|---|-------------------|--|--|--|--|
| B.1 | Test methods for spark ignition | | | | | | |
| B.1.1 | Principle | Tests were not conducted. | N/A | | | | |
| B.1.2 | Apparatus | Tests were not conducted. | N/A | | | | |
| B.1.3 | Calibration of spark test apparatus Tests were not conducted. | | | | | | |
| B.1.4 | Preparation and cleaning of tungsten wires Tests were not conducted. | | | | | | |
| B.1.5 | Conditioning a new cadmium disc | N/A | | | | | |
| B.1.6 | Limitations of the apparatus | Tests were not conducted. | N/A | | | | |
| B.1.7 | Modifications of test apparatus for use at higher currents | Tests were not conducted. | | | | | |
| Annex C | Measurement of creepage distan | ces, clearances and separation distance | s through casting | | | | |
| (Informative) | compound and through solid insu | | | | | | |
| | 1 | | | | | | |
| Annex D (Normative) | Encapsulation | | | | | | |
| D.1 | Adherence | See Cl.6.6. | N/A | | | | |
| D.2 | Temperature | See Cl.6.6. | N/A | | | | |

| Annex E (Informative) | Transient energy test |
|--------------------------|---|
| | |
| Annex F | Alternative separation distances for assembled printed circuit boards and separation of |

| Annex F (Normative) | Alternative separation distances for assembled printed circuit boards and separation of components | | | | | | | |
|------------------------|--|---|-----|--|--|--|--|--|
| F.1 | General | The equipment is not assessed with Annex F. | N/A | | | | | |
| F.2 | Control of pollution access | The equipment is not assessed with Annex F. | N/A | | | | | |

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|--------------|------------------------------------|---|---------|--|--|--|--|--|
| Clause | Requirement – Test | Result – Remark | Verdict | | | | | |
| F.3 | Distances for printed circuit boar | Distances for printed circuit boards and separation of components | | | | | | |
| F.3.1 | Level of protection "ia" and "ib" | The equipment is not assessed with Annex F. | N/A | | | | | |
| F.3.2 | Level of protection "ic" | The equipment is not assessed with Annex F. | N/A | | | | | |

| Annex G (Normative) | Fieldbus intrinsically safe concer | ot (FISCO) – Apparatus requirements | | | | | |
|------------------------|---|-------------------------------------|-----|--|--|--|--|
| G.1 | Overview | The equipment is not FISCO. | N/A | | | | |
| G.2 | Apparatus requirements | | | | | | |
| G.2.1 | ieneral The equipment is not FISCO. | | | | | | |
| G.2.2 | FISCO power supplies | | | | | | |
| G.2.2.1 | General | The equipment is not FISCO. | N/A | | | | |
| G.2.2.2 | Additional requirements of 'ia' and 'ib' FISCO power supplies | The equipment is not FISCO. | N/A | | | | |
| G.2.2.3 | Additional requirements of 'ic' FISCO power supplies | The equipment is not FISCO. | N/A | | | | |
| G.3 | FISCO field devices | | | | | | |
| G.3.1 | General | The equipment is not FISCO. | N/A | | | | |
| G.3.2 | Additional requirements of 'ia' and 'ib' FISCO field devices | The equipment is not FISCO. | N/A | | | | |
| G.3.3 | Additional requirement of 'ic' | The equipment is not FISCO. | N/A | | | | |
| G.3.4 | Terminator | The equipment is not FISCO. | N/A | | | | |
| G.3.5 | Simple apparatus | The equipment is not FISCO. | N/A | | | | |
| G.4 | Marking | The equipment is not FISCO. | N/A | | | | |
| G.4.1 | Examples of marking | The equipment is not FISCO. | N/A | | | | |

| Annex H (Informative) | Ignition testing of semiconductor limiting power supply circuits | |
|--------------------------|--|--|
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Measurement Section, including Additional Narrative Remarks

APPENDIX A: Description of product

A.1 General overview

A.1.1 Scope

This report provides the basis for the certification of the G-Finder Multi GFM-400 series Portable Multi Gas Detectors as intrinsically safe electrical apparatus as defined in the standards IEC 60079-0:2017 and IEC 60079-11:2011 to Level of protection "ia", Group IIC and Temperature Class T4 in an ambient temperature -20 °C ~ +50 °C. The equipment provides a degree of protection of at least IP20. The tests and assessments in this report are limited to the aforementioned standards.

A.1.2 Equipment

The G-Finder Multi GFM-400 series are hand-held, battery operated multi gas detectors. The "G-Finder Multi" is a brand name and the main model name is "GFM-400". The detector is a personal safety device designed to continuously monitor the presence of oxygen(O_2), Carbon Monoxide (CO), Hydrogen Sulfide (CO) and one of methane (CO) or propane (CO). The detector samples the atmosphere in diffusion mode using an electrochemical sensors for CO, a dual toxic electrochemical sensor for CO and CO0 and CO18.

The detector alerts the user to potentially unsafe exposure with visual, vibrating and audible alarms when gas concentration exceeds user configurable set points, and readings are displayed on a LCD. The detector has IR communications for changing the alarm set point, the calibration range and etc. The IR communications shall only be used in safe area.

The detector is comprised of two printed circuit boards with a LCD, three gas sensors and two batteries in parallel, housed in a non-metallic enclosure which is constructed by double-shot injection molding with polycarbonate and thermoplastic elastomer alloy. The non-metallic enclosure consists of a front half (cover) and a back half (body). A wide LCD window of the front half of the enclosure is fully covered with an anti-static coating film. A metallic suspender clip is attached to the back half of the enclosure. The parts of the enclosure are secured by screws. The detector has no facilities for connection of external circuits.

Power is provided by non-user replaceable, two Lithium/Thionyl chloride (Li/SOCl₂) batteries (Tekcell, type SB-AA11 manufactured by VITZRO CELL, AA size, Nominal 3.6 V, Peak 3.9 V, 2.5 Ah) connected in parallel. The detector is intended to be a disposable unit.

The configuration for GFM-400 series is as follows; GFM-400(-X)(-Y)

- GFM-400: Model name
- *X: Flammable gas type (blank(default sensor), MM2.5, MM100, MP1.5, MP2.5, PP1.5, PP2.5)
- *: This option can be selected only if the user require a particular target gas, a particular calibration gas and a particular measurement range different from the default sensor to detect a flammable gas (CH₄ or C₃H₈).
- **Y: Housing body color (blank : orange(default), YE : yellow, GN : green, VT : violet, and etc.)
- **: This option is not marked on the label and can only be used at an order if the user require a particular housing body color different from the default. The option does not affect intrinsic safety. For the detailed information, see the instruction manual.

A.2 Spark ignition considerations

Spark ignition tests were not necessary for the equipment because the structure and electrical parameters of the circuits in the equipment were sufficiently well defined for its safety to be deduced from the methods described in Annex A. The safety of the circuits was assessed using the reference tables, Tables A.1~A.2, and the reference curve, Figure A.6.

The circuits on the boards were classified into source power block (battery), block-A (Buzzer), block-B(Motor, LED), block-C(CPU, LCD, Electrochemical Sensor, IRDA and etc) and block-D(NDIR Sensor) according to the applied voltage and current levels. The blocks were segregated each other through the

zener diodes, D1~D2, and the resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board. See the block diagram (Ex-GE-25S00) and the related circuit drawings for identification of the aforementioned blocks and safety components in detail. Intrinsic safety depends on separation of conductive parts between circuits of the blocks, between the infallible components/assemblies and the surrounding circuits, and across the current limiting devices mentioned as above. The separations did not invalidate the classification of the blocks and the safety components when considering the application of faults, as provided in Cl.5.2.

Thus, the voltage and current levels applied in each block were determined, except the effect of the electrochemical cells for the detection of gases, as follows.

For power source block

- $U_{max} = 3.9 \text{ V}$ (from a maximum open circuit voltage of one Lithium/Thionyl chloride (Li/SOCl₂) cell in the battery).
- U_n = 3.6 V (from a nominal voltage of one Lithium/Thionyl chloride (Li/SOCl₂) cell in the battery).
- $I_{max} = U_{max} / (internal resistance of the batteries in parallel + R2||R5||R10 on the main board) = 3.9 V / (5.68 <math>\Omega$ + 7.26 Ω) = 0.30 A;

For block-A

- U_{max} = 3.9 V × 3 = 11.7 V (from U3 with 3X charge pump in block-A),
- $U_n = 3.6 \text{ V (from power source block)}$,
- I_{max} = U_{max} from power source block / (internal resistance of the batteries in parallel + R2||(R1 + R10||(R5 + R4||R7||R8 on the main board ||R25 ||R8||R13||R20||R23||R40 on the sensor board))) = 3.9 V / 27.0 Ω = 0.144 A;

For block-B

- U_{max} = 4.1 V (from D1 and D2 between block-A and block-C),
- U_n = 3.6 V (from power source block),
- l_{max} = U_{max} from power source block / (internal resistance of the batteries in parallel + R5) + U_{max} from D1 and D2 / (R4||R7||R8 on the main board ||R25||R8||R13||R20||R23||R40 on the sensor board) = 3.9 V / 27.46 Ω + 4.1 V / 241.44 Ω = 0.159 A;

For block-C

- U_{max} = 4.1 V (from D1 and D2 between block-A and block-C),
- U_n = 3.6 V (from power source block),
- I_{max} = U_{max} from power source block / (internal resistance of the batteries in parallel + R10||(R5 + R4||R7||R8 on the main board ||R25||R8||R13 ||R20||R23||R40 on the sensor board)) + U_{max} from D1 and D2 / R1 on the main board = 3.9 V / (5.68 Ω + 20.12 Ω) + 4.1 V / (1 K Ω × 0.99) = 0.155 A;

For block-D

- U_{max} = 4.1 V (from D1 and D2 between block-A and block-C),
- $U_n = 3.6 \text{ V (from power source block)}$,
- $I_{max} = U_{max} \dot{i}$ (R1||R10||(R5 + R4||R7||R8 on the main board ||R25||R8||R13||R20||R23||R40 on the sensor board) + R43||R44||R45 on the sensor board) = 4.1 V / ((19.91 Ω + 27.57 Ω) × 0.99) = 0.087 A;

The current limiting resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board, segregate each block from being adversely affected by capacitors and inductors in the other blocks. Thus, according to the classification of the above blocks, effective capacitance and inductance of each block per the applied voltage and current levels were considered separately as follows.

For power source block

- Total effective maximum capacitance connected to the maximum voltage (3.9 V) = negligible,
- Total effective maximum inductance = negligible;

For block-A

- Total effective maximum capacitance connected to the maximum input voltage (3.9 V) = C11 + C12 + C15 + C16 + BZ1 on the main board = (1 μ F × 1.1) + (0.1 μ F × 1.1 x 3) + (15 μ F,
- Total effective maximum capacitance connected to the maximum charge pumped voltage (11.7 V) = C11 + C12 + C16 + BZ1 on the main board = $(0.1 \, \mu F \times 1.1 \times 3) + (15 \, nF \times 1.3) = 0.35 \, \mu F$,
- Total effective maximum inductance = negligible;

For block-B

- Total effective maximum capacitance connected to the maximum voltage (4.1 V) = C17 on the main board = 0.11 uF.
- Total effective maximum inductance = maximum inductance of the vibration motor, M1 on the main board = $127 \mu H$;

For block-C

- Total effective maximum capacitance connected to the maximum voltage (4.1 V) = (C1 + C2 + ... + C26 on the main board) + (C1 + C2 + ... + C55 on the Bluetooth module, U4) + (C1 + C3 + ... + C25 + CF1 + ... + CF12 on the sensor board) = $29.15 \,\mu\text{F}$,
- Total effective maximum inductance = L1 + L8 + L9 + L11 + L46 on the Bluetooth module, U4 = 54.8 nH;

For block-D

- Total effective maximum capacitance connected to the maximum voltage (4.1 V) = (C13 + C20 + C23 + C224 on the sensor board) + C_i of NDIR Sensor = (10 μ F × 1.2 × 2) + (68 μ F × 1.05 x 2) + 26 μ F = 50 μ F, - Total effective maximum inductance = L1 on the sensor board + L_i of NDIR Sensor = (2.2 μ H × 1.1) + 0 = 2.42 μ H;

In addition, influences by voltages and currents generated from two electrochemical sensors on the circuits were considered for the separation assessment of conductive parts and the spark ignition assessment. When the maximum voltage, 1.3 V, generated from the sensors is added to the voltages in the blocks above, it does not adversely affect the previous separation assessment in Cl.6.3 because the assessment using the 10 V and 30 V lines in Table 5 is still maintained. And the maximum voltage and the maximum current generated at worst fault condition by two sensors connected in parallel, 1.3 V and 1.5 A, were also taken into account during the spark ignition assessment of the block-C/D below.

A.2.1 Resistive spark ignition

In case of the block-C/D, the maximum voltage and the maximum current in the circuits were determined by addition of the voltage, 1.3 V, and the current, 1.5 A, generated from the electrochemical sensors to the voltage and the current applied in the block-C/D.

In case of the other blocks, the maximum voltage and the maximum current in each circuit were determined as the voltage and the current applied in each block.

- 1) 0.30 A at 3.9 V < 3.33 A at 12.1 V for Group IIC and a safety factor of 1.5.
- 2) 0.144 A at 11.7 V < 3.33 A at 12.1 V for Group IIC and a safety factor of 1.5.
- 3) 0.159 A at 4.1 V < 3.33 A at 12.1 V for Group IIC and a safety factor of 1.5.
- 4) 1.655 A at 5.4 V < 3.33 A at 12.1 V for Group IIC and a safety factor of 1.5.

The circuits in the equipment were assessed as intrinsically safe in regard to resistive spark ignition.

A.2.2 Inductive spark ignition

The maximum current and the inductance value shall be compared to the values given in Figure A.6. However, the points of the values to be compared are located beyond Figure A.6. So, the possibility of inductive spark ignition was assessed on the calculation of spark ignition energy considering a safety factor of 1.5.

The following is the assessment result based on the calculation of spark ignition energy.

- block-B: Vibration motor, M1

Maximum flowing current to the motor = U_{max} from power source block / (internal resistance of the batteries in parallel + R5 + resistance of the motor) + U_{max} from D1 and D2 / (R4||R7||R8 on the main board ||R25||R8||R13||R20||R23||R40 on the sensor board + resistance of the motor) = 3.9 V / 54.46 Ω + 4.1 V / 268.44 Ω = 0.087 A

 $E = \frac{1}{2} \times L_{max} \times (I_{max} \times safety factor)^2 = 0.5 \times 127 \,\mu\text{H} \times (0.087 \,\text{A} \times 1.5)^2 = 1.08 \,\mu\text{J} < 40 \,\mu\text{J} \text{ for Group IIC.}$

- block-C: Bluetooth module, U4

Maximum flowing current to the Bluetooth module = maximum current of block-C + maximum current of two electrochemical sensors = 0.155 A + 1.5 A = 1.655 A

E = $1/2 \times L_{max} \times (I_{max} \times safety factor)^2 = 0.5 \times 54.8 \text{ nH} \times (1.655 \text{ A} \times 1.5)^2 = 0.17 \mu J < 40 \mu J for Group IIC.$

- block-D: L1 on the sensor board

Maximum flowing current to block-D = U_{max} from block-C by addition of the maximum voltage, 1.3 V, generated from the electrochemical sensors / (R43||R44||R45 on the sensor board) = 5.4 V / (27.57 Ω × 0.99) = 0.198 A

 $E = 1/2 \times L_{max} \times (I_{max} \times safety factor)^2 = 0.5 \times 2.42 \,\mu\text{H} \times (0.198 \,\text{A} \times 1.5)^2 = 0.11 \,\mu\text{J} < 40 \,\mu\text{J}$ for Group IIC.

The circuits in the equipment were assessed as intrinsically safe in regard to inductive spark ignition.

A.2.3 Capacitive spark ignition

In case of the block-C/D, the maximum voltages in the circuits were determined by addition of the maximum voltage, 1.3 V, generated from the electrochemical sensors to the voltages applied in the block-C/D. In case of the other blocks, the maximum voltage in each circuit was determined as the voltage applied in each block.

The maximum voltage of each block and the maximum effective capacitance connected to the voltage were compared to the values given in Table A.2 as follows.

- block-A

1.45 μ F at 3.9 V < 100 μ F at 5.0 V for Group IIC and a safety factor of 1.5. 0.35 μ F at 11.7 V < 1.54 μ F at 11.7 V for Group IIC and a safety factor of 1.5.

- block-B

0.11 μ F at 4.1 V < 100 μ F at 5.0 V for Group IIC and a safety factor of 1.5.

block-C

29.15 μ F at 5.4 V < 65 μ F at 5.4 V for Group IIC and a safety factor of 1.5.

- block-D

50 μ F at 5.4 V < 65 μ F at 5.4 V for Group IIC and a safety factor of 1.5.

The circuits in the equipment were assessed as intrinsically safe in regard to capacitive spark ignition.

A.2.4 Combination of inductive and capacitive spark ignition

The sum of all the capacitances or all the inductances in each block on the circuit boards is less than 1 % of the allowable limit as follows. The circuits were considered acceptable without further testing.

- block-B

0.11 μF at 4.1 V < 100 μF at 5.0 V for Group IIC and a safety factor of 1.5. \rightarrow 0.11 % of the allowable capacitance limit

- block-C

E = $1/2 \times L_{max} \times (I_{max} \times safety factor)^2 = 0.5 \times 54.8 \text{ nH} \times (1.655 \text{ A} \times 1.5)^2 = 0.17 \text{ μJ} < 40 \text{ μJ for Group IIC.} \rightarrow 0.43 \% \text{ of the allowable inductance limit}$

- block-D

E = $1/2 \times L_{max} \times (I_{max} \times safety factor)^2 = 0.5 \times 2.42 \,\mu\text{H} \times (0.198 \,\text{A} \times 1.5)^2 = 0.11 \,\mu\text{J} < 40 \,\mu\text{J}$ for Group IIC. \rightarrow 0.28 % of the allowable inductance limit

The circuits in the equipment were assessed as intrinsically safe in regard to combination of inductive and capacitive spark ignition.

A.2.5 Shunt short-circuit (crowbar) spark ignition

The equipment does not contain any crowbar circuits. The assessment of this section isn't necessary.

A.2.6 Other spark ignition considerations

<Piezo-electric buzzer, BZ1, on the main board>

The equipment contains a piezo-electric buzzer, part no. CBE1440BP-L, manufactured by Daeyoung Electric and was tested in accordance with Cl.10.7 (see Appendix B.4). The maximum capacitance of the buzzer is 19.5 nF at 120 Hz from the manufacturer's specification. The maximum voltage appearing across the buzzer was 17.5 V from the test.

According to Cl.10.7, for Group IIC apparatus, the calculated energy resulting from the test shall not exceed 50 μ J. The calculation of the worst case energy is as follows; E = $1/2 \times C \times V^2 = 0.5 \times 19.5$ nF × $(17.5 \text{ V})^2 = 2.99 \,\mu\text{J} < 50 \,\mu\text{J}$

Therefore, the piezo-electric buzzer was considered acceptable for use.

<NDIR Sensor, MIPEX-04-X-XX-3.1, on the main board>

The equipment contains an IECEx certified (Certificate No. IECEx ITS 19.0005U) NDIR sensor, part no. MIPEX-04-X-XX-3.1, manufactured by Optosense LLC.

The applicable types of the NDIR sensor are as follows; MIPEX-04-a-bb-3.1

- MIPEX-04: MIPEX model number
- a: Target gas; 1 CH₄, 2 C₃H₈
- bb: Application; if a = 1, 01, 11, 21, 02, 12, 22, 61, 71, 62, 72 If a = 2, 61, 71, 62, 72

The applicable NDIR sensors have the following electrical parameters for intrinsic safety. $U_i = 5.5 \text{ V}$, $I_i = 200 \text{ mA}$, $P_i = 0.13 \text{ W}$, $C_i = 26 \mu\text{F}$, $L_i = 0$

The NDIR sensor is used in the block-D. Maximum electrical parameters applied in the block-D are determined after considering the maximum voltage generated from the electrochemical sensors in the block-C, 1.3 V, as follows;

- $-U_{max} = 4.1 \text{ V} + 1.3 \text{ V} = 5.4 \text{ V} < U_i = 5.5 \text{ V}$
- $I_{max} = U_{max} / (R43||R44||R45)$ on the sensor board) = 5.4 V / (27.57 $\Omega \times 0.99$) = 198 mA < I_i = 200 mA

Therefore, the NDIR sensor was considered acceptable for use in regard to spark ignition.

A.3 Thermal ignition consideration

A.3.1 Temperature for small components for Group I and Group II

Maximum power dissipated in the circuits after passing through the zener diodes, D1~D2, the internal resistance of the batteries and the current limiting resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board, is 130 mW based on the calculation shown below.

 $P_{block-A} = V^2/4R = (U_n \text{ from a nominal voltage of the cell})^2 / (4 \times (\text{internal resistance of the batteries in parallel} + R2||(R1 + R10||(R5 + R4||R7||R8 \text{ on the main board } ||R25||R8||R13||R20||R23||R40 \text{ on the sensor board}))) = (3.6 V)^2 / (4 \times 27.0 \ \Omega) = 120 \ \text{mW}$

 $P_{block-B} = V^2/4R = (\dot{U}_n \text{ from a nominal voltage of the cell})^2 / (4 \times (\text{internal resistance of the batteries in parallel} + R5||(R10 + R4||R7||R8 \text{ on the main board }||R25||R8||R13||R20||R23||R40 \text{ on the sensor board}))} + U_{max} \text{ from D1 and D2 } / (4 \times (R1 + R4||R7||R8 \text{ on the main board }||R25||R8||R13||R20||R23||R40 \text{ on the sensor board}))} = (3.6 \text{ V})^2 / (4 \times 25.8 \ \Omega) + (4.1 \text{ V})^2 / (4 \times 1241.44 \ \Omega) = 129 \text{ mW}}$

 $P_{block-c} = V^2/4R = (U_n \text{ from a nominal voltage of the cell})^2 / (4 \times (\text{internal resistance of the batteries in parallel} + R10||(R5 + R4||R7||R8 \text{ on the main board }||R25||R8||R13||R20||R23||R40 \text{ on the sensor board}))} + U_{max} \text{ from D1 and D2} / (4 \times R1) = (3.6 \text{ V})^2 / (4 \times 25.8 \ \Omega) + (4.1 \text{ V})^2 / (4 \times 990 \ \Omega) = 130 \text{ mW}$ $P_{block-D} = V^2/4R = (U_n \text{ from a nominal voltage of the cell})^2 / (4 \times (\text{internal resistance of the batteries in parallel} + R10||(R5 + R4||R7||R8 \text{ on the main board }||R25||R8||R13||R20||R23||R40) + R43||R44||R45 \text{ on the sensor board})) + U_{max} \text{ from D1 and D2} / (4 \times (R1 + R43||R44||R45) = (3.6 \text{ V})^2 / (4 \times 53.37 \ \Omega) + (4.1 \text{ V})^2 / (4 \times 1.017.57 \ \Omega) = 64.8 \text{ mW}$

The maximum dissipation power of each current limiting resistor is 374 mW based on the calculation shown below.

 $P_{R2,R5,R10_max} = R \times I^2 = R2 \times (U_n / (internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2) (Internal resistance of the batteries in parallel + R2))^2 = (22 \Omega \times 0.99) \times Internal resistance of the batteries in parallel + R2) (Internal resistance of the batteries in parallel + R2)) (Internal$ $(3.6 \text{ V} / (5.68 \Omega + 22 \Omega \times 0.99))^2 = 374 \text{ mW}$ for R2, R5 and R10 on the main board $P_{R1 \text{ max}} = R \times I^2 = R1 \times (U_{max} \text{ from D1 and D2 / R1})^2 = (1 \text{ K}\Omega \times 0.99) \times (4.1 \text{ V} / (1 \text{ K}\Omega \times 0.99))^2 = 17 \text{ mW for}$ R1 on the main board

 $P_{R8 \text{ on the main board_max}} = R \times I^2 = R8 \times (U_n / (internal resistance of the batteries in parallel + R5 + R8))^2 = (330)$ $\Omega \times 0.99$) × (3.6 V / (5.68 Ω + 22 $\Omega \times 0.99$ + 330 $\Omega \times 0.99$))² = 34 mW for R8 on the main board $P_{R25_max} = R \times I^2 = R25 \times (U_n / (internal resistance of the batteries in parallel + R5 + R25))^2 = (1 K\Omega \times 0.99)$ $\times (3.6 \text{ V} / (5.68 \Omega + 22 \Omega \times 0.99 + 1 \text{ K}\Omega \times 0.99))^2 = 12 \text{ mW for R25 on the sensor board}$

 $P_{R4.R7.R8 \text{ on the sensor board.R13.R20.R23.R40 max}} = R \times l^2 = R4 \times (U_n / (internal resistance of the batteries in parallel + leaves and the sensor board.R13.R20.R23.R40 max})$ R5 + R4))² = $(100 \text{ K}\Omega \times 0.99) \times (3.6 \text{ V} / (5.68 \Omega + 22 \Omega \times 0.99 + 100 K}\Omega \times 0.99))^2 = 0.13 \text{ mW for R4, R7}$ on the main board, R8, R13, R20, R23, R40 on the sensor board

PR43,R44,R45_max \leq Pblock-c = 130 mW

The maximum dissipation power of each zener diode in the Zener mode is 120 mW based on the calculation shown below.

 $I_{D1,D2}$ Zener max = V/R = U_n / (internal resistance of the batteries in parallel + R2||(R1 + R10||(R5 + R4||R7||R8 on the main board ||R25||R8||R13||R20||R23||R40 on the sensor board))) = 3.6 V / 27.0 Ω = 0.133 A

 $P_{D1,D2_Zener_max} = V \times I/4 = U_n \times I_{D1,D2_Zener_max} / 4 = 3.6 V \times 0.133 A / 4 = 120 mW$

In case of small components having total surface area not less than 20 mm², maximum dissipation power in each component is less than 1.25 W required at T4 and 50 °C ambient as per Table 4 of IEC 60079-0 because maximum power supplied from the batteries to the boards after passing through the zener diodes, D1~D2, the internal resistance of the batteries and the current limiting resistors, R1, R2, R4, R5, R7, R8 and R10 on the main board, R8, R13, R20, R23, R25, R40, R43, R44 and R45 on the sensor board, is 0.130 W and maximum dissipation power of each current limiting resistor is 0.374 W.

In case of small components having total surface area less than 20 mm², maximum surface temperature of the components does not exceed 275 °C required at T4 and 50 °C ambient as per Table 3 of IEC 60079-0. In other words, their thermal coefficients, Rthj-a (Junction to Ambient) or Rthc-a (Case to Ambient), shall be less than (275 °C - 50 °C) / 0.130 W = 1 730 °C/W. The thermal coefficients were obtained from the test results or the manufacturer's specifications below.

- •R31(100 Ω , 1/10 W) on the sensor board at 130 mW : 41.3 °C at 24.7 °C ambient \rightarrow Rthc-a = (41.3 °C -24.7 °C) / 0.130 W = 127 °C/W from test results
- •R43(51 Ω , 1/4 W) on the sensor board at 0.130 W : 38.7 °C at 24.7 °C ambient \rightarrow Rthc-a = (38.7 °C 24.7 °C) / 0.132 W = 106 °C/W from test results
- •D1(BZT52C3V9) on the main board : Rthj-a = 338 °C/W from the manufacturer's specification
- •Q1(DDC123JU) on the main board : Rthj-a = 625 °C/W from the manufacturer's specification
- •Q3(NTGS3441 or NVGS3441) on the main board : Rthj-a = 244 °C/W from the manufacturer's specification
- •U5(AT25DF512C-MAHN-T) on the main board : Rthj-a = 64.58 °C/W from the manufacturer's specification
- •Q2(SST177) on the sensor board : Rthj-a = 357 °C/W from the manufacturer's specification
- •U1(TSU111) on the sensor board : Rthi-a = 205 °C/W from the manufacturer's specification
- •U2(TSU112) on the sensor board : Rthi-a = 57 °C/W from the manufacturer's specification
- •U6(SN74AUP1G07) on the sensor board : Rthj-a = 252 °C/W from the manufacturer's specification
- •U7(SN74AUP1T50) on the sensor board : Rthj-a = 259 °C/W from the manufacturer's specification
- •U5(MAX17220) on the sensor board : Rthj-a = 223.6 °C/W from the manufacturer's specification

The highest thermal coefficient obtained was 625 °C/W, which is less than 1 730 °C/W.

Therefore, the equipment satisfies the assigned temperature class T4 at 50 °C ambient.

A.3.2 Wiring within intrinsically safe apparatus for Group I and Group II

The internal wiring is used for connection between the battery pack containing two batteries connected in parallel and the main board, which belongs to the block-A. According to the dissipated power calculation of the block-A in A.3.1, the maximum dissipation power of internal wires is 0.120 W which is less than 1.25 W required at T4 and 50 °C ambient as per Table 2 and Table 4 of IEC 60079-0. Therefore, the wires satisfy Table 2.

A.3.3 Tracks on printed circuit boards for Group I and Group II

Minimum Track width on PCB: 0.2 mm

Factor(Refer to the Table 3)

- Copper thickness: 33 µm (Factor: 1)
- Printed board thickness: 1.6 mm (Factor: 1)
- track layer on board : Four (Factor : ÷ 2)
- Tracks passing under component dissipating 0.25 W or more. : None (Factor : ÷ 1)
- Component dissipating 0.25 W or more & 1.00mm along the conductor: Yes (Factor: ÷2)
- Ambient temperature : 50 °C (Factor : ÷ 1.2)

The PCB tracks (with minimum track width of 0.2 mm and copper of 33 μ m thickness on multilayer of a PCB of 1.6 mm thickness) are considered suitable for a maximum current of 375 mA dc for a temperature classification of T4 in an ambient temperature of 50 °C. The maximum current in the equipment is U_n / (internal resistance of the batteries in parallel + R2||R5||R10 on the main board) = 3.6 V / (5.68 Ω + 7.26 Ω) = 278 mA from the power source block. Therefore, the PCB tracks satisfy Table 3.

A.3.4 Intrinsically safe apparatus and component temperature for Group III

This section is not applicable.

A.3.5 Temperature for the battery pack

Ten samples of the battery pack containing two batteries connected in parallel were tested for temperature rise under short circuit condition as per Cl.10.5.3. The maximum surface temperature of the battery pack determined from the tests was 126.6 °C at 50 °C ambient, which does not exceed 135 °C (T4), considering safety margin.

Therefore, the battery pack satisfies the assigned temperature class T4 at 50 °C ambient.

A.4 Rating of components

A.4.1 Resistors

| Component designation | Value : | Maximum rating (W1) | Rating used* (W2) | WiW2. | Calculation |
|-----------------------|------------|---------------------|-------------------|-------|--------------------------|
| R2,R5,R10 | 22 Ω ±1% | 1 000 mW | 374 mW | 2.67 | Refer to Appendix A.3.1. |
| R1 | 1 KΩ ±1% | 250 mW | 17 mW | 14.7 | Refer to Appendix A.3.1. |
| R8(main) | 330 Ω ±1% | 250 mW | 34 mW | 7.35 | Refer to Appendix A.3.1. |
| R25 | 1 KΩ ±1% | 250 mW | 12 mW | 20.8 | Refer to Appendix A.3.1. |
| R4,R7,R8(sensor), | | | | | |
| R13,R20,R23,R40 | 100 KΩ ±1% | 250 mW | 0.13 mW | 1 923 | Refer to Appendix A.3.1. |
| R43 | 51 Ω ±1% | 250 mW | 130 mW | 1.92 | Refer to Appendix A.3.1. |
| R44,R45 | 120 Ω ±1% | 250 mW | 130 mW | 1.92 | Refer to Appendix A.3.1. |

^{(*&}quot;Rating used" is a term used to describe the maximum voltage, current and/or power which the component may be subjected to when applying the number of faults as prescribed in the Standards.)
(All the components are rated at 50 °C ambient.)

A.4.2 Shunt voltage limiters

The maximum dissipation power of each zener diode in the Zener mode was described in Appendix A.3.1. The maximum dissipation power of each zener diode in the forward direction is calculated as below; $l_{D1,D2_forward_max} = 0$ (The current of D1 and D2 in forward direction does not occur after the application of faults, as provided in Cl.5.2.)

| Component designation | Value | | Rating used* (W2) | , W1/W2 | Calculation |
|-----------------------|-----------|--------|-------------------|---------|--------------------------|
| D1,D2(BZT52C | | | | | |
| 3V9) in Zener | 3.9 V ±5% | 300 mW | 130 mW | 2.31 | Refer to Appendix A.3.1. |
| mode | | | | | |

^{(*&}quot;Rating used" is a term used to describe the maximum voltage, current and/or power which the component may be subjected to when applying the number of faults as prescribed in the Standards.)
(All the components are rated at 50 °C ambient.)

A.4.3 Series current limiter

The equipment does not contain any semiconductor series current limiting devices.

APPENDIX B: Tests

Option 2: If tests records are not provided as an attachment, please complete the following table:

B.1 Temperature tests

| Equipment Tested: | Components on the circuit board in the equipment |
|----------------------------|--|
| Date of Test (yyyy/mm/dd): | 2019/11/15 |
| Clause and Standards: | Cl.26.5 of IEC 60079-0 and Cl.10.2 of IEC 60079-11 |

B.1.1 Test procedures

Samples of selected components used in the intrinsically safe circuits were in turn connected across a source of supply. At the approximate powers or currents indicated, the temperatures of the components and the exact powers dissipated across them were recorded. The components were mounted as intended, i.e. on an equivalent sample to the manufacturer's circuit board, in their worst case mounting configuration. The temperatures were measured using a thermal image scanner (Ti25 of Fluke).

B.1.2 Results

Temperature tests were conducted on some small components to determine their thermal coefficients which are not obtained from the manufacturers.

| 原控制 | Component ¼ , ¼ | 的机场的 | 强输Test co | nditions 🤻 🥨 | . Test | resulti | Calculate | ed maximum temp | erature | Verdict |
|-------------|-----------------------|------------|-----------|--------------|----------------|------------|------------|-----------------|--|-----------|
| No. | 2000年 | 第二条 | | | Max temp: | 为新业 | Max | Max temp. | Control of the Contro | 没想 |
| Ref. | Part No. | | Condition | Actual | Max. temp: | Amblent | amblent. | VIOLENCE OF THE | Odie | Ti Class |
| NO. | TANK THE PARTY OF THE | | desired | condition | measured | & temp\$## | temp | Corrected | | (for≱T4) |
| 多 種。 | 的时间 对特别 | 建 | | 经基础整理 | 发现这种形 数 | | 家(for T4)点 | | | 新 |
| R31 | 100Ω±1%,1/10W | Ti | 130 mW | 130 mW | 41.3 °C | 24.7 °C | 50 °C | 66.6 °C | 5K | Pass |
| R43 | 51 Ω ±1%,1/4W | TI | 130 mW | 132 mW | 38.7 °C | 24.7 °C | 50 °C | 64.0 °C | 5K | Pass |

(*"Test method": TC-Thermocouple, TI-Thermal image scanner)

(***Condition desired" is a term used to describe the maximum voltage, current and/or power which the component may be subjected to when applying the number of faults as prescribed in the Standards.)

The thermal coefficients were determined from the test results as follows.

- 1) R31(100 Ω , 1/10 W) on the sensor board at 0.130 W : 41.3 °C at 24.7 °C ambient \rightarrow Rthc-a = (41.3 °C 24.7 °C) / 0.130 W = 127 °C/W.
- 2) R43(51 Ω , 1/4 W) on the sensor board at 0.130 W : 38.7 °C at 24.7 °C ambient \rightarrow Rthc-a = (38.7 °C 24.7 °C) / 0.132 W = 106 °C/W.

The components smaller than 20 mm² above were verified as having their thermal coefficients less than 1 730 °C/W. Therefore, the components satisfy the assigned temperature class T4 at 50 °C ambient.

The maximum surface temperature rise of the enclosure of the equipment determined at worst fault conditions is negligible (less than 10 K). The service temperature is regarded as 60 °C at 50 °C ambient.

B.2 Determination of parameters of loosely specified components

| Equipment Tested: | 10 samples of the vibration motor, M1 (Z6SH1B0060711) |
|----------------------------|---|
| Date of Test (yyyy/mm/dd): | 2019/02/21 |
| Clause and Standards: | Cl.10.4 of IEC 60079-11 |

B.2.1 Test procedures

Ten unused samples of each component above were obtained from the manufacturer of the equipment. Their relevant parameters were measured using suitable instruments (such as E4980AL Precision LCR Meter of KEYSIGHT).

B.2.2 Results

Parameters of ten unused samples of the vibration motor, M1 (Z6SH1B0060711), manufactured by JINLONG MACHINERY & ELECTRONIC CO., LTD., were measured using 1 kHz and 1 V conditions at room temperature, 20 °C to determine the maximum inductance. The results are as follows.

| Component | | Vibration motor, M1 (Z6SC0B0150081) | | | | | | | | |
|--|----------------|-------------------------------------|------------|-------------|--------------|-----------------|------------|-------|------------------------|--------|
| Charles and the same of the sa | | | 是一个 | W. Christia | 森像 Samp | ie No. | A STATE OF | | d reduction and are in | |
| Talalle le la | 多斯/指数 集 | 数 20 0 | 机震3厘线 | 运动400 | 第25 5 | 10 6 0 电 | 概念78期空 | W 8 3 | 沙城 9系统 | 器線10線料 |
| Inductance (uH) | 127 | 125 | 121 | 118 | 111 | 108 | 113 | 118 | 114 | 119 |

The motor was determined as having the maximum measured inductance of 127 μH.

B.3 Determination of internal resistance of cells and batteries

| Equipment Tested: | 10 samples of the battery pack containing two batteries (Tekcell, type SB-AA11) connected in parallel |
|----------------------------|---|
| Date of Test (yyyy/mm/dd): | 2019/04/16 |
| Clause and Standards: | Cl.7.4.4, Cl.10.4, Cl.10.5.1 and Cl.10.5.3 of IEC 60079-11 |

B.3.1 Test procedures

Ten representative samples of the battery for use in the intrinsically safe equipment were obtained from the manufacturer of the battery.

The internal resistance of the battery was determined from the open circuit voltage and short circuit current and measured at room temperature using suitable instruments (such as HIOKI 3555 Battery HITESTER). The short circuit was configured using a link with a maximum resistance of 3 m Ω or a voltage drop across it not exceeding 200 mV or 15 % of the cell e.m.f.

B.3.2 Results

Internal resistances of ten samples of the battery pack containing two batteries (Tekcell, type SB-AA11) connected in parallel manufactured by VITZRO CELL were measured as follows.

| Component | | Battery pack containing two batteries (Tekcell, type SB-AA11) connected in parallel | | | | | | | | |
|----------------------------------|-------------------------|---|----------------|----------|----------------|-------|--------------|-----------------|------|--------------------|
| Datamatan | | | SPIXXXX | | Samp | le No | | | | |
| Falalletelo | TEXT 1 1 1 1 1 1 | 54.2 2 | H# 3 144 | 温度如4300年 | 新籍 5 里普 | 國際6門標 | 阿里7/赛 | 建設 8 基 建 | 整整9 | 39 条1000000 |
| Internalls (Ω) Resistance (Ω) | 6.80 | 8.65 | 5.85 | 6.61 | 5.68 | 8.26 | 7.18 | 6.02 | 6.71 | 7.34 |

The battery pack was determined as having the minimum internal resistance of 5.68 Ω.

B.4 Surface temperature and Electrolyte leakage test of cells and batteries

| Equipment Tested: | 10 samples of the battery pack containing two batteries (Tekcell, type SB-AA11) connected in parallel |
|----------------------------|---|
| Date of Test (yyyy/mm/dd): | 2019/04/16~23 |
| Clause and Standards: | Cl.10.5.2 and Cl.10.5.3 of IEC 60079-11 |

B.4.1 Test procedures

Ten representative samples of the battery for use in the intrinsically safe equipment were obtained from the manufacturer of the battery.

All current limiting devices external to the cell were short circuited and each cell was in turn short circuited until discharged using a short-circuit link with a maximum resistance of 3 m Ω (excluding the connections to the cell). The cells were arranged in a way as to simulate the thermal effects of their intended position in the complete equipment. The temperatures were measured at the interface of the sheath and the metal surface of each cell because the external sheath was fitted. The temperature was determined on the hottest surface of the cell that may be exposed to the explosive atmosphere and the maximum figure taken. The temperatures of the cells short-circuited were recorded with respect to time at room temperature.

The temperatures were measured using T-type thermocouples connected to a temperature-indicating device (µR10000 recorder of Yokogawa). The thermocouples were secured by tape.

After the application of the above tests, the test samples were placed with any case discontinuities, e.g. seals, facing downward over a piece of blotting paper for a period of at least 12 h.

B.4.2 Results

The test results were as follows.

| | | | Testr | esulty | , Calcu | lated maxim | iúm, c | Verdict | Leaked |
|---------------------------|------------------|-----------------|-----------|---------|------------------|-----------------------|--------------------|----------|--------------|
| Component | ≇Test/ method | Test conditions | Max temp. | Ambient | Max | Max temp | Safety | T Class | for a period |
| | | | measured | temp | temp (for T4) | corrected (for T4) | margin (for T4) | (for T4) | hours (Y/N) |
| Tekcell, type SB-AA11 #1 | TC | Short-circuited | 98.4 °C | 21.8 °C | 50 °C | 126.6 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #2 | TC | Short-circuited | 93.2 °C | 21.6 °C | 50 °C | 121.6 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #3 | TC | Short-circuited | 96.5 °C | 21.2 °C | 50 °C | 125.3 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #4 | TC | Short-circuited | 91.0 °C | 21.8 °C | 50 °C | 119.2 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #5 | TC | Short-circuited | 90.1 °C | 21.2 °C | 50 °C | 118.9 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #6 | TC | Short-circuited | 90.2 °C | 19.4 °C | 50 °C | 120.8 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #7 | TC | Short-circuited | 93.6 °C | 21.2 °C | 50 °C | 122.4 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #8 | TC | Short-circuited | 95.0 °C | 21.0 °C | 50 °C | 124.0 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #9 | TC | Short-circuited | 93.1 °C | 21.0 °C | 50 °C | 122.1 °C | 5K | Pass | No leakage |
| Tekcell, type SB-AA11 #10 | TC | Short-circuited | 92.8 °C | 20.8 °C | 50 °C | 122.0 °C | 5K | Pass | No leakage |

(*"Test method": TC-Thermocouple, TI-Thermal image scanner)

The maximum surface temperature of the battery pack determined from the tests was 126.6 °C at 50 °C ambient, which does not exceed 135 °C (T4), considering safety margin. Therefore, the battery pack satisfies the assigned temperature class T4 at 50 °C ambient.

For 12 hours after the short-circuited tests of the test samples until discharged, there was no visible sign of electrolyte leakage from the test samples.

B.5 Tests for intrinsically safe apparatus containing piezoelectric devices

| Equipment Tested: | A sample of the G-Finder Multi GFM-400 series Portable Multi Gas Detector |
|----------------------------|---|
| Date of Test (yyyy/mm/dd): | 2019/11/15 |
| Clause and Standards: | Cl.10.7 of IEC 60079-11 |

B.5.1 Test procedures

The capacitance of the piezoelectric device was first obtained from the manufacturer's specification or measured using suitable instruments (such as E4980AL Precision LCR Meter of KEYSIGHT). The enclosure of the device was then subjected to two impact at (20 ± 10) °C and the maximum voltage generated across the piezoelectric device was measured using suitable instruments (such as DL1740 Digital Oscilloscope of Yokogawa). An impact energy of 7 J was affected by 1 kg test mass having a hardened steel impact head 25 mm in diameter falling through a vertical distance of 0.7 m. For the test, the intrinsically safe equipment was mounted on a steel base having a mass of at least 20 kg.

For portable equipment, the position was determined to produce the highest voltage. Protective guards(enclosure) used to prevent direct physical impact of the piezoelectric device were left in place for the test.

At the conclusion of the test, the energy stored by the piezoelectric device was calculated using the following formula:

 $E = 1/2 \times CV^2$

Where:

E = energy stored by the piezoelectric device, J

C = capacitance of the piezoelectric device, F

V = voltage measured across the piezoelectric device, V

B.5.2 Results

The test ambient temperature was 24.7 °C. The test results were as follows.

| Test sample | | | Capacitance | Impact No. | Measured Voltage (V) | Calculated Energy (µJ) |
|-------------|-------------------|----------------------------|-------------|------------|-------------------------|---------------------------|
| Part No. | Manufacturer | Condition | 19.5 nF | 1 | 10.63 | 1.10 |
| CBE1440BP-L | Daeyoung Electric | Installed in the equipment | (@ 120 Hz) | 2 | 17.50 | 2.99 |

The energy stored by the piezoelectric device did not exceed 50 μJ for Group IIC. There was no damage to the protective guard(enclosure).

B.6 Drop test

| Equipment Tested: | A sample of the G-Finder Multi GFM-400 series Portable Multi Gas Detector |
|----------------------------|---|
| Date of Test (yyyy/mm/dd): | 2019/11/15 |
| Clause and Standards: | Cl.26.4.3 and Cl.26.4.4 of IEC 60079-0 |

B.6.1 Test procedures

Prior to being dropped, the sample of the equipment employing a non-metallic enclosure was placed in a climate chamber for 24 hours to reduce its temperature to 5 °C below the lowest ambient temperature of the equipment, -25 °C.

The equipment was dropped four times onto a smooth concrete surface from a height of 1 m. the sample was released from the most unfavourable initial position(s) as determined by examination of the overall construction of the equipment.

The sample was observed for displacement or deformation invalidating the intrinsic safety and no ejection of any component.

B.6.2 Results

There was no significant visible damage of the equipment except superficial damage and no ejection of any component.

B.7 Surface resistance test of parts of parts of enclosures of non-metallic materials

| Equipment Tested: | Each rectangular plate with 149 mm x 60 mm size of conductive elastomer, RTP 2099 E X 100781, and anti-static coating film, JB-SD10008 |
|----------------------------|--|
| Date of Test (yyyy/mm/dd): | 2019/03/21, 2019/06/04 |
| Clause and Standards: | Cl.26.13 of IEC 60079-0 |

B.7.1 Test procedures

Each rectangular plate of conductive elastomer, RTP 2099 E X 100781, and anti-static coating film, JB-SD10008, having an intact clean surface was obtained from the manufacturer of the equipment. The test pieces were cleaned with distilled water, then with isopropyl alcohol, then once more with distilled water before being dried. Untouched by bare hands, they were placed in a climate chamber and conditioned for at least 24 h at (23 ± 2) °C and (30 ± 5) or (50 ± 5) % relative humidity. The surface resistance tests were carried out under the same ambient conditions.

A voltage of (500 ± 10) V was applied for (65 ± 5) s between the electrodes and the resistance was measured using suitable instruments (such as UNILAP ISO X Digital Insulation tester).

B.7.2 Results

The surface resistance of the conductive elastomer, RTP 2099 E X 100781, was measured to be less than $3 \times 10^8 \Omega$ at (30 ± 5) % relative humidity.

The surface resistance of the anti-static coating film, JB-SD10008, was measured to be less than 2×10^7 Ω at (50 ± 5) % relative humidity.

GFM-400 ELECTRONIC SCHEDULE DRAWING LIST

| Drawing No. | Title | Rev. No. | Date of Revision | Designed | Checked | Approved | Remarks |
|----------------|---|----------|------------------|----------|----------|-------------|---------|
| Ex-GE-25S00 | GFM-400 INTRINSIC BLOCK DIAGRAM | 1 | 14.08.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25801 | GFM-400 MAIN SCHEMATIC | ı | 24.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25S02 | GFM-400 SENSOR SCHEMATIC | 1 | 13.08.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25S03 | GFM-400 BLEUTOOTH SCHEMATIC | 1 | 15.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-1 | TOP LAYER | 0 | 22.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-2 | SILK SCREEN TOP + SOLDER MASK TOP LAYERS | 0 | 22,07,2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-3 | BOTTOM LAYER | 0 | 22,07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-4 | SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS | 0 | 22.07.2019 | S.M. BAE | S.H. YI | II,J, JOUNG | |
| Ex-GE-25P00-5 | GROUND PLANE | 0 | 22.07.2019 | S.M. BAE | S,II, YI | H.J. JOUNG | |
| Ex-GE-25P00-6 | POWER PLANE | 0 | 22.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-7 | TOP LAYER DIMENSION | 0 | 22.07.2019 | S.M. BAE | S.H. Yl | H.J. JOUNG | |
| Ex-GE-25P00-8 | BOTTOM LAYER DIMENSION | 0 | 22,07,2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-9 | GROUND PLANE DIMENSION | 0 | 22.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-10 | POWER PLANE DIMENSION | 0 | 22.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P00-11 | DRILL | 0 | 22.07.2019 | S,M, BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-1 | TOP LAYER | 0 | 20,09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-2 | SILK SCREEN TOP + SOLDER MASK TOP LAYERS | 0 | 20.09.2019 | S.M. BAE | S,H, Yl | H.J. JOUNG | - |
| Ex-GE-25P01-3 | BOTTOM LAYER | 0 | 20.09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-4 | SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS | 0 | 20.09.2019 | S.M. BAE | S.11. Y1 | HJ. JOUNG | |
| Ex-GE-25P01-5 | GROUND PLANE | 0 | 20,09,2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-6 | POWER PLANE | 0 | 20.09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-7 | TOP LAYER DIMENSION | 0 | 20.09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-8 | BOTTOM LAYER DIMENSION | 0 | 20.09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-9 | GROUND PLANE DIMENSION | 0 | 20.09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-10 | POWER PLANE DIMENSION | 0 | 20.09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P01-11 | DRILL | 0 | 20,09.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P02-1 | TOP LAYER(SILK SCREEN TOP + SOLDER MASK TOP) LAYERS | 0.3 | 19.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P02-2 | BOTTOM(SILK SCREEN BOT + SOLDER MASK BOT) LAYERS | 0.3 | 19.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25P02-3 | GROUND-I PLANE | 0.3 | 19,07,2019 | S,M, BAE | S.11. YI | H.J. JOUNG | |
| Ex-GE-25P02-4 | GROUND-2 PLANE | 0.3 | 19.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25B00 | GFM-400 MAIN PART LIST | 1 | 30.09.2019 | S.M. BAE | Ş,H. YI | H.J. JOUNG | |
| Ex-GE-25B01 | GFM-400 SENSOR PART LIST | 1 | 14.08.2019 | S.M. BAE | S.H. YI | H.J. JOUNG | |
| Ex-GE-25B02 | GFM-400 BLUETOOTH PART LIST | 1 | 24.07.2019 | S.M. BAE | S.H. Yl | H.J. JOUNG | |

GFM-400 / INTRINSIC BLOCK DIAGRAM

Ex-GE-25S00 REV1.0 / 2019.08.14

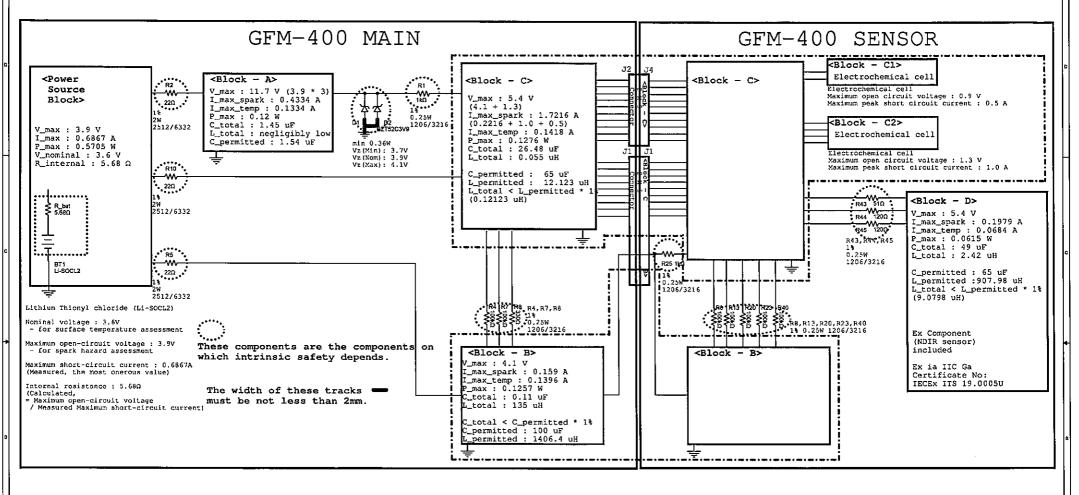
SCHEDULE DRAWING

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R&D PART GASTRON



| Rev. | Description | Rev. Date | DRAWN | CHECKED | APPROVED |
|------|-------------|------------|----------|---------|------------|
| 1.0 | For issued | 14.08.2019 | S.M. BAE | S.H. YI | H.J. JOUNG |
| | | | | | |
| | · | | | | |
| | | | | | |
| | | | | | |





SCHEDULE DRAWING

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| APPROVAL | | ON CO., LTD. |
|-----------|-----------------------|------------------------|
| S.M BAE | Model GFM-400 | _ |
| CHECKED | Tite GFM-400 Ir | ntrinsic Block Diagram |
| S.H YI | Size A3 | Rev 1.0 |
| APPROVED | Date Wednesday, Au | gust 14, 2019 |
| H.3 JOUNG | DWG. No Ex-GE-25 | S00 Sheet 1 of 1 |

GFM-400 / MAIN SCHEMATIC

Ex-GE-25S01 REV1.0 / 2019.07.24

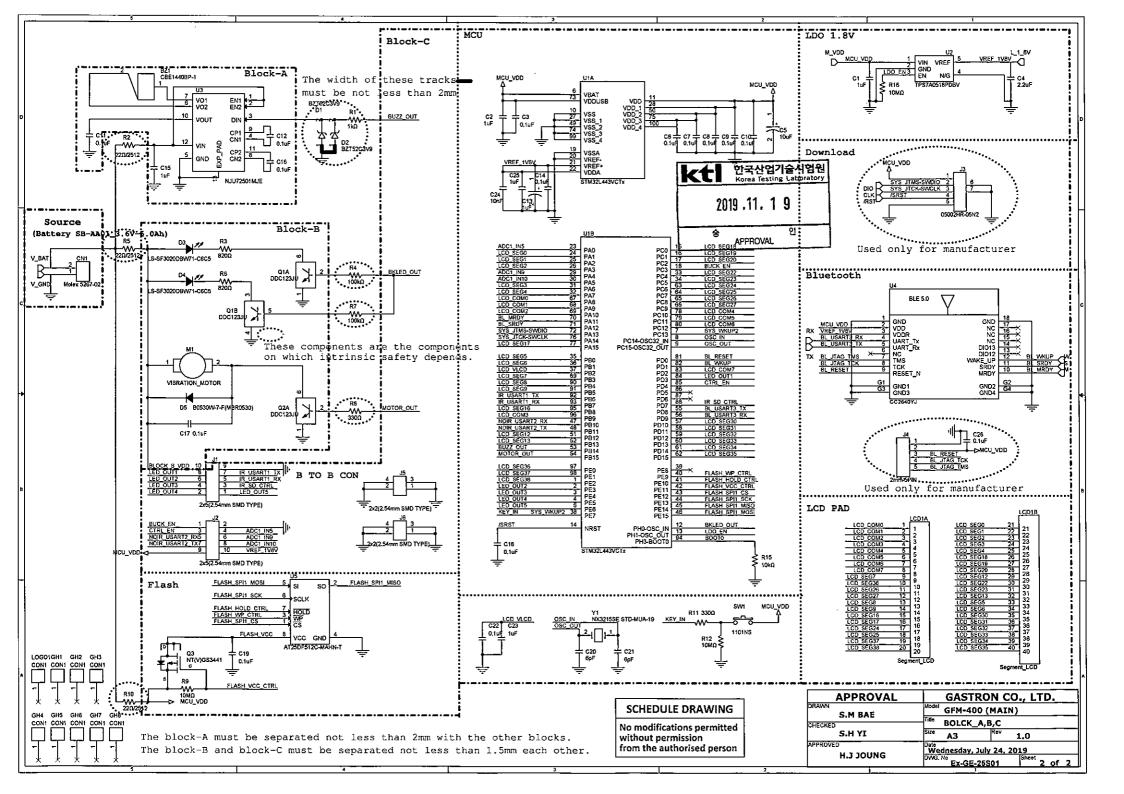
SCHEDULE DRAWING

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R&D PART GASTRON



| Rev. | Description | Rev. Date | DRAWN | CHECKED | APPROVED |
|------|-------------|------------|----------|---------|------------|
| 1.0 | For issued | 24.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG |
| | | | | | |
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| | | | | | |
| | | | | | |



GFM-400 / SENSOR SCHEMATIC

Ex-GE-25S02 REV1.0 / 2019.08.13

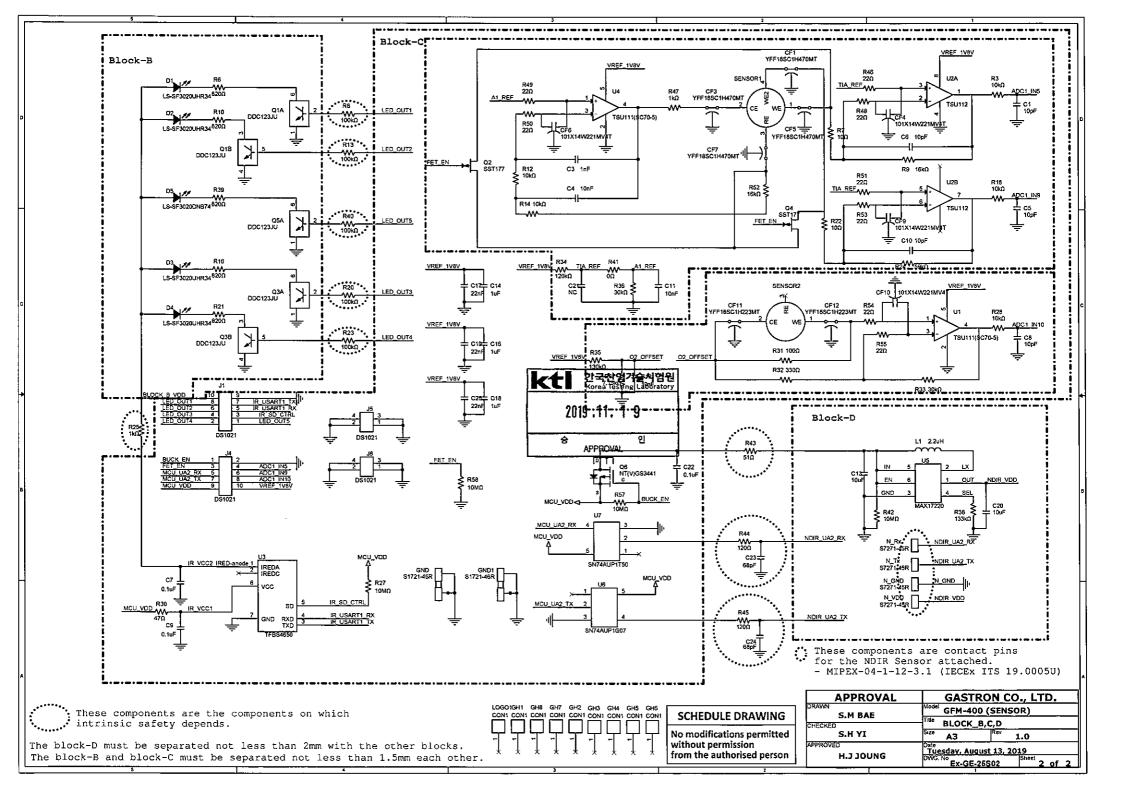
SCHEDULE DRAWING

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R&D PART GASTRON



| Rev. | Description | Rev. Date | DRAWN | CHECKED | APPROVED |
|------|-------------|------------|----------|---------|------------|
| 1.0 | For issued | 08.13.2019 | S.M. BAE | S.H. YI | H.J. JOUNG |
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GFM-400 / BLUETOOTH SCHEMATIC

Ex-GE-25S03 REV1.0 / 2019.07.15

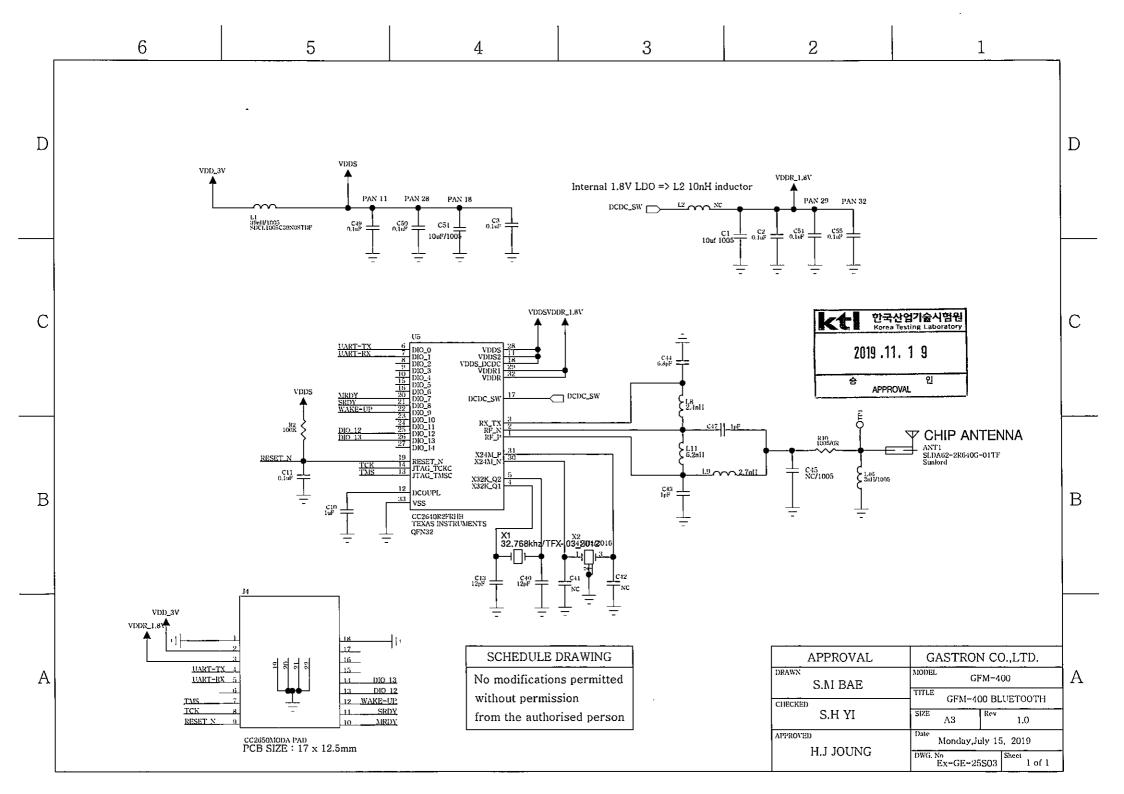
SCHEDULE DRAWING

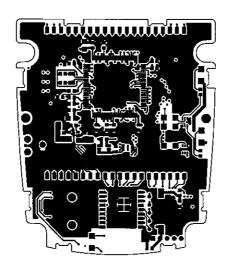
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R&D PART GASTRON



| Rev. | Description | Rev. Date | DRAWN | CHECKED | APPROVED |
|------|-------------|------------|----------|---------|------------|
| 1.0 | For issued | 15.07.2019 | S.M. BAE | S.H. YI | H.J. JOUNG |
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Rev.

For issued (PCB Rev1.0) 22.07.2019

Description

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S.M.BAE

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S.H.YI

Checked

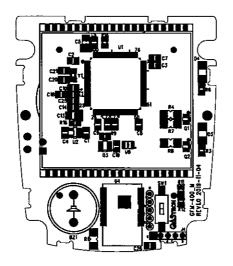
Approved

< PCB INFORMATION >

- PCB Material : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminated structure of the PCB

| ZZIIIIIII | radiate of the co | | | |
|----------------------------------|--|--------------------------|--|--|
| Structure | Thickness | Layer | | |
| Silk | - | Silk Top | | |
| Soldermask | - | Soldermask Top | | |
| Copper | > 33 um | Top Layer | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | |
| Copper | 35 um (1 oz) | Ground Plane | | |
| | 1.13 mm or | | | |
| Core | 0,93 mm | - | | |
| Core Copper | | - Power Plane | | |
| | 0,93 mm | Power Plane | | |
| Copper Prepreg / | 0,93 mm 35 um (1 oz) | Power Plane Bottom Layer | | |
| Copper Prepreg / Substrate | 0,93 mm 35 um (1 oz) 0,06 ~ 0,2 mm | - | | |

| | | GAS | TD. | | | | |
|--|-----------|-----------------|--------------|------------------|----------|--|--|
| | | Model | GFM | GFM-400 MAIN PCB | | | |
| | | Title | TOP LAYER | | | | |
| | | Part No. | 490A801-0001 | | | | |
| | | Material | FR-4 / ENIG | Finish | | | |
| | | Q'ty | - | Scale | 1/1 | | |
| | | Pro- jection | ⊕ | Units | mm | | |
| | H.J.JOUNG | DWG. No. | | | Rev. | | |
| | Approved | Ex-GE-25P00-1 | | | <u> </u> | | |





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S.M.BAE

Designed

S.H.YI

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SCHEDULE DRAWING

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Rev.

For issued (PCB Rev1.0) 22.07.2019

Description

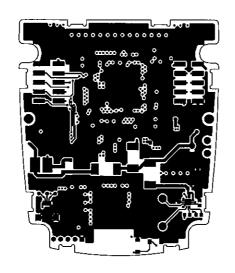
No modifications permitted without permission from the authorised person

< PCB INFORMATION >

- PCB Material : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminated structure of the PCB

| Structure | Thickness | Layer | | | |
|------------------------|-----------------------|-------------------|--|--|--|
| Silk | | Silk Top | | | |
| Soldermask | | Soldermask Top | | | |
| Copper | > 33 um | Top Layer | | | |
| Prepreg / Substrate | 0,06 ~ 0,2 mm | 1 | | | |
| Copper | 35 um (1 oz) | Ground Plane | | | |
| Core | 1,13 mm or 0,93 mm | - | | | |
| Copper | 35 um (1 oz) | Power Plane | | | |
| Prepreg / Substrate | 0.05 ~ 0.2 mm | - | | | |
| Copper | > 33 um | Bottom Layer | | | |
| Soldermask | - | Soldermask Bottom | | | |
| Silk | - | Silk Bottom | | | |

| | | Model | GFM-400 MAIN | | PCB |
|-------|-----------|-----------------|--|--------|----------|
| Title | | Title | SILK SCREEN TOP + SOLDER MASK TOP LAYERS | | |
| | | Part No. | 490A801-0001 | | 01 |
| | | Material | FR-4 / ENIG | Finish | Ī |
| | | Q'ty | - | Scale | 1/1 |
| | | Pro- jection | ⊕□ | Units | mm |
| | H.J.JOUNG | DWG. No. | | | Rev. |
| | Approved | Ex- | -GE-25P00- | -2 | <u> </u> |





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APPROVAL

S.M.BAE

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Checked

- PC8 Material : FR-4 - PCB Thickness : 1.6 mm - PCB Layer: 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um

< PCB INFORMATION >

- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminated structure of the PCB

| Structure | Thickness | Layer |
|------------------------|-----------------------|-------------------|
| Silk | | Silk Top |
| Soldermask | - | Soldermask Top |
| Copper | > 33 um | Top Layer |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | A.M. |
| Copper | 35 um (1 oż) | Ground Plane |
| Core | 1.13 mm or 0,93 mm | - |
| Copper | 35 um (1 oz) | Power Plane |
| Prepreg / Substrate | 0,06 ~ 0,2 mm | - |
| Соррег | > 33 um | Bottom Layer |
| Soldermask | - | Soldermask Bottom |
| Silk | - | Silk Boltom |

GASTRON CO.,LTD.

| | Model | GFM | PCB | _ | |
|-----------|-----------------|--------------|-----------|------|---|
| | Title | BOTTOM LAYER | | | |
| | Part No. | 49 | 90A801-00 | 01 | |
| | Material | FR-4 / ENIG | Finish | | _ |
| | Q'ty | 1 | Scale | 1/1 | |
| | Pro- jection | ♦ | Units | mm | |
| H.J.JOUNG | DWG. No. | | | Rev. | _ |
| Approved | Ex- | -GE-25P00- | -3 | | |

SCHEDULE DRAWING

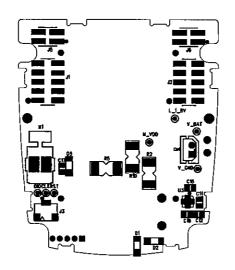
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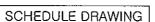
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Rev.

For issued (PCB Rev1.0) 22,07,2019

Description





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For issued (PCB Rev1.0) 22.07.2019

Date

Description

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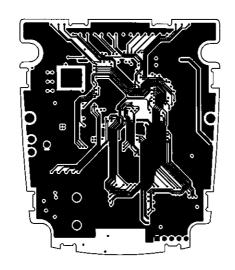
Checked

< PCB INFORMATION >

- PCB Material : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminated structure of the PCB

| Cambialca anaciale of the Fob | | | | | |
|-------------------------------|-----------------------|-------------------|--|--|--|
| Structure | Thickness | Layer | | | |
| Silk | - | Silk Top | | | |
| Soldermask | . <u>-</u> | Soldermask Top | | | |
| Copper | > 33 um | Top Layer | | | |
| Prepreg / Substrate | 0.06 - 0.2 mm | _ | | | |
| Copper | 35 um (1 oz) | Ground Plane | | | |
| Core | 1.13 mm or 0.93 mm | - | | | |
| Copper | 35 um (1 oz) | Power Plane | | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | | |
| Copper | > 33 um | Bottom Layer | | | |
| Soldermask | - | Soldermask Bottom | | | |
| Silk | - | Silk Battom | | | |

| | Model | Model GFM-400 MAIN | | PCB | |
|-----------|-----------------|--|-----------|------|--|
| Title | | SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS | | | |
| | Part No. | 4: | 90A801-00 | 01 | |
| | Material | FR-4 / ENIG | Finish | | |
| | Q'ty | _ | Scale | 1/1 | |
| | Pro- jection | ♦ □ | Units | mm | |
| H.J.JOUNG | DWG. No. | | | Rev. | |
| Approved | Ex-GE-25P00-4 | | | ₾ | |





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Rev.

For issued (PCB Rev1.0) 22.07,2019

Description

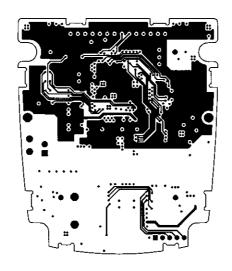
< PCB INFORMATION >

- PCB Malerial : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminaled structure of the PCB

| Structure | Thickness | Layer | | | |
|------------------------|-----------------------|-------------------|--|--|--|
| Silk | - | Silk Top | | | |
| Soldermask | - | Soldermask Top | | | |
| Copper | > 33 um | Top Layer | | | |
| Prepreg / Substrale | 0.06 ~ 0.2 mm | _ | | | |
| Copper | 35 um (1 oz) | Ground Plane | | | |
| Core | 1.13 mm or 0,93 mm | | | | |
| Copper | 35 um (1 oz) | Power Plane | | | |
| Prepreg / Substrate | 0,06 ~ 0,2 mm | - | | | |
| Copper | > 33 um | Bottom Layer | | | |
| Soldermask | | Soldermask Bottom | | | |
| Silk | - | Silk Boltom | | | |

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|----|-----|------|--------|-----|--------------|-----|-----|
| U/ | 13. | ľ | OI. | 1 C | VJ. . | L i | ľD. |

| | Model | GFM-400 MAIN | | PCB | |
|-----------|-----------------|-----------------|--------|------|---|
| | Title | GROUND PLANE | | NE | |
| | Part No. | Part No. 490A80 | | 01 | |
| , | Material | FR-4 / ENIG | Finish | | |
| | Q'ty | - | Scale | 1/1 | |
| | Pro- jection | ⊕□ | Units | mm | • |
| H.J.JOUNG | DWG. №. | | | Rev. | |
| Approved | Ex- | -GE-25P00- | ·5 | | |



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For issued (PCB Rev1.0) 22,07,2019

Description



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< PCB INFORMATION >

- PCB Material : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33,5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater

Model

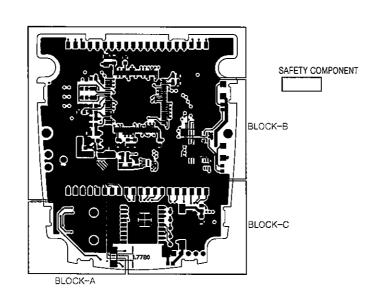
- Laminated structure of the PCB

| Laminated 360 | | |
|------------------------|-----------------------|-------------------|
| Structure | Thickness | Layer |
| Silk | - | Silk Top |
| Soldermask | - | Soldermask Top |
| Copper | > 33 um | Top Layer |
| Prepreg / Substrate | 0.06 0.2 mm | _ |
| Copper | 35 um (1 oz) | Ground Plane |
| Core | 1.13 mm or 0.93 mm | - |
| Copper | 35 um (1 oż) | Power Plane |
| Prepreg / Substrate | 0,06 ~ 0.2 mm | |
| Copper | > 33 um | Bottom Layer |
| Soldermask | - | Soldermask Bottom |
| Silk | | Silk Bottom |

GASTRON CO.,LTD.

GFM-400 MAIN PCB

| | Title | POWER PLAN | | ΛE |
|-----------|-----------------|----------------|--------|------|
| | Part No. | 490A801-0001 | | |
| | Material | FR-4 / ENIG | Finish | |
| | Q'ty | ** | Scale | 1/1 |
| | Pro- jection | ♦ □ | Units | mm |
| H.J.JOUNG | DWG. No. | | | Rev. |
| Approved | Ex- | Ex-GE-25P00-6 | | |



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Rev.

For issued (PCB Rev1.0) 22.07.2019

Date

Description

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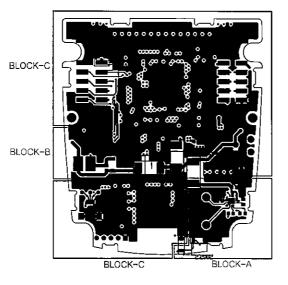
Checked

$\underline{< PCB \, INFORMATION >}$

- PCB Material : FR-4
- PCB Thickness: 1.6 mm
- PCB Layer: 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0,2 mm
- CTI: 100 or Greater
- Laminated structure of the PC

| - Laminaled structure of the PCB | | | | |
|----------------------------------|-----------------------|-------------------|--|--|
| Structure | Thickness | Layer | | |
| Silk | | Silk Top | | |
| Soldermask | - | Soldermask Top | | |
| Copper | > 33 um | Top Layer | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | |
| Copper | 35 um (1 oz) | Ground Plane | | |
| Core | 1.13 mm or 0.93 mm | - | | |
| Copper | 35 um (1 oz) | Power Plane | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | |
| Copper | > 33 um | Boltom Layer | | |
| Soldermask | - | Soldermask Bottom | | |
| Silk | - | Silk Boltom | | |

| | Model | GFM | 1-400 MAIN | PCB | |
|-----------|-----------------|-------------|------------|-------|--|
| | Title | TOPL | AYER DIME | NSION | |
| | Part No. | 45 | 90A801-00 | 01 | |
| | Material | FR-4 / ENIG | Finish | | |
| | Q'ty | ı | Scale | 1/1 | |
| | Pro- jection | * | Units | mm | |
| H'1'10NNG | DWG. No. | | | Rev. | |
| Approved | Ex- | -GE-25P00- | •7 | 🙆 | |



SAFETY COMPONENT

For issued (PCB Rev1.0) 22.07.2019

Date

Description

BLOCK-B

< PCB INFORMATION >

PCB Material : FR-4

PCB Thickness : 1.6 mm

PCB Layer: 4 Layers Conductor material : Copper

Minimum conducting track thickness: 33.5 um

Minimum track width: 0.2 mm

CTI: 100 or Greater

- Laminated structure of the PCB

| Structure | Thickness | Layer |
|------------------------|-----------------------|-------------------|
| Silk | - | Silk Top |
| Soldermask | | Soldermask Top |
| Copper | > 33 um | Top Layer |
| Prepreg / Substrate | 0,06 ~ 0,2 mm | - |
| Copper | 35 um (1 oz) | Ground Plane |
| Core | 1,13 mm or 0.93 mm | - |
| Copper | 35 um (1 oz) | Power Plane |
| Prepreg / Substrate | 0.06 0.2 mm | - |
| Copper | > 33 um | Bottom Layer |
| Soldermask | | Soldermask Bottom |
| Silk | - | Silk Bottom |

SCHEDULE DRAWING

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Rev.

한국산업기술시험원 Korea Testing Laboratory 2019 .11. 1 9 슝 APPROVAL

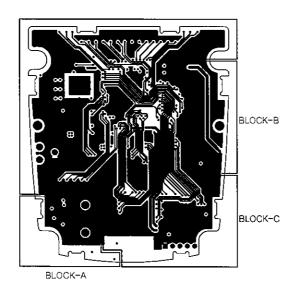
S.M.BAE

Designed

S,H.YI

Checked

| | Model | GFM | -400 MAIN | PC8 |
|-----------|-----------------|-------------|-----------|---------|
| | Title | воттом | LAYER DI | MENSION |
| | Part No. | 4! | 90A801~00 | 01 |
| | Material | FR-4 / ENIG | Finish | |
| | Q'ty | _ | Scale | 1/1 |
| | Pro- jection | ⊕ | Units | mm |
| H'1'100NG | DWG. №. | | | Rev. |
| Approved | Ex- | -GE-25P00- | ·8 | 🙆 |



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Date

S.M.BAE

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S.H.YI

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For issued (PCB Rev1.0) 22.07.2019

Description

< PCB INFORMATION >

- PCB Material : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0,2 mm
- CTI: 100 or Greater

Model

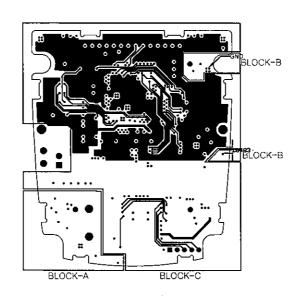
- Laminated structure of the PCB

| - Califficated attraction of the FCO | | | |
|--------------------------------------|-----------------------|-------------------|--|
| Structure | Thickness | Layer | |
| Silk | - | Şilk Top | |
| Soldermask | | Soldermask Top | |
| Copper | > 33 um | Top Layer | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | |
| Copper | 35 um (1 oz) | Ground Plane | |
| Core | 1.13 mm or 0.93 mm | _ | |
| Copper | 35 um (1 oż) | Power Plane | |
| Prepreg / Substrate | 0,06 ~ 0.2 mm | | |
| Copper | > 33 um | Bottom Layer | |
| Soldermask | | Soldermask Bottom | |
| Silk | - | Silk Botlom | |

GASTRON CO.,LTD.

GFM-400 MAIN PCB

| | Title | Title GROUND PLANE DIN | | |
|-----------|-----------------|------------------------|--------|------|
| | Part No. | Part No. 490A801-000 | | 01 |
| | Material | FR-4 / ENIG | Finish | |
| | Q¹ty | - | Scale | 1/1 |
| | Pro- jection | ₩□ | Units | mm |
| H.J.JOUNG | DWG. No. | | | Rev. |
| Approved | Ex-GE-25P00-9 | | | |

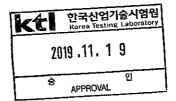


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For issued (PCB Rev1.0)

Description



22.07.2019

Date

S.M.BAE

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S.H.YI

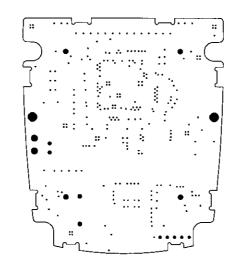
Checked

< PCB INFORMATION >

- PCB Malerial : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer : 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- ~ Laminated structure of the PCB

| Structure | Thickness | Layer |
|-------------------------|-----------------------|-------------------|
| Silk | - | Silk Top |
| Soldermask | - | Soldermask Top |
| Copper | > 33 um | Top Layer |
| Prepreg / Substrate | 0.06 0.2 mm | _ |
| Copper | 35 um (1 oz) | Ground Plane |
| Core | 1.13 mm or 0.93 mm | _ |
| Copper | 35 um (1 oz) | Power Plane |
| Prepreg / 0.06 ~ 0.2 mm | | |
| Copper | > 33 um | Bottom Layer |
| Soldermask | - | Soldermask Boltom |
| Silk | | Silk Bottom |

| | Model | GFM | -400 MAIN | PCB |
|-----------|-----------------|--|---|---|
| | Title | POWER | PLANE DIM | MENSION |
| | Part No. | 4: | 90A801-00 | 01 |
| | Material | FR-4 / ENIG | Finish | |
| | Q'ty | | Scale | 1/1 |
| | Pro- jection | ⊕□ | Units | mm |
| H.J.JOUNG | DWG. No. | | | Rev. |
| Approved | Ex- | GE-25P00- | 10 | |
| | | Title Part No. Material Q'ty Projection H.J.JOUNG DWG. No. | Title POWER Part No. 49 Material FR-4 / ENIG Q'ty - Projection DWG. No. | Title POWER PLANE DIM Part No. 490A801-00 Material FR-4 / ENIG Finish Q'ty - Scale Pro- jection Units H.J.JOUNG DWG, No. |



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For issued (PCB Rev1.0) 22,07,2019

Date

Description



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APPROVAL

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Designed

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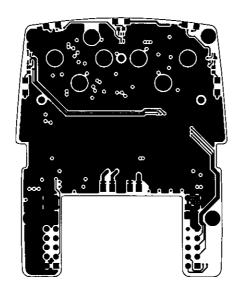
Checked

< PCB INFORMATION >

- PCB Material : FR-4
- PCB Thickness : 1.6 mm PCB Layer: 4 Layers
- Conductor material: Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminaled structure of the PCR

| - Laminaled Structure of the PCB | | | |
|----------------------------------|-----------------------|-------------------|--|
| Structure | Thickness | Layer | |
| Silk | → | Silk Top | |
| Soldermask | | Soldermask Top | |
| Copper | > 33 um | Top Layer | |
| Prepreg / Substrate | 0.06 ~ 0,2 mm | - | |
| Copper | 35 um (1 oz) | Ground Plane | |
| Core | 1,13 mm or 0,93 mm | - | |
| Copper | 35 um (1 oz) | Power Plane | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | |
| Copper | > 33 um | Bottom Layer | |
| Soldermask | - | Soldermask Bottom | |
| Şiik | - | Silk Bottom | |

| | | Model | GFM | -400 MAIN | PCB | |
|--|-----------|-----------------|--------------|-----------|------|--|
| | | Title | DRILL | | | |
| | | Part No. | 490A801-0001 | | | |
| | | Material | FR-4 / ENIG | Finish | | |
| | | Q'ty | _ | Scale | 1/1 | |
| | | Pro- jection | \Phi | Units | mm | |
| | н.ז.лопис | DWG. No. | | | Rev. | |
| | Approved | Ex- | GE-25P00- | 1.1 | 🙆 | |



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Rev.

For issued (PCB Rev1.0)

Description



20.09.2019

S.M.BAE

Designed

S.H.YI

Checked

PCB Material : FR-4 PCB Thickness : 1.6 mm

- PCB Layer : 4 Layers

- PCB Layer : 4 Layers

- Conductor material : Copper

- Minimum conducting track thickness: 33.5 um

- Minimum track width: 0,2 mm

- CTI: 100 or Greater

Model

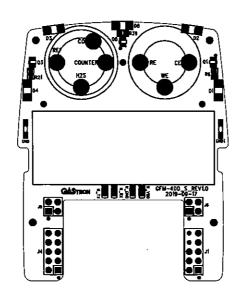
- Laminated structure of the PCB

| Caminated structore of the FOD | | | |
|--------------------------------|-----------------------|-------------------|--|
| Structure | Thickness | Layer | |
| Silk | - | Silk Top | |
| Soldermask | - | Soldermask Top | |
| Copper | > 33 um | Top Layer | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | |
| Copper | 35 um (1 oz) | Ground Plane | |
| Core | 1.13 mm or 0.93 mm | - | |
| Copper | 35 um (1 oz) | Power Plane | |
| Prepreg / 0,06 ~ 0.2 mm | | - | |
| Copper | > 33 um | Bottom Layer | |
| Soldermask | • | Soldermask Bottom | |
| Silk | | Silk Bottom | |

GASTRON CO.,LTD.

GFM-400 SENSOR PCB

| | Title TOP LAYER | | 1 | | |
|---|-----------------|-----------------|-------------|--------|------|
| | | Part No. | 490A802-00 | | 01 |
| | | Material | FR-4 / ENIG | Finish | |
| 1 | | Q'ty | - | Scale | 1/1 |
| | | Pro- jection | ⊕ | Units | mm |
| | H.J.JOUNG | DWG. No. | | | Rev. |
| | Approved | Ex- | -GE-25P01-1 | | |



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<u>A</u>

For issued (PCB Rev1.0) 20.09.2019

Date

Description



S,M,BAE

Designed

S.H.YI

Checked

PCB Material : FR-4

PCB Thickness : 1,6 mm

PCB Layer: 4 Layers

- Conductor material : Copper

- Minimum conducting track thickness: 33,5 um

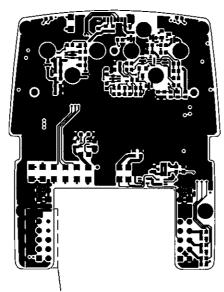
- Minimum track width: 0.2 mm

- CTI: 100 or Greater

- Laminated structure of the PCB

| Laminated structure of the FOB | | | |
|--------------------------------|-----------------------|-------------------|--|
| Structure | Thickness | Layer | |
| Silk | | Şilk Top | |
| Soldermask | - | Soldermask Top | |
| Copper | > 33 um | Top Layer | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | |
| Copper | 35 um (1 oz) | Ground Plane | |
| Core | 1,13 mm or 0.93 mm | - | |
| Copper | 35 um (1 oz) | Power Plane | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | |
| Copper | > 33 um | Bottom Layer | |
| Soldermask | _ | Soldermask Bottom | |
| Silk | - | Silk Botlom | |

| Model | | GFM-400 SENSOR PCB | | | |
|-------|-----------|--|--------------|--------|------|
| Title | | SILK SCREEN TOP + SOLDER MASK TOP LAYERS | | | |
| Pa | | Part No. | 490A802-0001 | | |
| | | Material | FR~4 / ENIG | Finish | |
| | | Q'ty | - | Scale | 1/1 |
| | | Pro- jection | ⊕ | Units | mm |
| | H.J.JOUNG | DWG. No. | | | Rev. |
| | Approved | Ex- | -GE-25P01- | | |



< Coating area on the bottom layer for the SENSOR PCB > This area should be coated at least once with coating material "PAS-7800" by using a brush after soldering.

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SCHEDULE DRAWING

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S.H.YI

Checked

Designed

For issued (PCB Rev1.0) 20.09.2019 S.M.BAE

Description

PCB Material : FR-4 PCB Thickness : 1.6 mm

PCB Layer: 4 Layers

Conductor material : Copper

Minimum conducting track thickness: 33,5 um

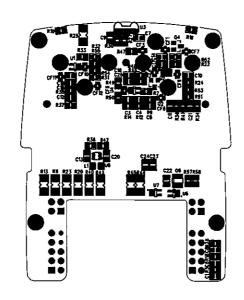
Minimum track width: 0,2 mm

- CTI: 100 or Greater ·

- Laminated structure of the PCB

| Carinnated Strocture of the Pop | | | |
|---------------------------------|-----------------------|-------------------|--|
| Structure | Thickness | Layer | |
| Silk | | Silk Top | |
| Soldermask | - | Soldermask Top | |
| Copper | > 33 um | Top Layer | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | | |
| Copper | 35 um (1 oz) | Ground Plane | |
| Core | 1.13 mm or 0,93 mm | - | |
| Copper | 35 um (1 oz) | Power Plane | |
| Prepreg / Substrate | 0,06 ~ 0,2 mm | _ | |
| Copper | > 33 um | Bottom Layer | |
| Soldermask | | Soldermask Boltom | |
| Silk | - | Silk Bottom | |

| | | Model | Model GFM-400 SENSOF | | R PCB |
|-------|----------------------|-----------------|----------------------|--------|-------|
| Title | | BOTTOM LAYER | | | |
| | Part No. 490A802-000 | | 01 | | |
| | | Material | FR-4 / ENIG | Finish | |
| | | Q'ty | | Scale | 1/1 |
| | | Pro- jection | ⊕ □ | Units | mm |
| | H.J.JOUNG | DWG. No. | | | Rev. |
| | Approved | Ex- | -GE-25P01-3 | | |



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Rev.

For issued (PCB Rev1.0) 20,09,2019

Description



S.M.BAE

Designed

S.H.YI

Checked

- PCB Material : FR-4 - PCB Thickness : 1,6 mm

- PCB Layer : 4 Layers

- Conductor material : Copper

Minimum conducting track thickness: 33.5 um

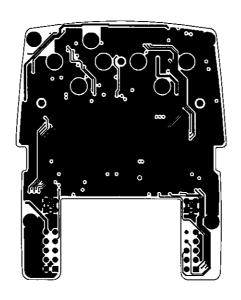
- Minimum track width: 0,2 mm

- CTI: 100 or Greater

- Laminated structure of the PCB

| | Laminated Structure of the Fob | | | | |
|----|--|--|------------------|--|--|
| IΕ | Structure | Thickness | Layer | | |
| IΓ | SIIk | - | Silk Top | | |
| П | Soldermask | , | Soldermask Top | | |
| ۱C | Copper | > 33 um | Top Layer | | |
| | Prepreg / Substrate | 0.06 ~ 0.2 mm | ı | | |
| ΙП | Copper | 35 um (1 az) | Ground Plane | | |
| ır | | 1.13 mm or | | | |
| П | Core | 0,93 mm | - | | |
| lE | Core | | - Power Plane | | |
| | | 0,93 mm | Power Plane | | |
| | Copper Prepreg / Substrate Copper | 0,93 mm 35 um (1 oz) | Bottom Layer | | |
| | Copper Prepreg / Substrate | 0,93 mm 35 um (1 oz) 0,06 ~ 0,2 mm | - | | |

| | Model GFM-400 SENS | | 400 SENSO | R PCB | |
|-------|-----------------------|--|-------------|--------|------|
| Title | | SILK SCREEN BOTTOM + SOLDER MASK BOTTOM LAYERS | | | |
| | Part No. 490A802-0001 | | 01 | | |
| | | Material | FR-4 / ENIG | Finish | |
| | | Q'ty | - | Scale | 1/1 |
| | - | Pro- jection | ⊕母 | Units | mm |
| | H.J.JOUNG | DWG. No. | ** | | Rev. |
| | Approved | Ëx- | -GE-25P01-4 | | |



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Rev.

For issued (PCB Rev1.0) 20,09,2019

Date

Description



S.M.BAE

Designed

S.H.YI

Checked

PCB Material : FR-4

- PCB Thickness : 1.6 mm

- PCB Layer: 4 Layers

- Conductor material : Copper

- Minimum conducting track thickness: 33,5 um

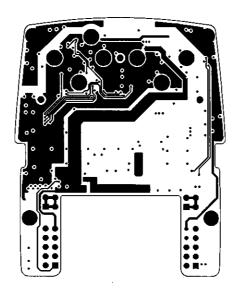
- Minimum track width: 0.2 mm

- CTI: 100 or Greater

- Laminated structure of the PCB

| Structure | Thickness | Layer |
|------------------------|-----------------------|-------------------|
| Silk | - | Silk Top |
| Soldermask | · - | Soldermask Top |
| Copper | > 33 um | Top Layer |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - |
| Copper | 35 um (1 oz) | Ground Plane |
| Core | 1,13 mm or 0.93 mm | _ |
| Copper | 35 um (1 oz) | Power Plane |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | |
| Copper | > 33 nm | Bottom Layer |
| Soldermask | | Soldermask Bottom |
| Silk | - | Slik Boltom |

| Model | | GFM-400 SENSOR PCB | | | |
|-------|-----------|--------------------|--------------|-----------|------|
| Tit | | Title | GF | ROUND PLA | NE |
| | | Part No. | 490A802-0001 | | |
| | | Material | FR-4 / ENIG | Finish | |
| | | Q'ty | - | Scale | 1/1 |
| | | Pro- jection | ⊕□ | Units | mm |
| | H.J.JOUNG | DWG. No. | | | Rev. |
| | Approved | Ex- | -GE-25P01-5 | | |



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> > For issued (PCB Rev1.0) 20,09,2019

Description

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S.M.BAE

Designed

S.H.YI

Checked

Approved

PCB Material : FR-4

PCB Thickness : 1.6 mm

PCB Layer: 4 Layers

Conductor material : Copper

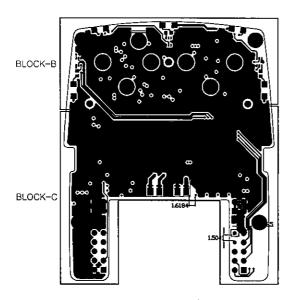
Minimum conducting track thickness: 33.5 um

Minimum track width: 0.2 mm

- CTI: 100 or Greater

| _ | - Laminated structure of the PCB | | | | |
|-----|----------------------------------|-----------------------|-------------------|--|--|
| ĺ | Structure | Thickness | Layer | | |
| 1 | Silk | → | Silk Top | | |
| ı | Soldermask | | Soldermask Top | | |
| 1 | Copper | > 33 um | Top Layer | | |
| | Prepreg / Substrate | 0,06 ~ 0,2 mm | ~ | | |
| 1 | Copper | 35 um (1 oz) | Ground Plane | | |
| | Core | 1,13 mm or 0.93 mm | - | | |
| 1 | Copper | 35 um (1 oz) | Power Plane | | |
| | Prepreg / Substrate | 0.06 0.2 mm | _ | | |
| ı | Copper | > 33 um | Bottom Layer | | |
| ı | Soldermask | - | Soldermask Bottom | | |
| . 1 | SIIL | _ | Silk Bottom | | |

| | | GASTRON CO.,LTD. | | | |
|---|-----------|------------------|--------------------|-----------|------|
| Ţ | | Model | GFM-400 SENSOR PCB | | |
| | | Title | POWER PLANE | | √E |
| | | Part No. | 49 | 90A802-00 | 01 |
| | | Material | FR~4 / ENIG | Finish | |
| | | Q'ty | - | Scale | 1/1 |
| | | Pro- jection | ♦ □ | Units | mm |
| | H.J.JOUNG | DWG. No. | | | Rev. |
| | Approved | Ex- | Ex-GE-25P01-6 | | |



BLOCK-B BLOCK-C ☐ BLOCK-D

SCHEDULE DRAWING

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Rev.

For issued (PC8 Rev1.0) 20.09.2019

Description



S,M,BAE

Designed

S.H.YI

Checked

- PCB Material : FR-4 - PCB Thickness : 1.6 mm

- PCB Layer: 4 Layers

- Conductor material : Copper

Minimum conducting track thickness: 33,5 um

- Minimum track width: 0.2 mm

- CTI: 100 or Greater

Model

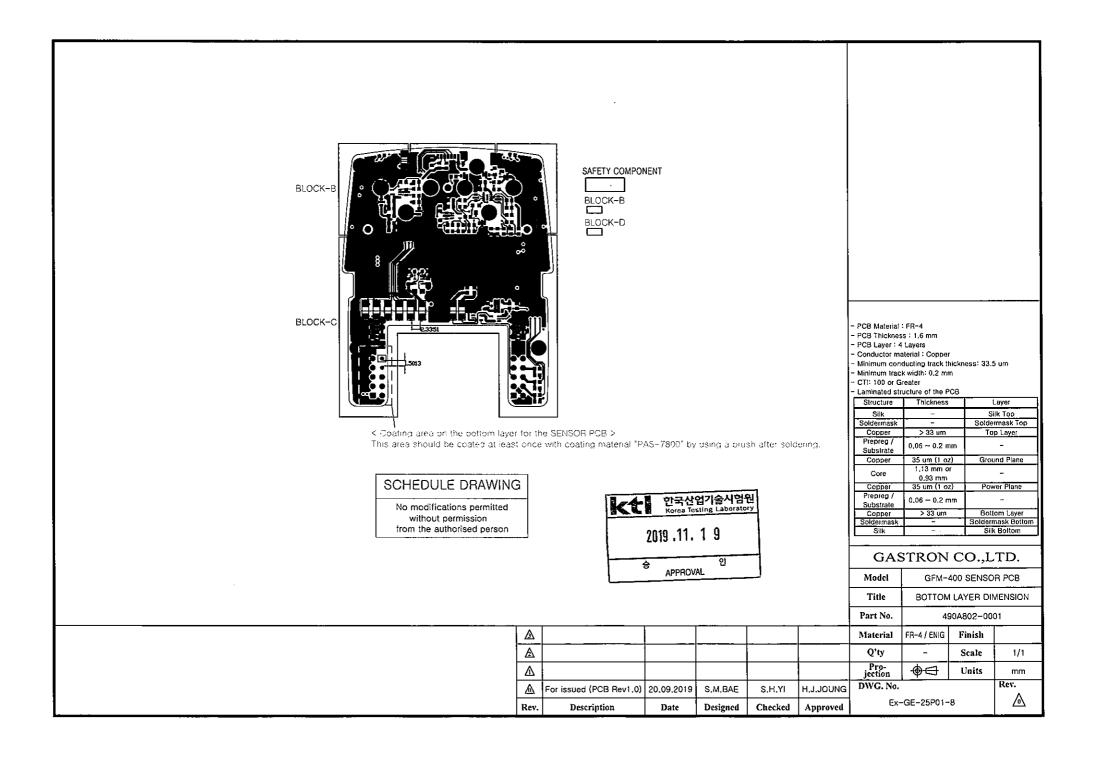
- Laminaled structure of the PCB

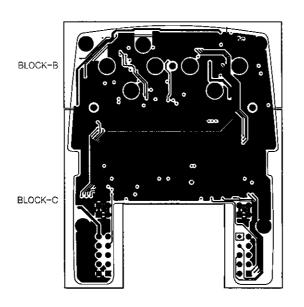
| | iciare of the rob | |
|------------------------|-----------------------|-------------------|
| Structure | Thickness | Layer |
| Silk | - | Silk Top |
| Soldermask | - | Soldermask Top |
| Copper | > 33 um | Top Layer |
| Prepreg / Substrate | 0.06 ~ 0,2 mm | _ |
| Copper | 35 um (1 az) | Ground Plane |
| Core | 1.13 mm or 0,93 mm | - |
| Copper | 35 um (1 oz) | Power Plane |
| Prepreg / Substrate | 0,06 ~ 0,2 mm | |
| Copper | > 33 um | Bottom Layer |
| Soldermask | - | Soldermask Bottom |
| Silk | - | Silk Bottom |

GASTRON CO.,LTD.

GFM~400 SENSOR PCB

| | Title | TOP L | AYER DIME | NOISM |
|-----------|-----------------|-------------|-----------|-------|
| | Part No. | 49 | 90A802-00 | 01 |
| | Material | FR-4 / ENIG | Finish | |
| | Q'ty | - | Scale | 1/1 |
| | Pro- jection | ⊕ | Units | mm |
| н.ј.јоџид | DWG. No. | | | Rev. |
| Approved | Ex- | -GE-25P01- | -7 | 🙆 |





BLOCK-B BLOCK-D

SCHEDULE DRAWING

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Rev.

For issued (PCB Rev1.0) 20.09.2019

Date

Description



S,M.BAE

Designed

S,H.YI

Checked

Approved

- PCB Malerial : FR-4

- PCB Thickness : 1,6 mm

- PCB Layer : 4 Layers

- Conductor material : Copper

- Minimum conducting track thickness: 33.5 um

- Minimum track width: 0,2 mm

- CTI: 100 or Greater

- Laminated structure of the PCB

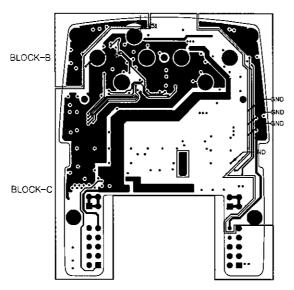
| Structure | Thickness | Layer | | | |
|------------------------|-----------------------|-------------------|--|--|--|
| Silk | - | Silk Top | | | |
| Soldermask | - | Soldermask Top | | | |
| Copper | > 33 um | Top Layer | | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | | |
| Copper | 35 um (1 oz) | Ground Plane | | | |
| Core | 1.13 mm or 0,93 mm | _ | | | |
| Copper | 35 um (1 oz) | Power Plane | | | |
| Prepreg / Substrate | 0,06 0,2 mm | - | | | |
| Copper | > 33 um | Bottom Layer | | | |
| Soldermask | - | Soldermask Bottom | | | |
| Silk | - | Silk Bottom | | | |

GASTRON CO.,LTD.

| | Model | Model GFM-400 SENS | | | | | | | |
|-----------|-----------------|--------------------|---------------------------------------|---------|--|--|--|--|--|
| | Title | GROUND | PLANE OI | MENSION | | | | | |
| | Part No. | 490A802-0001 | | | | | | | |
| | Material | FR-4 / ENIG | Finish | | | | | | |
| | Q'ty | 1 | Scale | 1/1 | | | | | |
| | Pro- jection | ⊕ ⊕ | Units | mm | | | | | |
| H.J.JOUNG | DWG. No. | | · · · · · · · · · · · · · · · · · · · | Rev. | | | | | |

Ex-GE-25P01-9

◬



BLOCK-D

SCHEDULE DRAWING

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2019 .11. 1 9

APPROVAL

- PCB Material : FR-4 - PCB Thickness : 1.6 mm

- PCB Layer : 4 Layers

- Conductor material : Copper

- Minimum conducting track thickness: 33,5 um

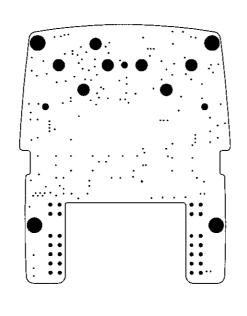
- Minimum track width: 0.2 mm

- CTI: 100 or Greater

| - Laminated structure of the POB | | | | | | | | |
|----------------------------------|-----------------------|-------------------|--|--|--|--|--|--|
| Structure | Thickness | Layer | | | | | | |
| Silk | - | Silk Top | | | | | | |
| Soldermask | - | Soldermask Top | | | | | | |
| Copper | > 33 um | Top Layer | | | | | | |
| Prepreg / Substrate | 0,06 ~ 0.2 mm | - | | | | | | |
| Copper | 35 um (1 az) | Ground Plane | | | | | | |
| Core | 1,13 mm or 0.93 mm | - | | | | | | |
| Copper | 35 um (1 oz) | Power Plane | | | | | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | | | | | |
| Copper | > 33 um | Bottom Layer | | | | | | |
| Soldermask | - | Soldermask Bollom | | | | | | |
| Silk | - | Silk Bottom | | | | | | |

| Model | GFM-400 SENSOR PCB | | | | | | | | |
|----------|-----------------------|--------|-----|--|--|--|--|--|--|
| Title | POWER PLANE DIMENSION | | | | | | | | |
| Part No. | 490A802-0001 | | | | | | | | |
| Material | FR-4 / ENIG | | | | | | | | |
| Q'ty | - | Scale | 1/1 | | | | | | |
| Pro- | 4 | WT 74. | | | | | | | |

| Δ | | | | , | | Material | FR-4 / ENIG | Finish | |
|------|-------------------------|------------|----------|---------|-----------|-------------------------|-------------|--------|------|
| Δ | | | | | | Q'ty | _ | Scale | 1/1 |
| Λ | | | | | | Pro- jection | ₩□ | Units | mm |
| ₩ | For issued (PCB Rev1.0) | 20,09,2019 | S,M.BAE | S.H.YI | н.Ј.Јоџис | DWG. No. | | | Rev. |
| Rev. | Description | Date | Designed | Checked | Approved | Ex-GE-25P01-10 <u>6</u> | | | |



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APPROVAL

S.M.BAE

Designed

S.H.YI

Checked

승

For issued (PCB Rev1.0) 20.09.2019

Description

- PCB Material : FR-4

- PCB Thickness : 1.6 mm

- PCB Layer: 4 Layers

- Conductor material : Copper

- Minimum conducting track thickness: 33,5 um

- Minimum track width: 0.2 mm

- CTI: 100 or Greater

- Laminated structure of the PCB

| Landinated Structure of the FOB | | | | | | | | |
|---------------------------------|-----------------------|-------------------|--|--|--|--|--|--|
| Structure | Thickness | Layer | | | | | | |
| Silk | - | Silk Top | | | | | | |
| Soldermask | | Soldermask Top | | | | | | |
| Copper | > 33 <u>um</u> | Top Layer | | | | | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | | | | | | | |
| Copper | 35 um (1 oz) | Ground Plane | | | | | | |
| Core | 1.13 mm ar 0.93 mm | - | | | | | | |
| Copper | 35 um (1 oz) | Power Plane | | | | | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | | | | | |
| Copper | > 33 um | Bottom Layer | | | | | | |
| Soldermask | - | Soldermask Bottom | | | | | | |
| Silk | - | Silk Battom | | | | | | |

| | OR PCB | | | | | | |
|-----------|-----------------|-------------|----------------|--|--|--|--|
| | DRILL | | | | | | |
| | 01 | | | | | | |
| | Material | FR-4 / ENIG | | | | | |
| | Q'ty | - | - Scale | | | | |
| | Pro- jection | ⊕□ | ⊕ Units | | | | |
| н.ј.јоџис | DWG. No. | Rev. | | | | | |
| Approved | Ex∼ | | | | | | |







Δ Δ Λ Δ

Rev.

For issued (PCB Rev0.3)

Description



SCHEDULE DRAWING

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19.07.2019

Date

S.M.BAE

Designed

S.H.YI

Checked

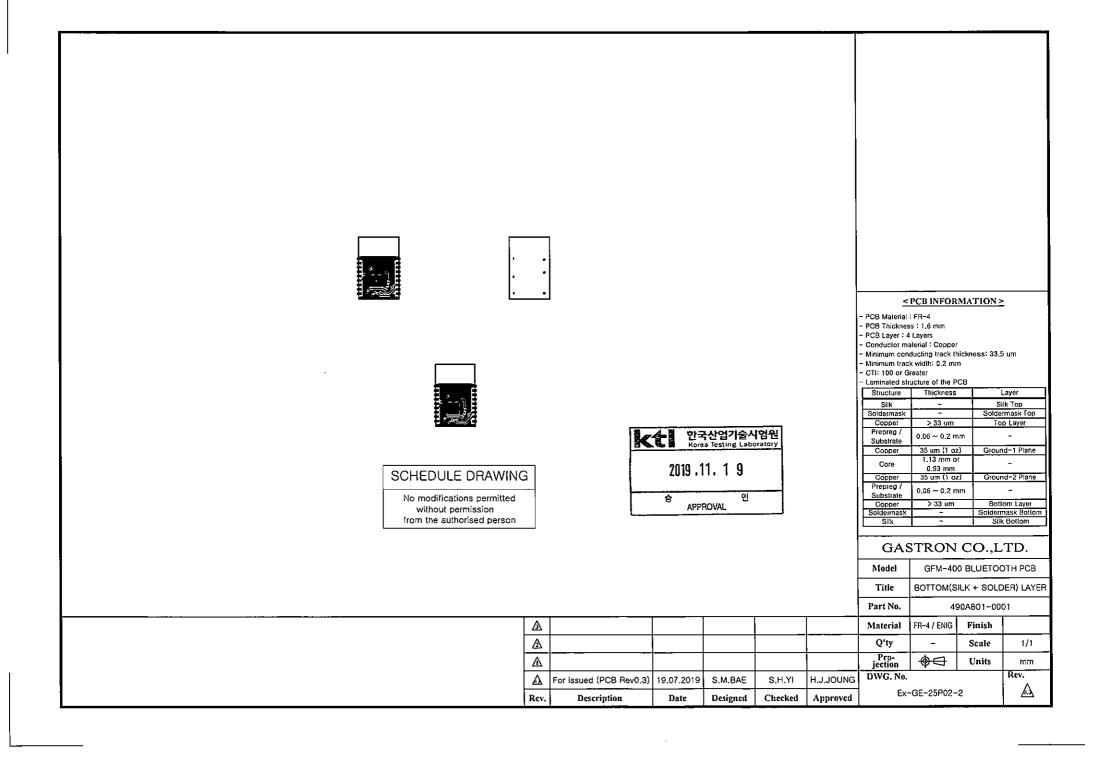
Approved

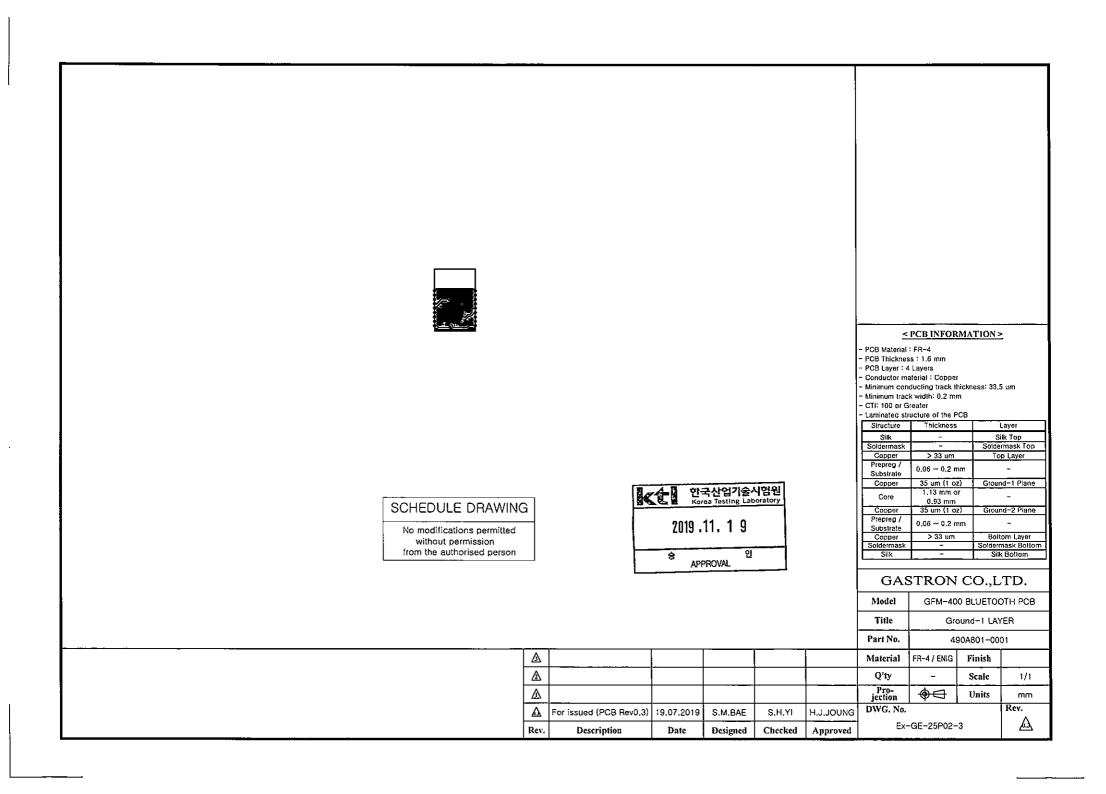
< PCB INFORMATION >

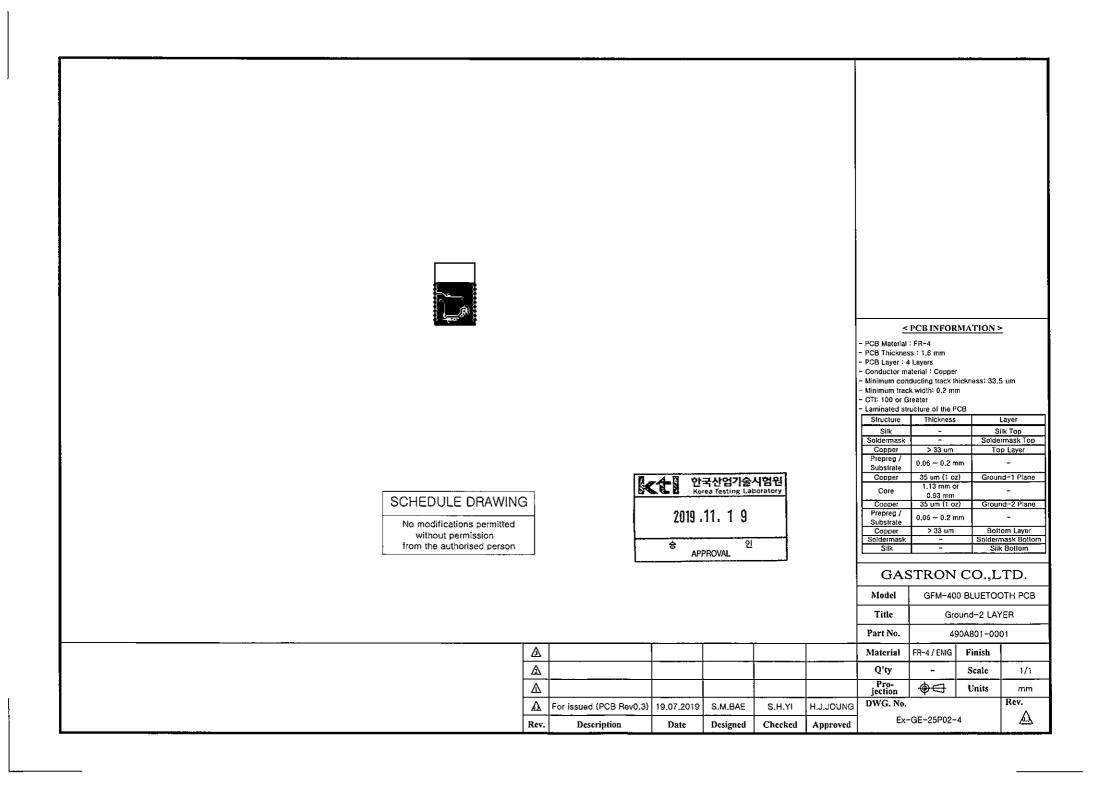
- PCB Material : FR-4
- PCB Thickness : 1,6 mm
- PCB Layer: 4 Layers
- Conductor material : Copper
- Minimum conducting track thickness: 33.5 um
- Minimum track width: 0.2 mm
- CTI: 100 or Greater
- Laminated structure of the PCB

| Laminated structure of the PCG | | | | | | | | |
|--------------------------------|-----------------------|-------------------|--|--|--|--|--|--|
| Structure | Thickness | Layer | | | | | | |
| Silk | - | Silk Top | | | | | | |
| Soldermask | - | Soldermask Top | | | | | | |
| Copper | > 33 um | Top Layer | | | | | | |
| Prepreg / Substrate | 0,06 ~ 0.2 mm | - | | | | | | |
| Copper | 35 um (1 oz) | Ground-1 Plane | | | | | | |
| Core | 1,13 mm or 0,93 mm | - | | | | | | |
| Copper | 35 um (1 oz) | Ground-2 Plane | | | | | | |
| Prepreg / Substrate | 0.06 ~ 0.2 mm | - | | | | | | |
| Copper | > 33 um | Bottom Layer | | | | | | |
| Soldermask | _ | Soldermask Bottom | | | | | | |
| Silk | - | Silk Bottom | | | | | | |

| | | Model | Model GFM-400 BLUETO | | | | | | | |
|---|-----------|-----------------|------------------------|--------------|----------|--|--|--|--|--|
| | | Title | TOP(SILE | C + SOLDER | R) LAYER | | | | | |
| | | Part No. | 49 | 490A801-0001 | | | | | | |
| | | Material | FR-4 / ENIG | Finish | | | | | | |
| | | Q'ty | - | Scale | 1/1 | | | | | |
| | | Pro- jection | Pro- jection Units | | | | | | | |
| | H.J.JOUNG | DWG. No. | Rev. | | | | | | | |
| 1 | Approved | Ex- | <u>6.3</u> | | | | | | | |







| | SCHEDULE DOCUMENT | | | | | Doc. NO. | Ex-GE-2 | 5B00 | | | |
|--|--|--------------------------------------|---------------------|--------------|-----------------------|----------------|---|------------------|-----------------------|--------------------|--------------------------|
| No modifications permitted without permission from the authorised person | | | | | Rev. No. Description | Description | Rev. Date | Prepared by | Reviewed by | Approved by | |
| | <u>•</u> | GFM-400_MAIN Part List | | | 1.0 | For issued | 2019.09.30 | S.M. BAE | S.H. Y) | H.J. JOUNG | |
| | without permission | 91141 -10 | | I C LIST | • | · | | | | | |
| l | from the authorised person | 1 | | | | | | | | | |
| NO. | Reference | Value (Available Range) | Value (Default) | Tolerance | Maximum Rating | Package | Manufacturer | Part Number | of Manufacturer | Ren | ı ıarks |
| _ 1 | BT1 | SB-AA11 | SB-AA11 | - | - | AA-size | VITZRO CELL | SE | B-AA11 | Component on which | intrinsic safety depends |
| 2 | R2,R5,R10 | 22Ω | 22Ω | 1% | ≥ 1 W | R2512 | WALSIN or ANY | WR25 | X22R0FTL | Component on which | ntrinsic safety depends |
| 3 | D1,D2 | BZT52C3V9 | BZT52C3V9 | 3.7 ~ 4.1 V | ≥ 0.3 W | SOD123 | GAOMI FEI SHI LONG DA ELECTRONICS Co.,Ltd or Diodes Incorporated | BZ | 52C3V9 | Component on which | intrinsic safety depends |
| 4 | R1 | 1kΩ | 1kΩ | 1% | ≥ 0.25 W | R1206 | WALSIN or ANY | WR1 | X1001FTL | Component on which | intrinsic safety depends |
| 5 | R8 | 330Ω | 330Ω | 1% | ≥ 0.25 W | R1206 | WALSIN or ANY | WR1: | 2X3300FTL | Component on which | ntrinsic safety depends |
| 6 | R4,R7 | 100kΩ | 100kΩ | 1% | ≥ 0.25 W | R1206 | WALSIN or ANY | WR1 | X1003FTL | Component on which | intrinsic safety depends |
| 7 | BZ1 | CBE14408P-L | CBE14408P-L | ±30% | 25 V | - | Daeyoung Electric Co., LTD. | CBE | 1440BP-L | i | • |
| 8 | M1 | Z6SH180060711 | Z6SH1B0060711 | • | 0.105A | - | JINLONG MACHINERY & ELECTRONICS CO., LTD. | Z6SH | 180060711 | İ | • |
| 9 | CN1 | 5267-02A | 5267-02A | - | - | - | Molex | 002 | 2035025 | | • |
| 10 | J1,J2 | D\$1023-15_10pin | DS1023-15_10pin | • | - | - | CONNFLY ELECTRONIC CO., LTD. | DS | 1023-15 | | • |
| 11 | J5,16 | DS1023-15_4pin | DS1023-15_4pin | • | - | - | CONNFLY ELECTRONIC CO., LTD. | DS | 1023-15 | | • |
| 12 | J3 | 05002HR-05N2 / NC | 05002HR-05N2 | • | - | - | YEONHO ELECTRONICS CO., LTD. | 0500 | O5002HR-05N2 - | | • |
| 13 | LCD1 | Segment LCD | KJCEL01023FS6-03_A | - | - | | KJC Display Corporation | KJCEL00 | 933FR6-03_A | | |
| 14 | LCD1 | LCD Rubber connector | KJCER00120-05_A | - | - | | KJC Display Corporation | KJCER | 0010S-03_A | | |
| 15 | SW1 | 1101NS(4.3mm) | 1101NS(4.3mm) | - | 12V / 0.05A | | ECHO TECH or ANY | 1101 | NS(4.3mm) | | |
| 16 | C1,C2,C15,C23,C25 | . 1uF | 1uF | ±10% | 50 V | C0603 | SAMSUNG or ANY | CL10A1 | 05KBBNNNC | | - |
| 17 | C3,C6,C7,C8,C9,C10,C11,C12,C14, C16,C17,C18,C19,C22,C26 | 0.1uF | 0.1uF | ±10% | 50 V | C0603 | MULATA or ANY | GRM188R71H104KAS | 930 / CL10B104KB8NNNC | | - |
| 18 | C4 | 2.2uF | 2.2uF | ±10% | 50 V | C0603 | MURATA or ANY | GRM188F | 61H225KE11D | | - |
| 19 | C5 | 10uF | 10uF | ±20% | 10 V | CT_R | VISHAY or ANY | TAJP1 | 06M010RNJ | | - |
| 20 | C13 | 1uF | 1uF | ±20% | 16 V | CT_P | VISHAY or ANY | TAJR1 | 05M016RNJ | | - |
| 21 | C20,C21 | 6pF | 6pF | ±0.25pF | 50 V | C0603 | SAMSUNG or ANY | CL10C0 | 60CB8NNNC | | - |
| 22 | C24 | 10nF | 10nF | ±10% | 50 V | C0603 | SAMSUNG or ANY | - | 03KB8NNNC | | - |
| 23 | D3,D4 | LS-SF3020DBW71-C6C5 | LS-SF3020DBW71-C6C5 | - | 0.1 A | | Daeyoung Electric Co., LTD. (Zhejiang Guyue LongShan Electronic Technology Development Co., LTD.) | | 0D8W71-C6C5 | | - |
| 24 | D5 | B0530W-7-F / MBR0530 | B0530W-7-F | - | 0.5A | SOD123 | Diodes Incorporated or ON Semiconductor or Micro Commercial Components | | 30W-7-F | 1 | - |
| 25 | Q1,Q2 | DDC123JU | DDC123JU | - | 50 V / 0.1 A / 0.2 W | SOT363 | Diodes Incorporated | | C123JU | <u> </u> | - |
| 26 | Q3 | NTGS3441 / NVGS3441 | NTGS3441 | | 20 V / 1.65 A / 0.5 W | TSOP-6 | ON Semiconductor | N1 | G\$3441 | | - |
| 27 | R3,R6 | min 100Ω | 820Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | 5X8200FTL | 1 | - |
| 28 | R9,R12,R16 | 1ΜΩ οτ 10ΜΩ | 10ΜΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | | SX1005FTL | | - |
| 29 | R11 | 330Ω | 330Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | 5X3300FTL | 1 | - |
| 30 | R15 | 10kΩ | 10kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | | 5X1002FTL | | - |
| 31 | U1 | STM32L443VCT6 | STM32L443VCT6 | • | 4 V / 1.4 A / 0.444 W | LQFP100(14x14) | STMicroelectronics | | 2L443VCT6 | | |
| 32 | U2 | TPS7A0518PDBV | TPS7A0518PDBV | | 6 V / 0.65 A | SOT23_5 | Texas Instruments | | AOS18PDBV | | - |
| 33 | U3 | NJU72501MJE | NJU72501MJE | - | 4 V / 1.3 W | EQFN12-3X3 | New Japan Radio Co., LTD. | | 72501MJE | | _ |
| 34 | U4 | CC2640YJ Module | CC2640YJ Module | | - | - | YJ SYSTEMS Co., LTD. | | 2640YJ | | - |
| 35 | U5 | AT25DF512C-MAHN-T / AT25DF011-MAHN-T | AT25DF512C-MAHN-T | - | 4.1 V | UDFN8_2X3 | Adesta Technologies | | 12C-MAHN-T | | |
| 36 | Y1 | NX3215SE STD-MUA-19 | NX3215SE STD-MUA-19 | | | NX3215SE | NIHON DEMPA KOGYO CO., LTD. | | E STD-MUA-19 | | |



| | SCHEDULE DOCUMENT | | | | <u> </u> | Doc. NO. | Ex-GE-; | 25801 | | | · |
|----------|-------------------------------------|---|--|----------------|----------------|--------------|---|----------------|----------------------|--|--|
| | | 7 | | | | Rev. No. | Description | Rev. Date | Prepared by | Reviewed by | Approved by |
| | No modifications permitted | GEM 400 | SENSOR Pa | set li | -4 | 1.0 | For issued | 2019.08.14 | S.M. BAE | S.H., YI | H.J. JOUNG |
| | without permission | GEIVI-400 | -SENSON P | ait Li | Si | | | | | | |
| | from the authorised person | | | | | | | | | i | - |
| | from the authorised person | | | | | | | | | i | |
| NO. | Reference | Value (Available Range) | Value (Default) | Tolerance | Maximum Rating | Package | Manufacturer | Part Number of | of Manufacturer | Rem | narks |
| 1 | R25 | 1kΩ | 1kΩ | 1% | ≥ 0.25 W | R1206 | WALSIN or ANY | | (1001FTL | Component on which i | |
| 2 | R43 | 51Ω | 51Ω | 1% | ≥ 0.25 W | R1206 | WALSIN or ANY | | (51ROFTL | Component on which i | |
| 3 | R44,R45 | 120Ω | 120Ω | 1% | ≥ 0.25 W | R1206 | WALSIN OF ANY | | (1200FTL | Component on which i | |
| 4 | R8,R13,R20,R23,R40 | 100kΩ | 100kΩ | 1% | ≥ 0.25 W | R1206 | WALSIN OF ANY | | (1003FTL | Component on which i | |
| 5 | C14,C16,C18 | 1uF | 1uF | ±10% | | | · · · · · · · · · · · · · · · · · · · | | SKB8NNNC | Component on which i | intrinsic salety depends |
| 6 | C7,C9,C22 | 0.1uF | 0.1uF | _! | 50 V | C0603 | SAMSUNG or ANY | | D / CL10B104KB8NNNC | | <u> </u> |
| 7 | | | | ±10% | 50 V | 1 | MULATA or ANY | | V221MV4T | | |
| 8 | CF4,CF6,CF9,CF10 CF1,CF3,CF5,CF7 | 101X14W series | 101X14W221MV4T (220pF) | ±20% | 50 V | C0603 | Johanson Dielectrics, Inc. | | / YFF18SC1H470MT0H0N | | - |
| 9 | CF1,CF3,CF3,CF7 | YFF18SC1H series YFF18SC1H series | YFF18SC1H470MT0H0N YFF18SC1H223MT0H0N | ±20% | 50 V 50 V | C0603 | TDK Corporation. | | / YFF18SC1H470MT0H0N | | <u>. </u> |
| 10 | C3 | 1nF | | | 50 V | C0603 | TDK Corporation. | | L10B102KB8NNNC | | - |
| 11 | C1,C5,C6,C8,C10 | | 1nF | ±10% | | 1 | SAMSUNG or ANY | | | ļ | |
| | | 10pF | 10pF | ±5% | 50 V | C0603 | SAMSUNG or ANY | | 100JBNC | | • |
| 12 | C13,C20 | 10uF | 10uF | ±20% | 16V | C0603 | SAMSUNG or ANY | _ | KO8NQNC | | - |
| 13 | C17,C19,C25 | 22nF | 22nF | ±10% | 50 V | C0603 | SAMSUNG OF ANY | | 3KB8NNNC | | - |
| 14 | C4,C11,C12 | 10nF | 10nF | ±10% | 50 V | C0603 | SAMSUNG or ANY | CL10B10 | 3KB8NNNC | | |
| 15 | <u>Q1</u> | NC | NC | <u> </u> | • | · · · · · · | • | | • | | - |
| 16 | C23,C24 | 68pF | 68pF | ±5% | 50 V | C0603 | SAMSUNG OF ANY | | 0JB8NNNC | | - |
| _17 | D1,D2,D3,D4 | LS-SF3020UHR34 | LS-SF3020UHR34 | • | • | - | Daeyoung Electric Co., Ltd. (Zhejiang Guyue LongShan Electronic Technology Development Co., Ltd.) | LS-SF30 | 220UHR34 | | - |
| _ 18 | D5 | LS-SF3020DNB74 | LS-SF3020DNB74 | • | • | • | Daeyoung Electric Co., Ltd. (Zhejiang Guyue LongShan Electronic Technology Development Co., Ltd.) | LS-SF30 | 20DNB74 | | - |
| . 19 | GND,GND1 | \$1721-46R | \$1721-46R | • | | - | HARWIN | \$172 | 21-46R | | - |
| 20 | N_VDD,N_TX,N_RX,N_GND | \$7271-45R | \$7271-45R | • | | | HARWIN | \$727 | 71-45R | | - |
| 21 | N_VDD,N_TX,N_RX,N_GND | MIPEX-04-1-02-3.1(Option code: MM2.5), MIPEX-04-1-22-3.1(Option code: MM100), MIPEX-04-1-62-3.1(Option code: MP1.5), MIPEX-04-1-72-3.1(Option code: MP2.5), MIPEX-04-2-62-3.1(Option code: PP1.5), MIPEX-04-2-72-3.1(Option code: PP2.5) | MIPEX-04-1-12-3.1 | | | | Optosense LLC | MIPEX-0 | 4-1-12-3.1 | | - |
| 22 | J1,J4 | DS1021_10pin | D\$1021_10pin | | - | - | CONNFLY ELECTRONIC CO, LTD | DS | 1021 | | • |
| 23 | 15,16 | DS1021_4pin | D\$1021_4pin | - | - | - | CONNFLY ELECTRONIC CO,LTD | | 1021 | | • |
| 24 | Li | 2.2uH | 2.2uH | ±10% | - | L0805 | Sunlord | | 2Q2R2KTF | | |
| 25 | Q1,Q3,Q5 | DDC123JU | DDC123JU | 11070 | | SOT363 | Diodes Incorporated | | 123/U | | |
| 26 | Q2,Q4 | SST177 | \$\$T177 | + | | SOT-23 | VISHAY or ANY | | T177 | <u> </u> | |
| 27 | Q6 | NTGS3441 | NTG\$3441 | + : | | TSOP-6 | | | i\$3441 | ļ | • |
| 28 | R41 | 0Ω | 0Ω | ±1% | 0.1 W | R0603 | ON Semiconductor | | X000PTL | | |
| | | | | | | | WALSIN OF ANY | | | | |
| 29 | R3,R12,R14,R18,R28 | 10kΩ | 10kΩ | ±1% | 0.1 W | R0603 | WALSIN OF ANY | | (1002FTL | ļ | - |
| 30 | R30 | 47Ω | 47Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | (47R0FTL | | - |
| 31 | R6,R10,R16,R21,R39 | min 100Ω | 820Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | KB200FTL | ļ | <u> </u> |
| 32 | R7,R22 | 10Ω | 10Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | (10R0FTL | | - |
| 33 | R27,R42,R57,R58 | 1MΩ or 10MΩ | 10ΜΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | | K1005FTL | · | - |
| 34 | R32 | 330Ω | 330Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | K3300FTL | | • |
| 35 | R31 | 100Ω | 100Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | K1000FTL | | - |
| 36 | R9,R52 | 1kΩ ~ 100kΩ | 16kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | | C1602FTL | | - |
| 37 | R24 | 1kΩ ~ 100kΩ | 59kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | WR06) | (5902FTL | | - |
| 38 | R33,R36 | 1kΩ ~ 100kΩ | 30kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | WR06X | (3002FTL | · · · · · · · · · · · · · · · · · · · | - |
| 39 | R34 | 1kΩ ~ 10MΩ | 120kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | WR062 | K1203FTL | | - |
| 40 | R35 | 1kΩ ~ 10MΩ | 130kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | WR06) | K1303FTL | | - |
| 41 | R37 | 1kΩ ~ 10MΩ | 7.15kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | WR06 | X7151FTL | <u> </u> | - |
| 42 | R38 | 133kΩ | 133kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | | X1333FTL | 1 | - |
| 43 | R46,R48,R49,R50,R51,R53,R54,R55 | 0Ω ~ 1kΩ | 22Ω | ±1% | 0.1 W | R0603 | WALSIN or ANY | | K22R0FTL | 1 | = |
| 44 | R47 | 0Ω ~ 10ΜΩ | 1kΩ | ±1% | 0.1 W | R0603 | WALSIN or ANY | | X1001FTL | ' | = |
| 45 | CE, WE, CO, H2S, REF, COUNTER | ds15s40 | ds15s40 | | - | - | Young Jin Enterprise or ANY | | 15s40 | | - |
| 46 | RE | NC NC | NC NC | | | - | Today in the price of Airi | | • | | - |
| 47 | CE, WE | O2 Sensor | O2 Sensor | | - | | DD-Scientific or ANY | | 40X | - | <u>. </u> |
| 48 | CO, H2S, REF, COUNTER | CO / H2S Dual Toxic Sensor | CO / H2S Dual Toxic Sensor | | - | - | DD-scientific or ANY | | +4DT | | <u>. </u> |
| 49 | | | | | | SC70-5 | | | 111ICT | | |
| | U1,U4 | TSU111 | TSU111 | - | • | | STMicroelectronics | | | | <u>. </u> |
| 50 | U2 | TSU112 | TSU112 | <u> </u> | • | DFN8_2X2_0P5 | STMicroelectronics | | 12IQ2T | - | • |
| 51 | U3 | TFBS4650 | TFBS4650 | <u> </u> | • | TFBS4650 | Vishay | | \$4650 | | • |
| 52 | US | MAX17220 | MAX17220 | <u> </u> | <u> </u> | uDFN | Maxim | | X17220 | + | <u>•</u> |
| 53 54 | U6 | SN74AUP1G07 | SN74AUP1G07 | • | • | \$C70-5 | Texas Instruments | | AUP1G07 | | • |
| | U7 | SN74AUP1T50 | SN74AUP1T50 | | 1 - | \$C70-5 | Texas Instruments | I SN74 | AUP1T50 | 1 | |

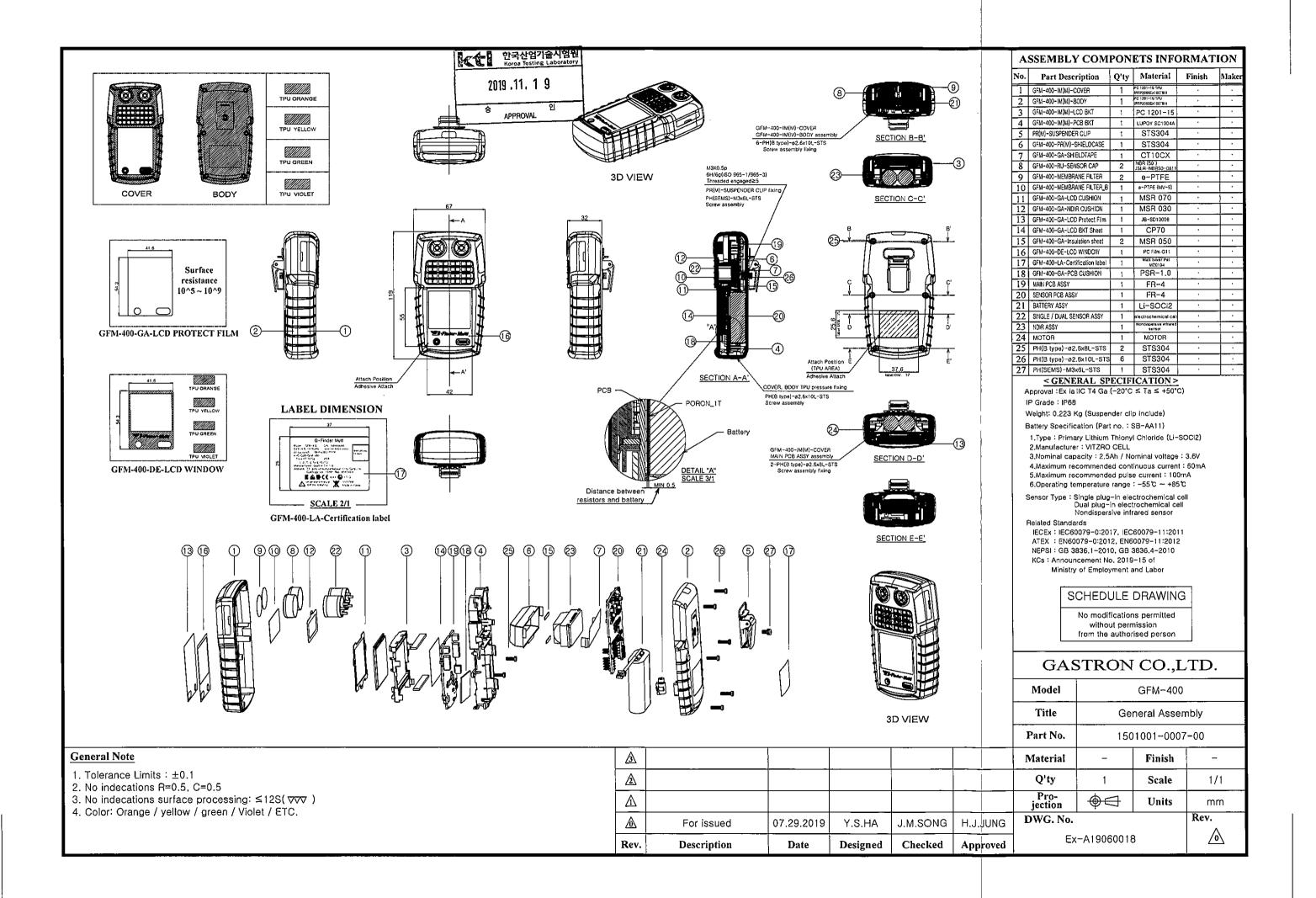


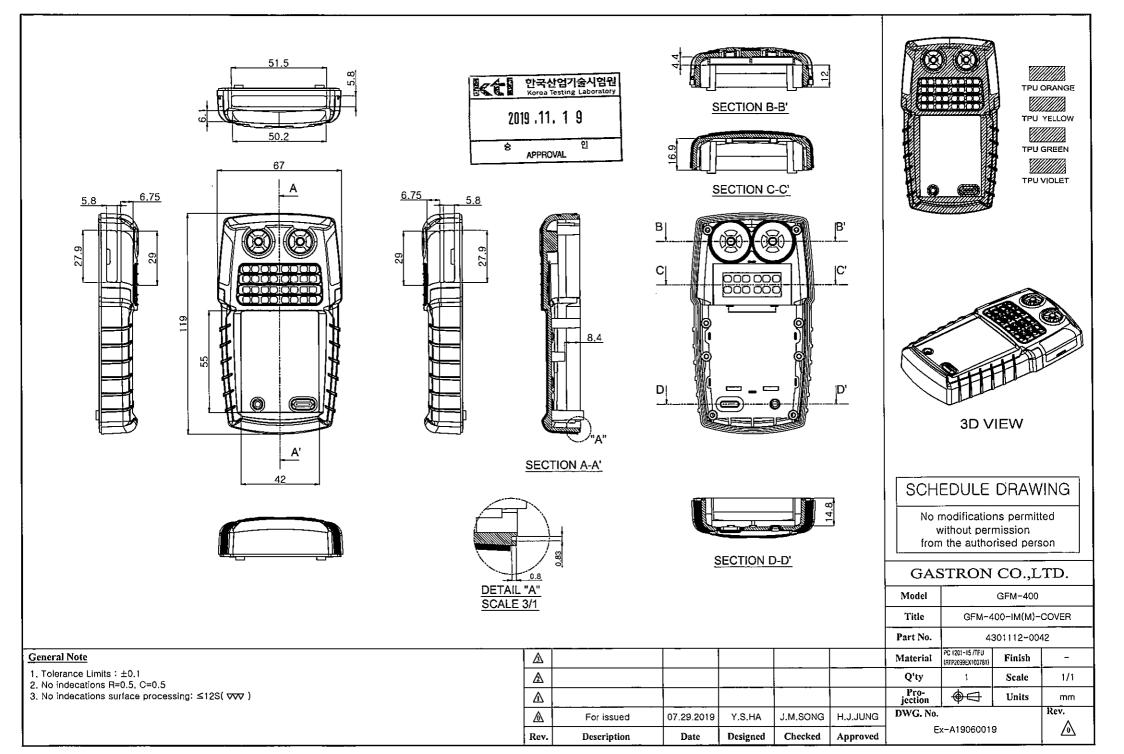
| | SCHEDULE DOCUMENT | Doc. NO. Ex-GI | | | | | | Ex-GE-25B02 | E-25B02 | | | | |
|-----|--|-----------------------------|--------------------|-----------|----------------|-----------------|-------------------|-----------------------------|---------------------------|--------------------|---|--|--|
| | h | GFM-400_BLUETOOTH Part List | | | | Rev. No. | Description | Rev. Date | Reviewed by Approved by | | | | |
| | No modifications permitted without permission from the authorised person | | | | | 1.0 | For issued | 2019.07.24 | S.M. BAE | S.H. YI H.J. JOUNG | | | |
| NO. | Reference | Value (Available Range) | Value (Default) | Tolerance | Maximum Rating | Package | Manufacturer | Part Number of Manufacturer | | Remarks | | | |
| 1 | US | CC2640RZFRHB | CC2640R2FRHB | • | 4.1 V | VQFN(32pin 5x5) | TEXAS INSTRUMENTS | CC264 | CC2640R2FRHB | | • | | |
| 2 | C43,C47 | 1pF | 1pf | ±0.25pF | 25 V | C0201 | SAMSUNG | CL03C01 | CL03C010CA3GNNC | | - | | |
| 3 | C44 | 6.8pF | 6.8pF | ±0.25pF | 25 V | C0201 | MURATA | GRM03350 | GRM0335C1E6R8CA01D | | • | | |
| 4 | C13,C40 | 12pF | 12pF | ±5% | 50 V | C0201 | MURATA | GRM0335 | 1H120JA01D | • | | | |
| 5 | C10 | 1uF | 1uF | ±20% | 16 V | C0201 | SAMSUNG | CL03A10 | CL03A105M03NRNH | | • | | |
| 6 | C2,C3,C11,C49,C50,C54,C55 | 0.1uF | 0.1uF | ±10% | 16 V | C0201 | MURATA | | , GRM033C71C104KE14D | | • | | |
| 7 | C1,C51 | 1uF | 1uF | ±10% | 25 V | C0402 | SAMSUNG | CL05A105KA5NQNC | | <u> </u> | | | |
| 8 | L8 | 2,4nH | 2.4nH | ±0.3nH | 310 mA | L0201 | Sunlord | SDCL0603Q2N4ST02B01 | | - | | | |
| 9 | L9 | 2.7nH | 2.7nH | ±0.3nH | 310 mA | L0201 | Sunford | SDCL0603Q2N7ST02B01 | | <u> </u> | | | |
| 10 | L11 | 6.2nH | 6.2nH | ±0.3nH | 210 mA | L0201 | Sunjord | SDCL0603Q6N2ST02B01 | | - | | | |
| 11 | L46 | 3nH | 3nH | ±0.3nH | 300 mA | L0402 | Sunlord | SDCL1005C3N0STDF | | - | | | |
| 14 | L1 | 39nH | 39nH | ±0.3nH | 200 mA | L0402 | Sunlord | SDCL1005C39NSTDF | | • | | | |
| 12 | R10 | 0Ω | 0Ω | - | 0.0625 W | R0402 | Walsin | | WR04X000PTL | | - | | |
| 13 | R2 | 100kΩ | 100kΩ | ±5% | 0.05 W | R0201 | Walsin | ` | WR02X104JTL - | | - | | |
| 14 | X2 | 24.000Mhz | 24.000Mhz | - | - | 3225 | EPSON | | TSX-3225 24.0000MF15X-AC3 | | | | |
| 15 | X1 | 32.768Khz | 32.768Khz | - | - | 3215 | EPSON | FC-135 32 | .7680KA-AG0 | | | | |
| 16 | ANT1 | SLDA62-2R640G-01TF | SLDA62-2R640G-01TF | - | - | 6x2mm | Sunlord | SLDA62-2 | R640G-01TF | | - | | |

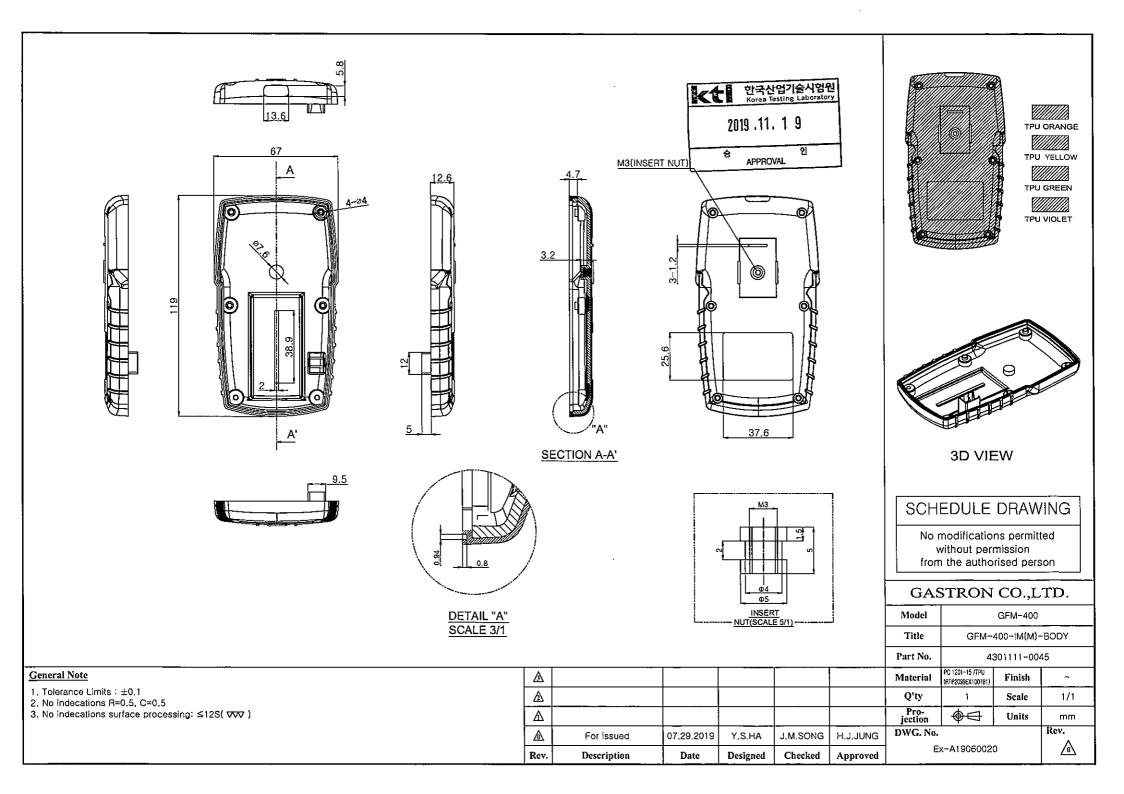
한국산업기술시엄원 Korea Testing Laboratory
2019 .11, 1 9

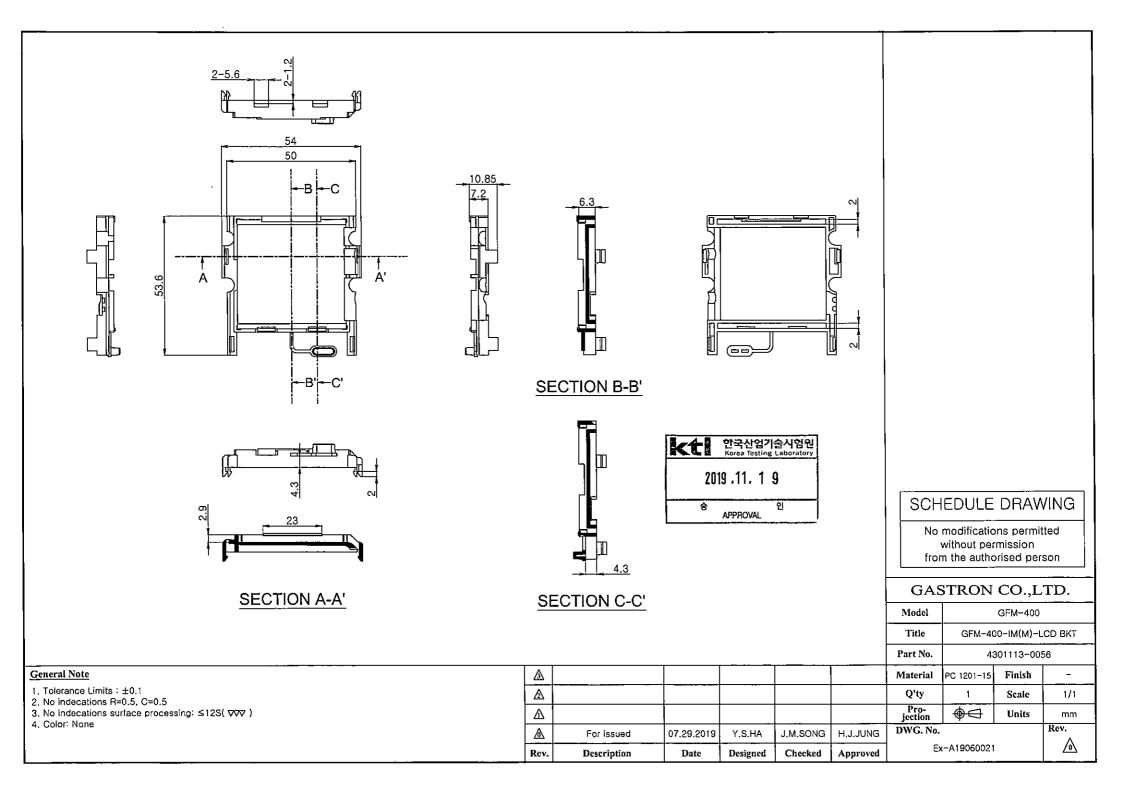
DATA SHEET LIST

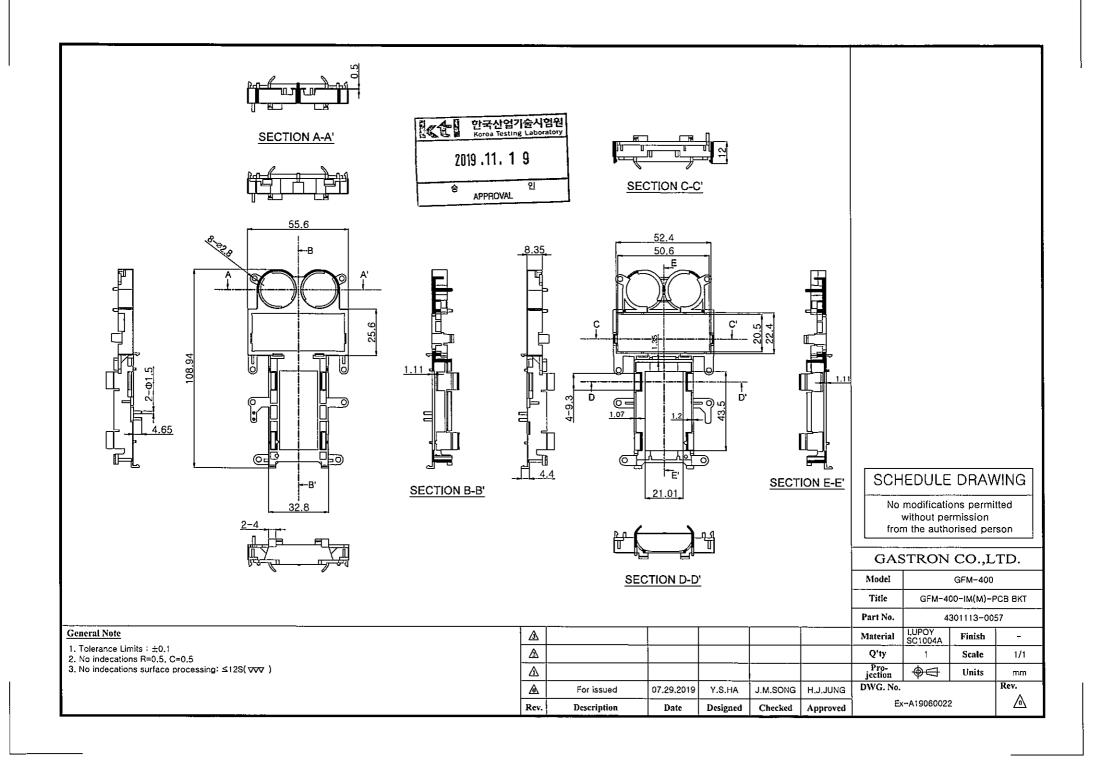
| | DWG No. | Part name | | | | <u></u> . | | | |
|----------|--------------|---|--------------|--|---------------------------------|---|------------|-------|-------|
| NO. | Rev No. | Part No. | lmage | Material | Date | Remark | DATA SHEET | RTI | сот |
| 1 | Ex-A19060018 | GENERAL ASSEMBLY | | NIA | 2019-07-29 | Product color : Orange / Yellow / Green / violet | N/A | N/A | N/A |
| | 0.0 | 1501001-0007-00 | | | | | | | |
| 2 | Ex-A19060019 | GFM-400-IM(M)-COVER | | PC 1201-15 / TPU (RTP2099EX100781) | 2019-07-29 | Product color : Orange / Yellow / Green / violet | PC:O | PC:O | PC:X |
| L | 0.0 | 4301112-0042 | | | | | TPU: O | TPU:X | TPU:X |
| 3 | Ex-A19060020 | GFM-400-IM(M)-BODY | | PC 1201-15 / TPU (RTP2099EX100781) | 2019-07-29 | Product color ; Orange / Yellow / Green / violet | PC:O | PC:O | PC:X |
| L | 0.0 | 4301111-0045 | | | | | TPU: O | TPU:X | TPU:X |
| 4 | Ex-A19060021 | GFM-400-IM(M)-LCD BKT | | PC 1201-15 | 2019-07-29 | | 0 | 0 | х |
| | 0.0 | 4301113-0056 | lineal . | | | | | | |
| 5 | Ex-A19060022 | GFM-400-IM(M)-PCB 8KT | 18 | LUPOY SC1004A | 2019-07-29 | | | ٥ | × |
| L | 0,0 | 4301113-0057 | | | | | | | |
| 6 | Ex-A18120012 | PR(M)-SUSPENDER CLIP | | STS 304 2019-07-29 | GFS-100 PR(M)-SUSPENDER CLIP | 0 | | | |
| | 0.0 | 4301220-0019 | | | | 공용자재 | | | |
| 7 | Ex-A19060023 | GFM-400-PR(M)-SHIELDCASE | 1000 | STS 304 | 2019-07-29 | | 0 | | |
| | 0.0 | 4301213-0036 | 1 11111 | | | | | | |
| 8 | | GFM-400-GA-SHIELDTAPE | | CT10CX | 2019-07-29 | | 0 | | |
| | 0.0 | 4302530-0020 | | | | | | | |
| 9 | Ex-A18120009 | GFM-400-RU-SENSOR CAP | | NBR(50*) JSLR-NBR50-0811 | 2019-07-29 | GFS-100 RU-SENSOR CAP | ٥ | × | 0 |
| | 0.0 | 4301330-0053 | | | | 공용자재 | | | |
| 10 | Ex-A18120013 | GFM-400-MEMBRANE FILTER | | e-PTFE | 2019-07-29 | GFS-100 MEMBRANE FILTER | 0 | x | 0 |
| | 0,0 | 4800202-0005 | | | | 공용자재 | | | |
| 11 | Ex-A19060025 | GFM-400-MEMBRANE FILTER_B | | e-PTFE (MV-9) | 2019-07-29 | | 0 | x | o |
| <u> </u> | 0.0 | 4800202-0006 | | 1 | | | | | |
| 12 | Ex-A19060026 | GFM-400-GA-LCD CUSHION | | MSR 070 | 2019-07-29 | | 0 | × | 0 |
| L | 0.0 | 4302310-0031 | | | | | | | : |
| 13 | Ex-A19060027 | GFM-400-GA-NDIR CUSHION | | MSR 030 | 2019-07-29 | • | 0 | × | 0 |
| _ | 0.0 | 4302310-0032 | | | | | | | |
| 14 | Ex-A19060028 | GFM-400-GA-LCD PROTECT FILM | | JB-SD10008 | 2019-07-29 | | 0 | × | o |
| | 0,0 | 4302530-0021 | | | | | | | |
| 15 | Ex-A19060029 | GFM-400-GA-LCD BKT Sheet | | CP70 | 2019-07-29 | | | × | ٥ |
| L | 0.0 | 4302530-0022 | E | | | | | | |
| 16 | Ex-A19060030 | GFM-400-GA-INSULATION SHEET | | MSR 050 | 2019-07-29 | | 0 | x | 0 |
| Ĺ | 0.0 | 4302530-0023 | | _ | | | | L | |
| 17 | Ex-A19060031 | GFM-400-DE-LCD WINDOW | | PC Film G11 | 2019-07-29 | Product color | 0 | х | 0 |
| Ľ. | 0.0 | 4302280-0063 | 5 2 6 | | | : Orange / Yellow / Green / violet | | | |
| 18 | Ex-A19060032 | GFM-400-LA- CERTIFICATION LABEL | | Matt Silver Pet MZ0104 | 2019-07-29 | | 0 | x | 0 |
| | 0.0 | 4304111-0068 | | | | | <u> </u> | | |
| 19 | Ex-A19100005 | GFM-400-GA- PCB CUSHION 4302310-0038 | | PSR -1.0 | 2019-11-08 | | o | × | 0 |
| | | | | | | | | | |

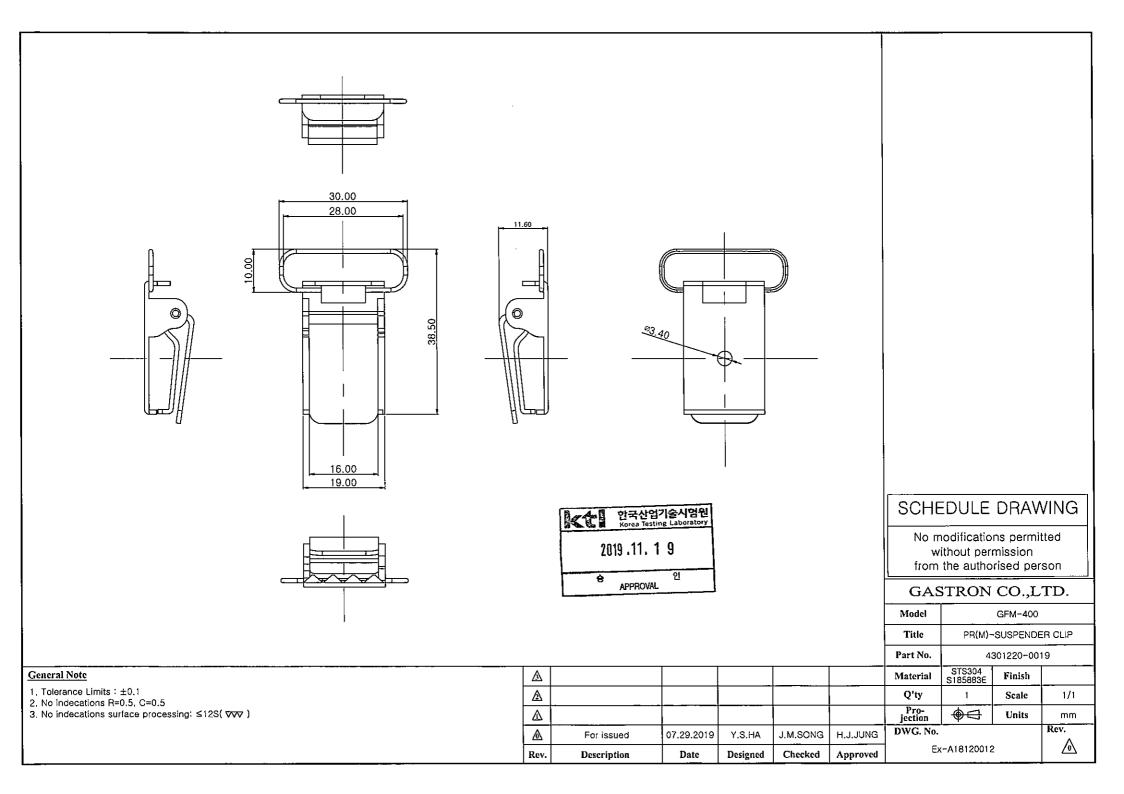


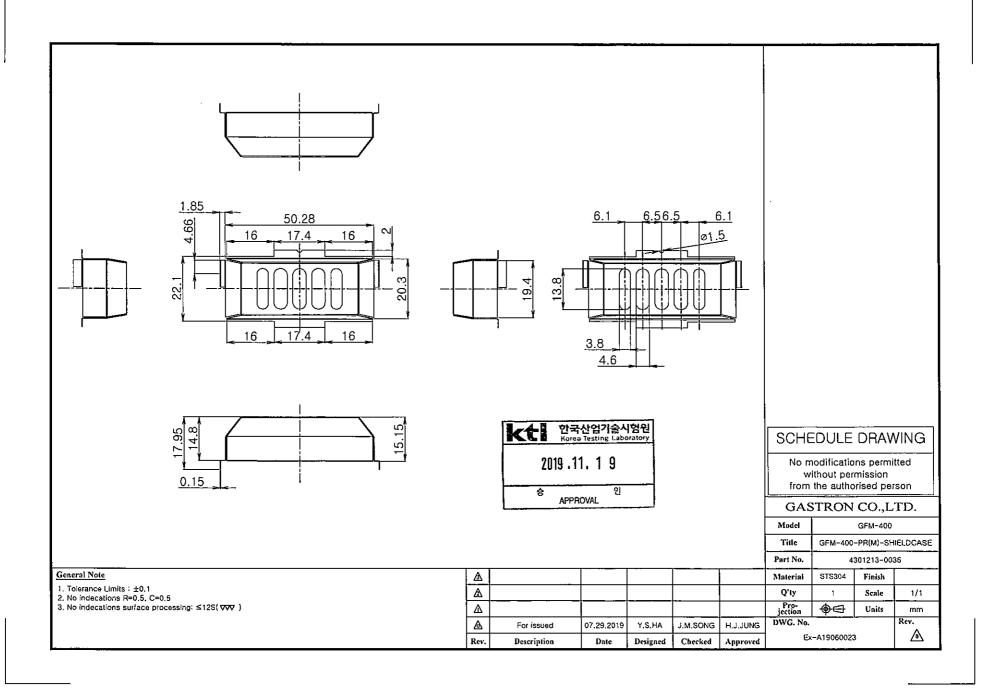


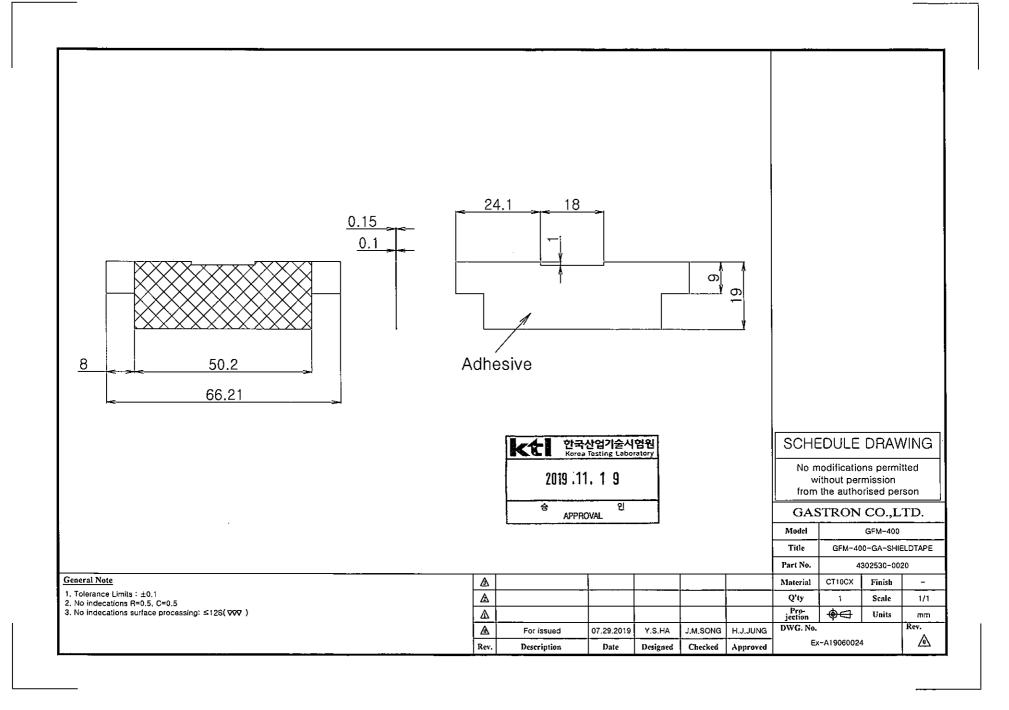


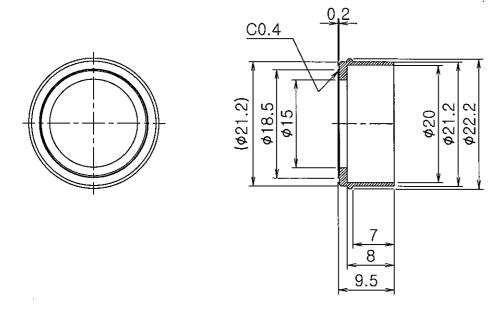


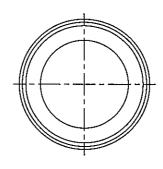


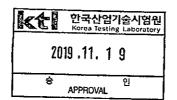












SCHEDULE DRAWING

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GASTRON CO.,LTD.

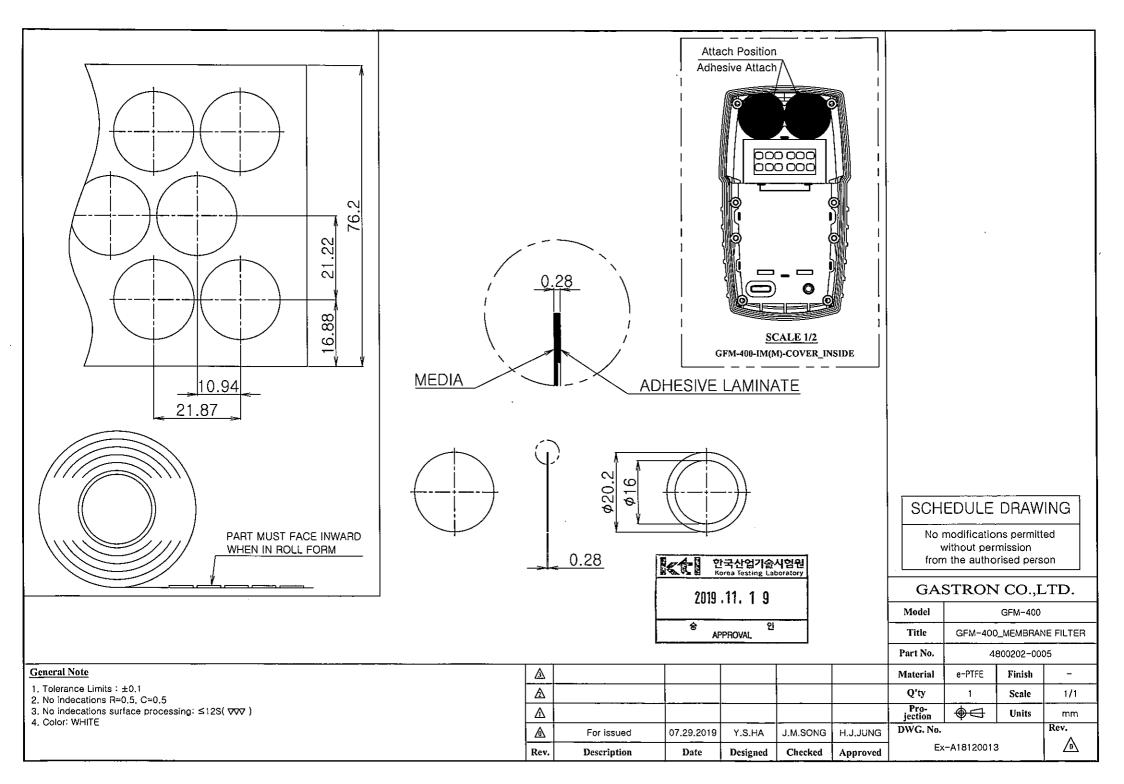
| i | Model | GFM-400 | | |
|---|----------|-----------------------|--------|---|
| | Title | GFM-400-RU-SENSOR CAP | | |
| | Part No. | 4301330-0053 | | |
| | Material | NBR (50°) | Finish | _ |

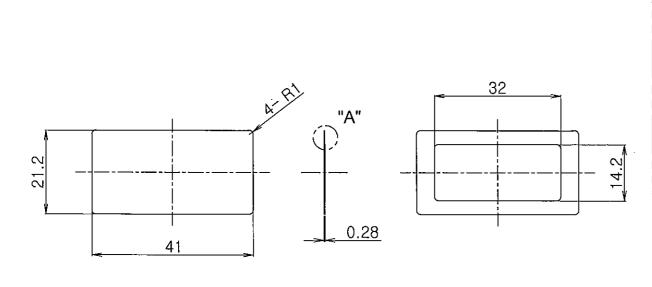
General Note

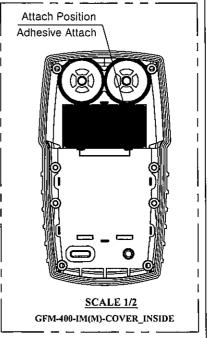
- 1. Tolerance Limits: ±0.1
 2. No indecations R=0.5, C=0.5
- 3. No indecations surface processing: ≤128(♥♥♥)
 4. Color: BLACK

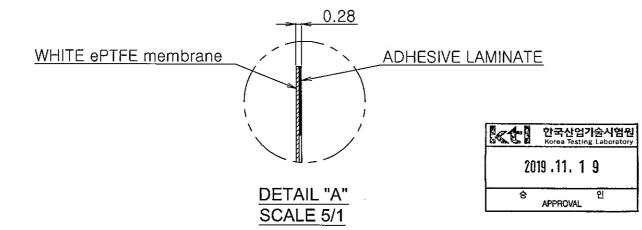
| - | _ | | | | - | | | | | , |
|---|------|-------------|------------|----------|----------|----------|-----------------|------------------------------|--------|------|
| | ⅓ | | | | | | Material | NBR (50°) JSLR-NBA50-0811 | Finish | - |
| | A | | | | | | Q'ty | 1 | Scale | 1/1 |
| | Δ | | | | | | Pro- jection | \$ | Units | mm |
| | ▲ | For issued | 07.29.2019 | Y.S.HA | J.M.SONG | H.J.JUNG | DWG. No. | | | Rev. |
| | Rev. | Description | Date | Designed | Checked | Approved | Ex-A18120009 | | | |

HARDNESS: 50°









SCHEDULE DRAWING

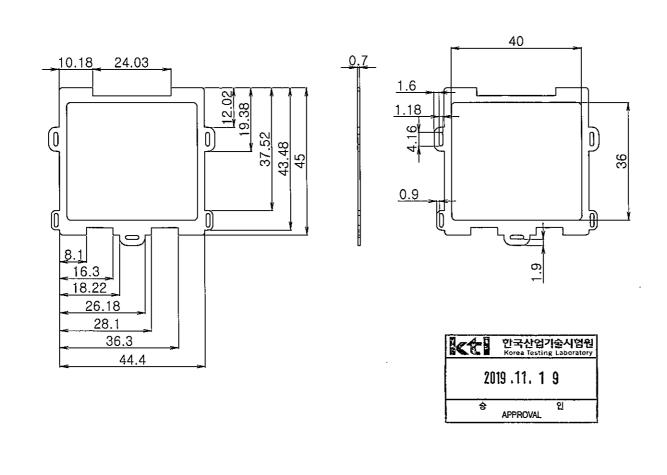
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GASTRON CO.,LTD.

| Model | GFM-400 | | | | | |
|----------|---------------------------|--|--|--|--|--|
| Title | GFM-400-MEMBRANE FILTER_B | | | | | |
| Part No. | 4800202-0006 | | | | | |
| | | | | | | |

- 1, Tolerance Limits: ±0.1
- 2. No indecations R=0.5, C=0.5
- 3. No indecations surface processing: ≤12S(▽▽▽)
- 4. Color: WHITE

| | | | | | | 1 41 6 1 10. | 7. | 300202 000 | |
|------|-------------|------------|----------|----------|----------|-----------------|-----------------------|------------|------|
| Δ | | | | | | Material | e-PTFE (MV-9) | Finish | _ |
| A | | | | | | Q'ty | 1 | Scale | 1/1 |
| Δ | | | | | | Pro- jection | \Phi | Units | тт |
| ⚠ | For issued | 07.29.2019 | Y.S.HA | J.M.SONG | H.J.JUNG | DWG. No. | DWG. No. | | Rev. |
| Rev. | Description | Date | Designed | Checked | Approved | Ex | Ex-A19060025 <u>0</u> | | |



⅓

Δ Λ ◬

For issued

Description

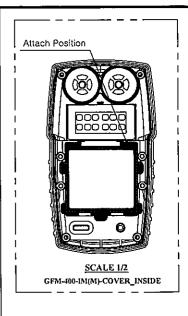
07.29.2019

Y.S.HA

Designed

J.M.SONG

Checked



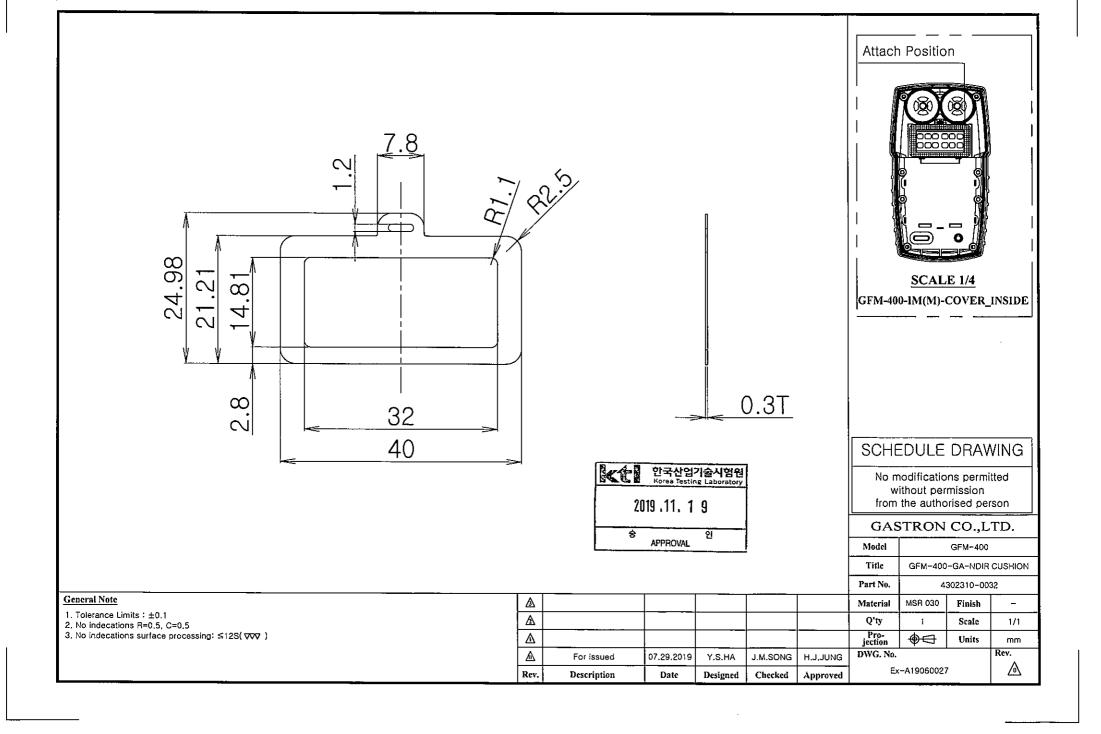
SCHEDULE DRAWING

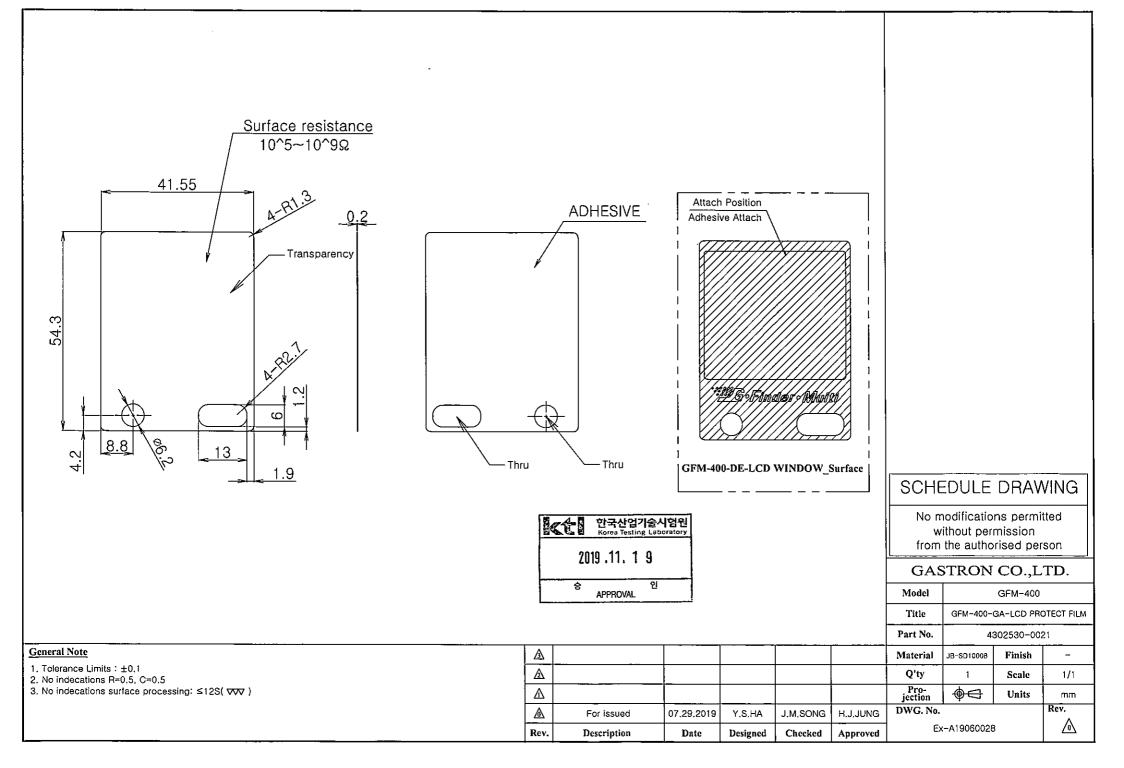
No modifications permitted without permission from the authorised person

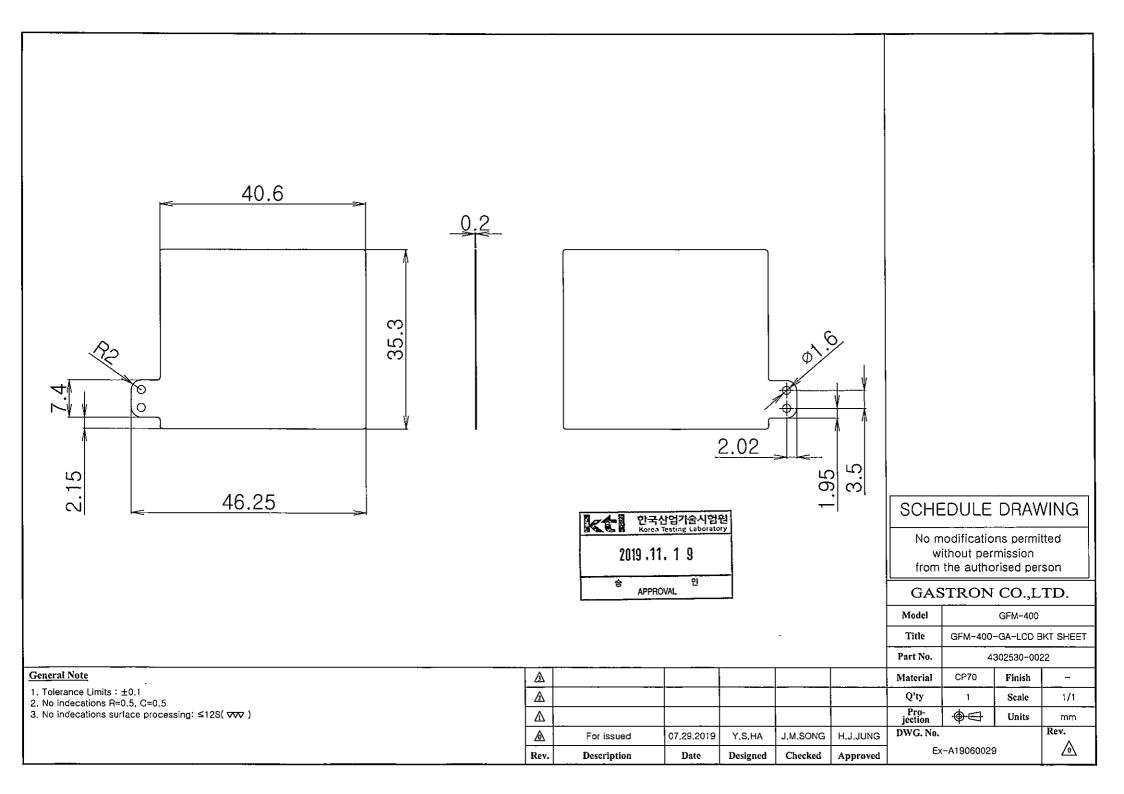
GASTRON CO.,LTD.

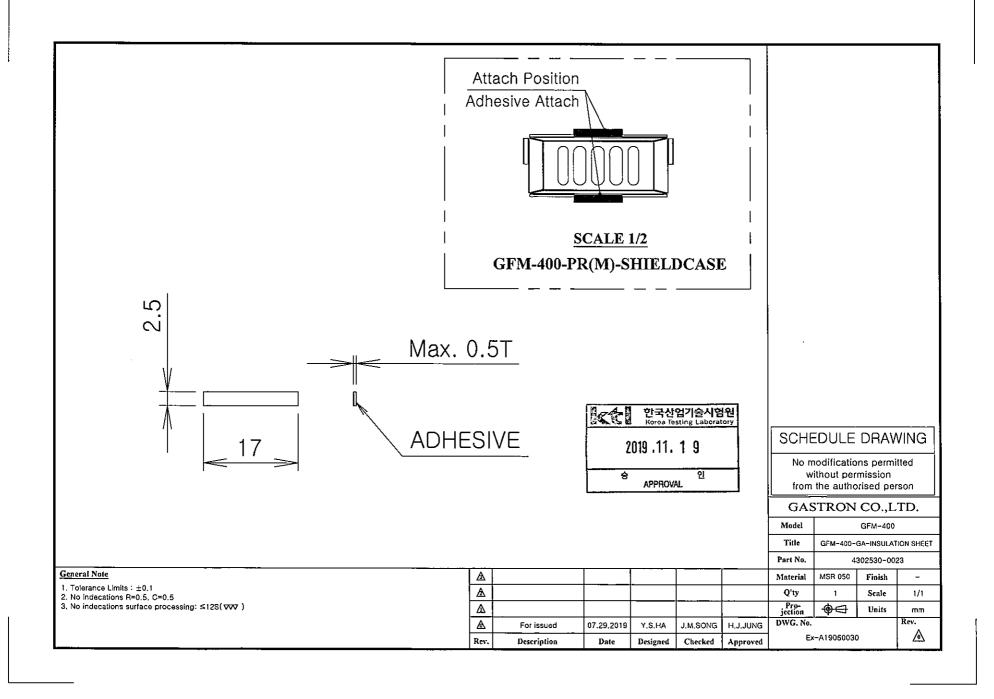
| Í | Model | - | | | |
|----------|-----------------|-------------|----------------|-----|--|
| | Title | GFM-400 | GFM-400-GA-LCD | | |
| | Part No. | 4: | 4302310-0031 | | |
| | Material | MSR 070 | Finish | - | |
| | Q'ty | 1 | Scale | 1/1 | |
| | Pro- jection | ⊕ □ | Units | mm | |
| H.J.JUNG | DWG. No. | | Rev. | | |
| Approved | Ex | x-A19060026 | | | |

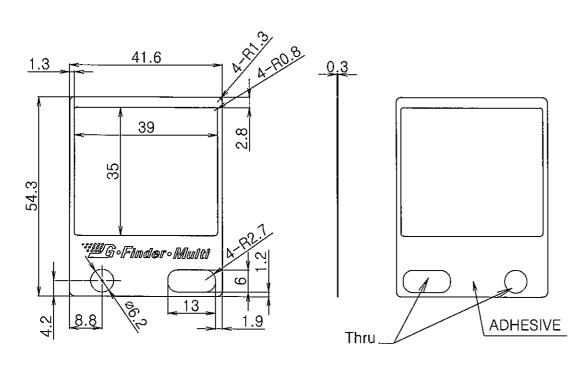
- 1. Tolerance Limits: ±0.1
 2. No indecations R=0.5, C=0.5
 3. No indecations surface processing: ≤12S(∇∇∇)

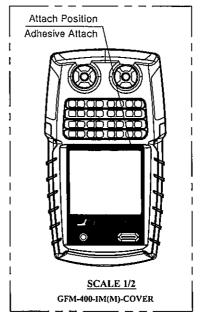




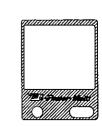




















SCHEDULE DRAWING

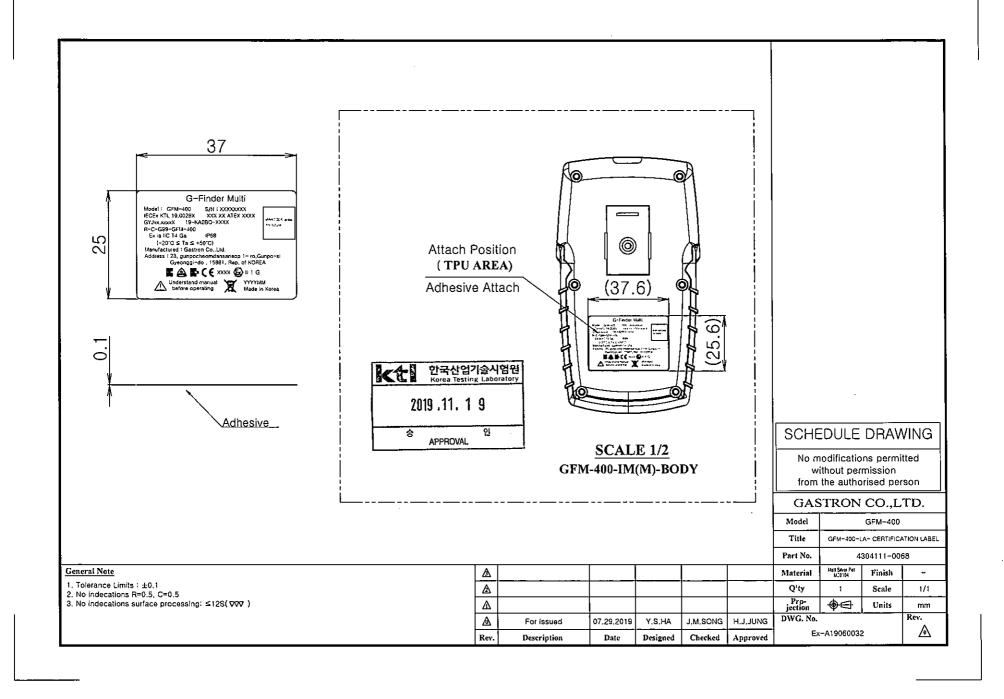
No modifications permitted without permission from the authorised person

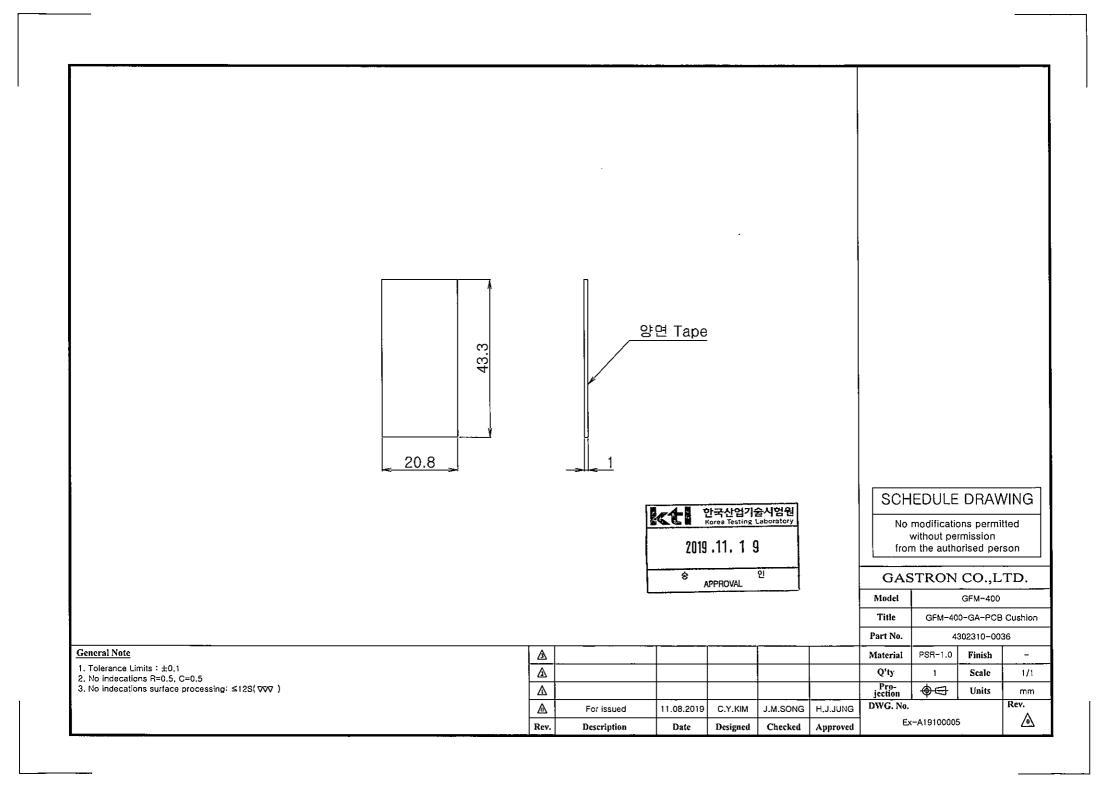
GASTRON CO.,LTD.

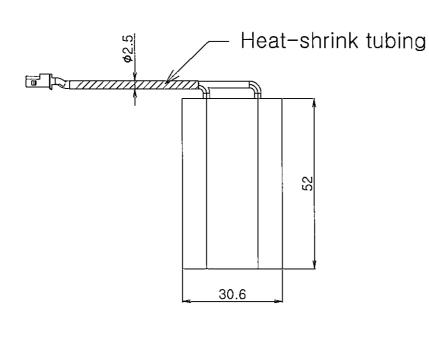
| Model | GFM400 |
|----------|-----------------------|
| Title | GFM-400-DE-LCD WINDOW |
| Part No. | 4302280-0053 |
| | |

- 1. Tolerance Limits: ±0.1
- 2. No indecations R=0.5, C=0.5
- 3. No indecations surface processing: ≤12S(▽▽▽)

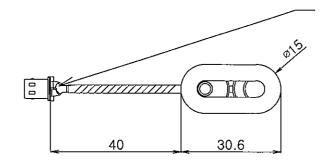
| _ | ⅓ | | | | | | Material | PC Film G11 | Finish | |
|---|----------|-------------|------------|----------|----------|----------|-----------------|-------------|--------|------|
| | A | | | | | | Q'ty | 1 | Scale | 1/1 |
| | Δ | | | | | | Pro- jection | ₩□ | Units | mm |
| | A | For issued | 07.29.2019 | Y.S.HA | J.M.SONG | H.J.JUNG | DWG. No. | | | Rev. |
| | Rev. | Description | Date | Designed | Checked | Approved | Ex-A19060031 | | | |











Cable SPEC

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Δ ⋒

Rev.

For issued

Description

| Type | (| Conductor | | Insulation Min.thick Ave.thick Diameter | | |
|----------|-------------|--------------------------|--------------------|--|-------------------|------------------|
| туре | AWG Size | Const ruction (No/mm) | Approx Diameter | Min,thick (mm) | Ave.thick (mm) | Diameter (mm) |
| Stranded | 24 | 11/0.16 T | 0.61 | 0.69 | 0.77 | 2.15 |

한국산업기술시험원 Korea Testing Laboratory

2019 .11. 1 9

11.08.2019

Date

C.Y.KIM

Designed

J.M.SONG

Checked

H.J.JUNG

Approved

APPROVAL

SCHEDULE DRAWING

No modifications permitted without permission from the authorised person

GASTRON CO.,LTD.

Model

| Model | Model GFM-400 | | | | | |
|-----------------|---------------|-------------------------------|------|--|--|--|
| Title | GFM-400_ | GFM-400_Battery(Ex Component) | | | | |
| Part No. | 4 | 4102302-0002 | | | | |
| Material | Li-SOCi2 | Finish | | | | |
| Q'ty | 1 | Scale | 1/1 | | | |
| Pro- jection | ₩□ | Units | mm | | | |
| DWG. No. | | | Rev. | | | |
| Ex-A19100004 | | | | | | |

- 1. Tolerance Limits: ±0.1
- 2. No indecations R=0.5, C=0.5
- 3. No indecations surface processing: ≤12S(♥♥♥)

G-Finder Multi Instruction Manual

G-Finder Multi is a personal safety device designed to detect the presence of Oxygen (O_2) , Carbon Monoxide (CO), Hydrogen Sulfide (H₂S), Methane (CH₄). Power is provided by one, nonuser replaceable, lithium-thionyl chloride primary 2-cell, Readings are displayed on LCD and the device has audible, visual, and vibrating alarms when set, user-configurable conditions are exceeded. It is your responsibility to respond appropriately to the alarms, G-Finder Multi has no facilities for connection of external electrical circuits. G-Finder Multi has IR communications for changing the alarm set point, the calibration range and etc. The IR communications shall only Kt 한국산업기술시험원
Korea Tasting Laboratory be used in safe area.



1) G-Finder Multi is designed for single Wsb and comes with a non-field replaceable lithium-ion battery, filter and sensor are already installed and ready for use.

2019 .11 . 1 9

- Do not attempt replacement or substitution of components, Replacement or Substitution of components may impair Intrinsic Safety and will void the warranty of the product,
- 3) The electrical, electronic and battery elements of this product must not be disposed of via municipal waste streams; they should be disposed of by a qualified recycler or hazardous materials handler. Correct disposal will contribute to recycling of materials and prevent negative consequences for the environment.
- 4) It is recommended performing a bump test prior to G-Finder Multi use every day to confirm sensor response and alarm activation by exposing the detector to a concentration of target gas that exceeds the low alarm set point.

- 5) For optimal performance, periodically calibrate zero for the sensor.
- 6) G-Finder Multi is provided with anti-static coating over the LCD window to minimize risk of ignition due to electro-static discharge. Periodic inspection of this coating is required to ensure no degradation, delamination, abrasions or other deformities to this surface. Clean only with a damp cloth.
- For all gas type of G-Finder Multi, always proceed bump test and calibration at room temperature and in a fresh air environment (20,9% v/v O2) that is free of hazardous gas.

ACAUTION

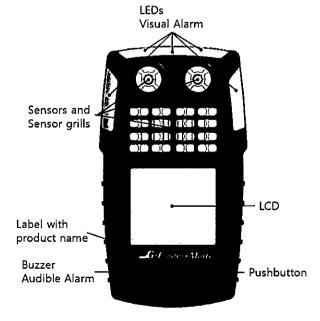
- 1) Activate G-Finder Multi before the activation date on the package.
- 2) In order to maintain normal operation of G-Finder Multi, keep the gas sensor grill from clogging and keep the gas sensor, LED and buzzer hole surfaces free from dust and dirt. Clean the exterior with a soft and damp cloth.
- 3) When using G-Finder Multi, sudden change in the temperature may cause change in the detected gas concentration value suddenly. Using in a stable temperature environment is recommended for more accurate detection.
- 4) The combustible gas sensor is initially calibrated to 50%LEL methane. Only methane gas should be used to calibrate or bump test the combustible gas sensor
- G-Finder Multi is a gas detector, not a measurement device.
- 6) Portable safety gas detectors are life safety devices. Accuracy of ambient gas reading is dependent upon factors such as accuracy of the calibration gas standard used for calibration and frequency of calibration.

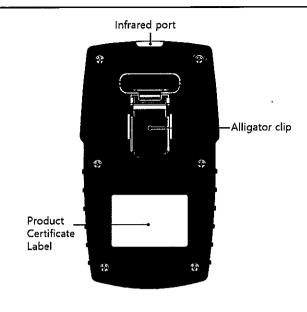
1. Specification

| ltem | Description |
|------------|--------------------------|
| Ex marking | 😉 II 1 G Ex ia IIC T4 Ga |

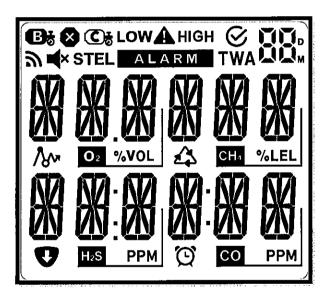
| Approvals | IECEx: IECEx KTL 19.0028X KCs: 19-KA4BO-xxxx ATEX: XXXX 19 ATEX xxxx NEPSI: GYJ19,xxxx |
|--------------|--|
| Dimensions | 120x68x41 mm (Alligator clip included) |
| Weight | 221 g (Alligator clip included) |
| Temperature | -20°C ~ 50 °C |
| Humidity | 5 ~ 95 % RH |
| IP | IP 68 |
| Sensor type | O_2 - electrochemical cell CO- electrochemical cell H_2S - electrochemical cell CH_4 or C_3H_8 - Non Dispersive Infrared sensor C_3H_8 is an option in the future. |
| Alarms | Visual, vibrating, audible (min. 95dB) |
| Display | Liquid Crystal Display (LCD) |
| Battery | Primary lithium-thionyl chloride (Li-SOCI2) |
| Event Log | Last 128 events. Newer events replace older events. |
| Battery Life | 24 months of operation/ 2 minutes of alarm per day. |
| Warranty | Full 2 years |

2. Each part for G-Finder Multi





3. LCD Icons Description

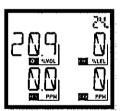


| lcon | Description |
|------------|------------------------------------|
| LOWA | Low alarm and high alarm. |
| ALARM | These signs are displayed when gas |
| 📤 HIGH | concentration exceeds alarm |
| ALARM | setpoints |
| | STEL alarm. |
| | These signs are displayed when gas |
| STEL ALARM | concentration exceeds alarm |
| | setponits |

| ALARM TWA | TWA alarm. These signs are displayed when gas concentration exceeds alarm setponits | |
|------------|--|--|
| C | This icon is displayed when a sensor calibration is in progress or overdue. | |
| B | This icon is displayed when a sensor bump test is in progress or overdue. | |
| 8 | This icon is displayed when a functional error occurs. | |
| <u></u> | This icon is displayed when a Bluetooth connection is due. | |
| × | This icon is displayed when a all alarm off. | |
| 8 | This icon is displayed when as long as the detector works normally without any gas alarms and functional errors. | |
| D D D | Displays remaining product life time | |
| %VOL | Oxygen concentration is measured as percent by volume. | |
| %LEL | Combustible gas concentration is meaned in lower explosive limit. | |
| PPM | Toxic gas concentration is measured in parts per million. | |
| % ~ | This icon is displayed when an alarm event has occurred within the past 10 hours. | |
| 4 | End of operating life warning indicator. | |
| O | When this symbol is displays, press one time or hold the pushbutton until the symbol disappears | |
| Ö | Time Indicator. (Remaining product life with 00M / 00d / 00h display, 00 means remaining months / days / hours) | |

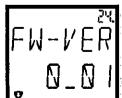
- 1) Move to a normal atmosphere (20.9% v/v O2) that is free of hazardous gas.
- Press and hold the pushbutton until 5 second countdown is displayed, then continue to hold until the countdown is completed to activate G-Finder Multi.
- 3) When the countdown is completed, the LCD, LEDs, vibration, and beep turn on and then turn off.
- 4) The alarm setpoints are displayed and the sensor stabilization countdown is displayed. The time required to stabilization is 2minute. When the countdown reaches 0, the activation is completed.
 - In case of G-Finder Multi, when the countdown reaches 0, the zero calibration is performed automatically and after the zero calibration, the activation is completed.
- The detector is in normal operating mode when the gas type and concentration are displayed.

5. Normal Operating Mode



Normal

 When the detector is in normal operating mode, the type of gas detected is permanently displayed. The detected concentration of the gas is displayed until it is disrupted by a pushbutton action, gas alarm, or error event. If you want to see the status information about the detector, please press the pushbutton once.



Firmware Version

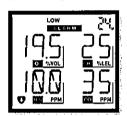
2) The display information on the LCD is changed to the current firmware version of the

detector from the normal display by pressing the button once. The number before the period '_' means major number of the firmware version, and the number after the period means minor number. In other word, "1_00" indicates the firmware number is '1.00'.



Remaining Product Life

3) The display information on the LCD is changed to the remaining product life from the current firmware version of the detector by pressing the button once. The unit of the remaining life will be changed automatically refer to the remaining life scale: "24m" ~ "1m", "30^D" ~ "1^D", "24" ~ "1".



Low Alarm Set Value

4) The display information on the LCD is changed to the low alarm set value from the remaining product life by pressing the button once.



High Alarm Set Value

5) The display information on the LCD is changed to the high alarm set value from the low alarm set value by pressing the button once.



STEL Alarm Set Value

6) The display information on the LCD is changed to the short term exposure limit(STEL) alarm

set value from the high alarm set value by pressing the button once.

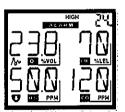


TWA Alarm Set Value

- 7) The display information on the LCD is changed to the time weighted average(TWA) alarm set value from the STEL alarm set value by pressing the button once.
- 8) The display information on the LCD is changed to the normal display from the TWA alarm set value by pressing the button once if there is not any alarm event occurred within the past 10 hours.



Elapsed Time



Alarm Value Occurred

9) Or if there is any alarm event occurred within the past 10 hours, the display information on the LCD is changed to elapsed time since the alarm occurred from the TWA alarm set value by pressing the button once, and then it is changed to the alarm value occurred by pressing the button once again, and it is changed to the normal display by pressing the button once again.

6. Alarms

An alarm is initiated when the sensor is exposed to a gas concentration that exceeds alarm setpoints. The alarm has four types; a low alarm and a high alarm and a STEL alarm and a TWA alarm.



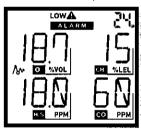
The alarm persists until the gas concentration returns to an acceptable range. Battery life decreases rapidly when the detector is in alarm condition.

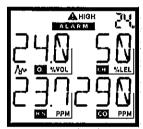
For G-Finder Multi O_2 , a low alarm occurs when the measured concentration value is lower than the low alarm setting value, while a high alarm occurs when the measured concentration value is higher than the high alarm setting value.

The following alarm settings are default for each detector gas type.

| Gas Type | Low Alarm | High Alarm | |
|-----------------|-----------------|-----------------|--|
| O ₂ | 19.5% v/v O₂ | 23.5% v/v O₂ | |
| СО | 30 ppm | 200 ppm | |
| H₂S | 10.0 ppm | 15,0 ppm | |
| CH ₄ | 10% LEL | 20% LEL | |

When the alarm occurs, LEDs flash, vibration and beep sounds occur and display will be changed as below for example.





7. Bump Test

- 1) Press the button twice at the normal operating mode in succession to get into the menu, it shows "BUMP" on the screen.
- Press and hold the button until a 3 second countdown is displayed, then continue to hold until the countdown is completed to perform the bump test.
- 3) Then the gas Injection display, the low alarm setpoint display, and the high alarm setpoint display occur cross and the detector waits for injection of gas which causes an alarm.







4) If the detector detects the gas concentration for the bump test, the bump test process is performed automatically. The result will be displayed on the screen at the end of the test. If an alarm occurs during the bump test, the test is succeeded, otherwise the test is failed.

8. Zero the Sensor

In case of G-Finder Multi O_2 , over time and through use, the sensor baseline at zero exposure may drift from the manufacturer's baseline. For optimal performance of O2 sensor, it is recommended to zero the O2 sensor at least once in a month at the condition of room temperature and in a fresh air environment (20.9% v/v O2) that is free of hazardous gas.

The user will be noted by the display of the calibration reminder icon when the sensor calibration is due. If the icon is showing please zero the sensor as instructed below:

- ** For all gas types, we recommend to zero the sensor periodically.
- Move to a normal atmosphere (20.9% v/v
 O2) that is free of hazardous gas.
- Press the button twice at the normal operating mode in succession to get into the menu, "BUMP" will be displayed on the screen.
- 3) "ZERO" is displayed on the screen by pressing the button once, then press and hold the button until a 3 second countdown is displayed. Continue to hold until the countdown is completed to calibrate zero.
- 4) Wait until the zeroing process is completed.
- When the zeroing process is completed, "PASS" or "FAIL" appears.
- 6) After displaying the result, "ZERO" is displayed on the screen again automatically.
- 7) If "FAIL" appears, repeat the zeroing process according to above procedure.
- 8) If the zeroing process fails again, please contact our service center.
- 9) To calibrate gas, press the button once, and "SPAN" will be displayed on the screen. Continue calibrating according to the "Calibration Gas" section.

 Or to exit the menu, press the button repeatedly to go back to normal operating mode

9. Gas Calibration

For more optimal performance of G-Finder Multi, gas calibration may be needed. To calibrate the detector, we recommend gas calibration after doing zero calibration at room temperature and in a fresh air environment (20.9% v/v O2) that is free of hazardous gas.

By default, G-Finder Multi is configured to use the following calibration gas mixtures:

| Gas Type | Standard Calibration Gas Concentration |
|-----------------|---|
| O ₂ | 18.0 % v/v O ₂ |
| СО | 100 ppm (balance N₂) |
| H₂S | 25 ppm (balance N₂) |
| CH ₄ | 50 % LEL (balance N₂) |

- Move to a normal atmosphere (20.9% v/v
 O2) that is free of hazardous gas.
- Press the button twice at the normal operating mode in succession to get into the menu. "bUMP" will be displayed on the screen.
- 3) "ZERO" will be displayed on the screen by pressing the button once, by pressing the button again, "SPAN" will be displayed on the screen.
- 4) Press and hold the button until a 3 second countdown is displayed. Continue to hold until the countdown is completed.
- The gas Injection display and the standard calibration gas concentration display occur cross and the detector waits for injection of calibration gas.







- 6) If the detector detects the gas concentration for the gas calibration, the gas calibration process will be performed automatically.
- 7) When the gas calibration process is completed, "PASS" or "FAIL" appears.
- 8) After displaying the result, "SPAN" will be displayed on the screen again automatically.
- 9) If "FAIL" appeared, repeat the gas calibration process according to above procedure.
- 10) If the gas calibration fails again, please contact our service center.
- Or to exit the menu, press the button repeatedly to go back to normal operating mode.

10. Detection Range

Detection ranges for each gas type are noted in the table below.

| Gas Type | Detection Range | | |
|-----------------|---------------------|--|--|
| | 0 to 25,0% Vol | | |
| O ₂ | with 0.1 increments | | |
| СО | 0 to 300 ppm | | |
| | with 1 increment | | |
| H₂S | 0 to 100 ppm | | |
| | with 0.1 increments | | |
| CH ₄ | 0 to 100% LEL | | |
| | with 1 increments | | |

11. Manufacturer Information

If there are any problems with our products, please contact us at the address below.

1) Address:

Gastron Co., Ltd. 23, Gunpocheomdansaneop 1-ro, Gunpo-si, Gyeonggi-do, Korea

Tel: 82-31-490-0800
 Fax: 82-31-490-0801

4) URL: www.gastron.com

5) e-mail: gastron@gastron.com

Certifications and Approvals

 The certification marking and certificate numbers are in the table below.

| Product Name | Specific Low Power Radio Equipment for Wireless Data Communication Systems |
|-----------------|--|
| Ex marking | ATEX: C € 0344 II 1 G Ex ia IIC T4 Ga IECEx / KCs / NEPSI: Ex ia IIC T4 Ga |
| Approvals | IECEx: IECEx KTL 19,0028X KCs: 19-XXXXX-XXXX ATEX: XXXXX 19ATEXXXXX NEPSI: GYJ19, XXXX KC: R-C-G99-GFM-400 |

2) The product is in conformity with the following standards:

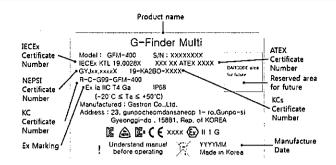
IECEx: IEC 60079-0:2017, IEC 60079-11:2011 KCs: Announcement No. 2019-15 of Ministry

of Employment and Labor

ATEX: EN 60079-0:2012, EN 60079-11:2012 NEPSI: GB 3836.1-2010, GB 3836.4-2010,

GB 3836.20-2010

- 3) The product may be used in zones 0, 1 & 2 with flammable gases and vapors with apparatus groups IIC and with temperature classes T1, T2, T3, T4.
- The product is only certified for use in ambient temperatures in the range -20°C ≤ Ta ≤ +50°C and should not be used outside this range,
- 5) With regard to explosion safety, it is not necessary to check for correct operation.
- 6) The product contains no user-replaceable parts and is not intended to be repaired by the user. Repair of the equipment is to be carried out by the manufacturer, or their approved agents, in accordance with the applicable code of practice.
- The certificate label is described as below.



13. Ordering Information

Please put an order according to model code description below.

GFM-400-X-Y

GFM-400: standard model name

*X: Flammable gas type

*X: Option code (default, MM2.5 ~ PP2.5) which can be selected when ordering by user demand which is not be a default for a target gas type, a calibration gas type, and a measurement range type about the flammable gas type. For the details about options, please refer to the table below. Other option codes except default option are options in the future.

| Option | Target | Calibration | Measurement | |
|---------|-------------------------------|-------------------------------|-------------|--|
| code | Gas | Gas | range, %vol | |
| default | CH ₄ | CH ₄ | 0 ~ 5 | |
| (blank) | | | | |
| MM2.5 | CH ₄ | CH ₄ | 0 ~ 2.5 | |
| MM100 | CH ₄ | CH ₄ | 0 ~ 100 | |
| MP1.5 | CH ₄ | C ₃ H ₈ | 0 ~ 1.5 | |
| MP2.5 | CH ₄ | C ₃ H ₈ | 0 ~ 2.5 | |
| PP1.5 | C ₃ H ₈ | C ₃ H ₈ | 0 ~ 1.5 | |
| PP2.5 | C ₃ H ₈ | C₃H8 | 0 ~ 2.5 | |

- *Y: Housing body color
 (Blank: orange(default), YE: yellow, GN: green, VT: violet, etc.)
 - *Y: Option which does not affect intrinsic safety. This option code is needed at the order if you want some color different with default for the

housing body. This option code will be not printed on the label.

14. Sales Information

This equipment may be operated in all EU members.

15. Revision History

| REV. | CONTENTS | DATE |
|------|------------------|-----------------|
| 0.1 | Initial Document | 25 JULY 2019 |
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